



**PRESENTATION**

**KRANJ, DEC 2018**

Zgodovina tehnologije tiskanih vezij



1948





1948





1948

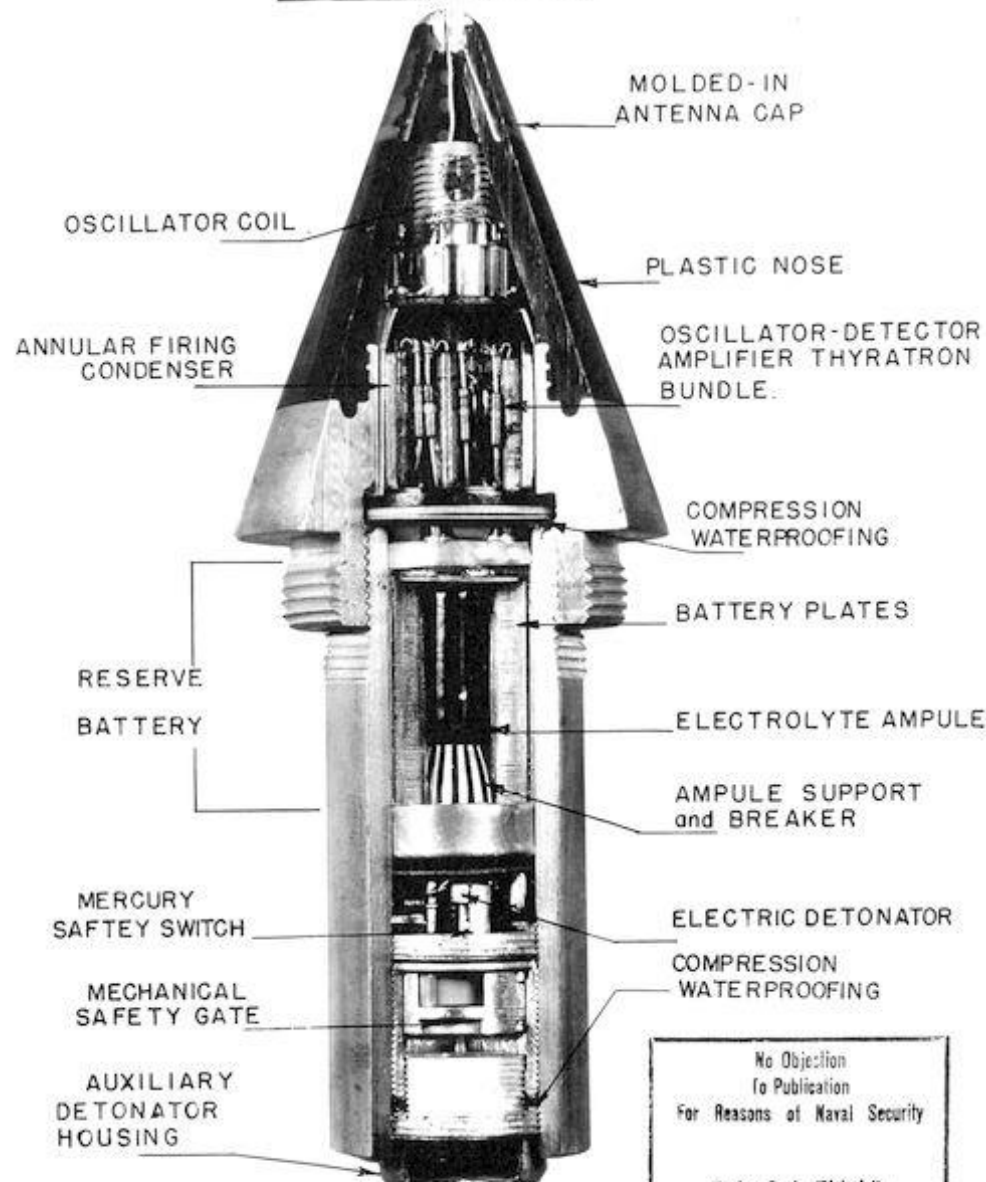




1948



MARK 53

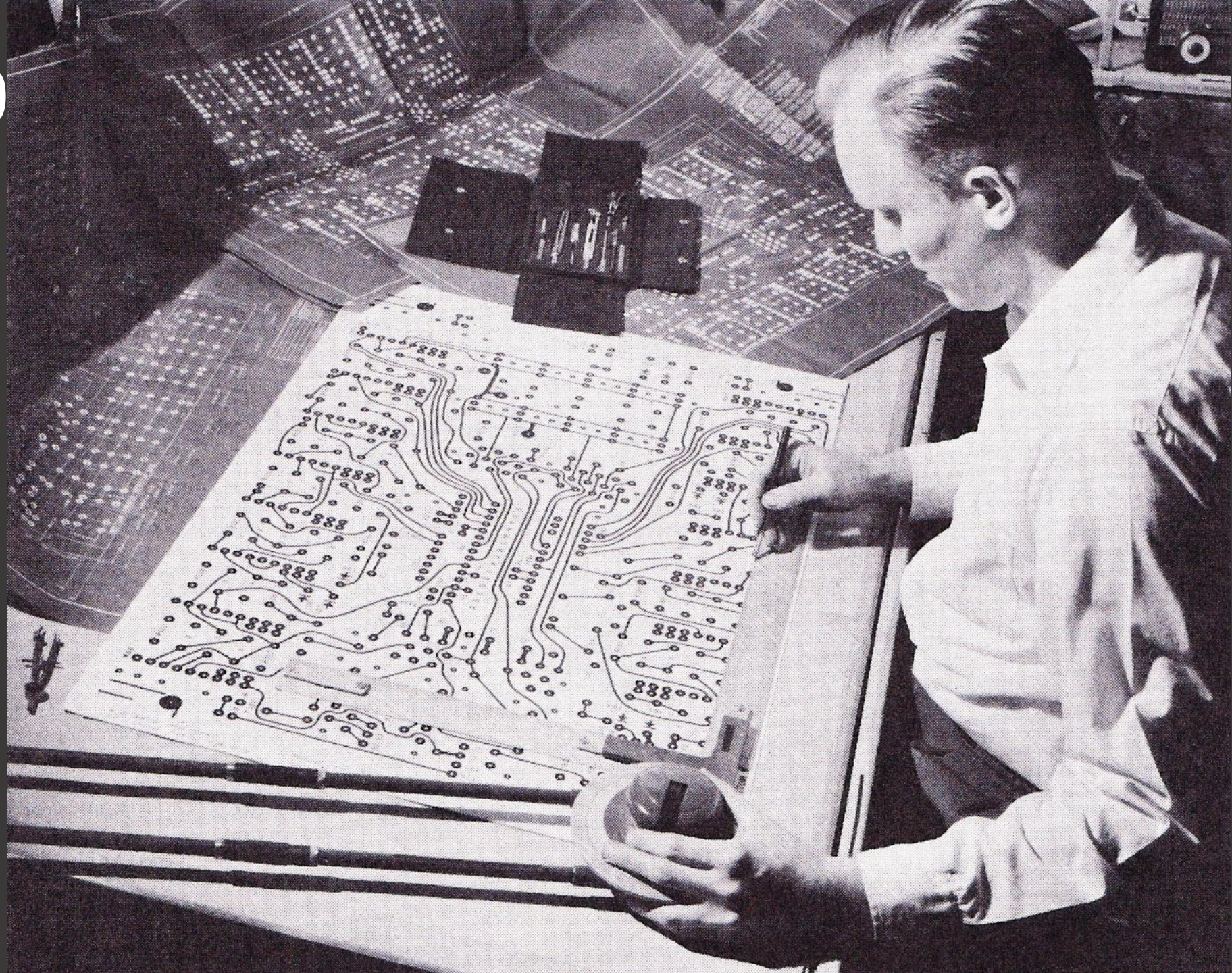


No Objection  
to Publication  
For Reasons of Naval Security

Review Sect. (Pierial)  
Office of Public Information  
NAVY DEPARTMENT

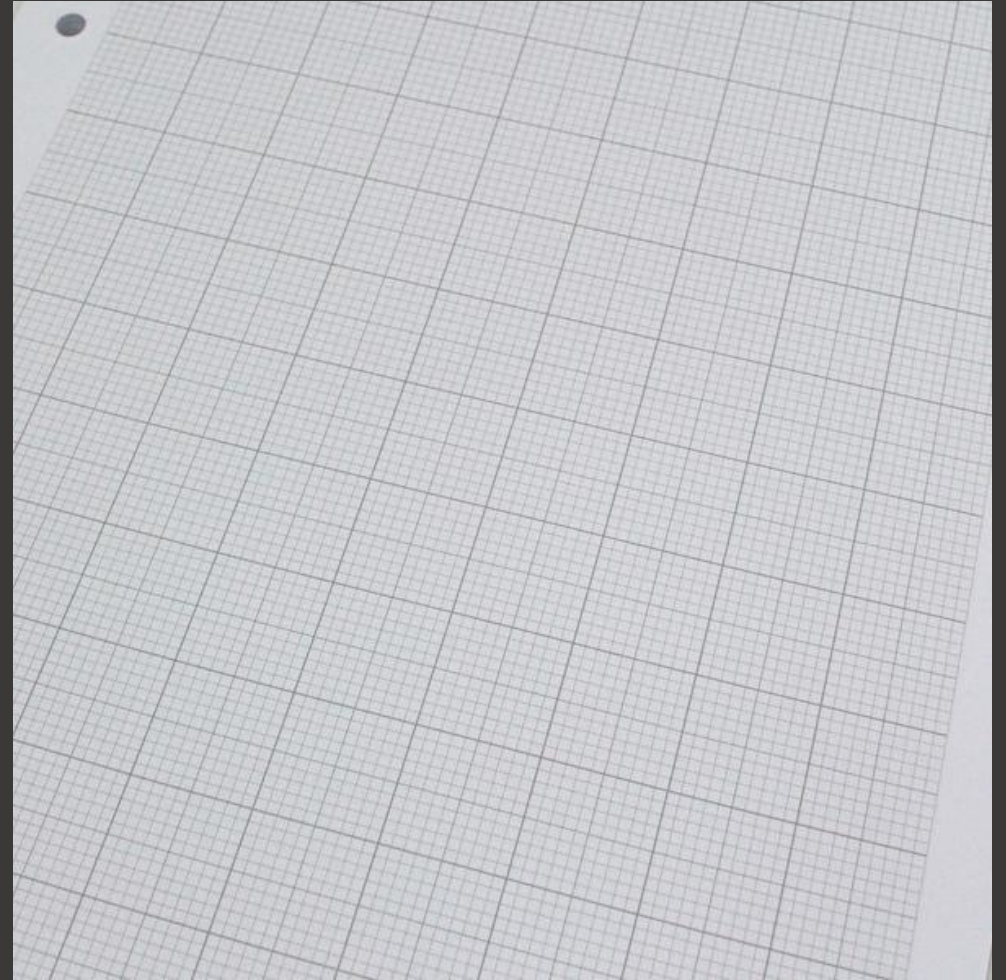
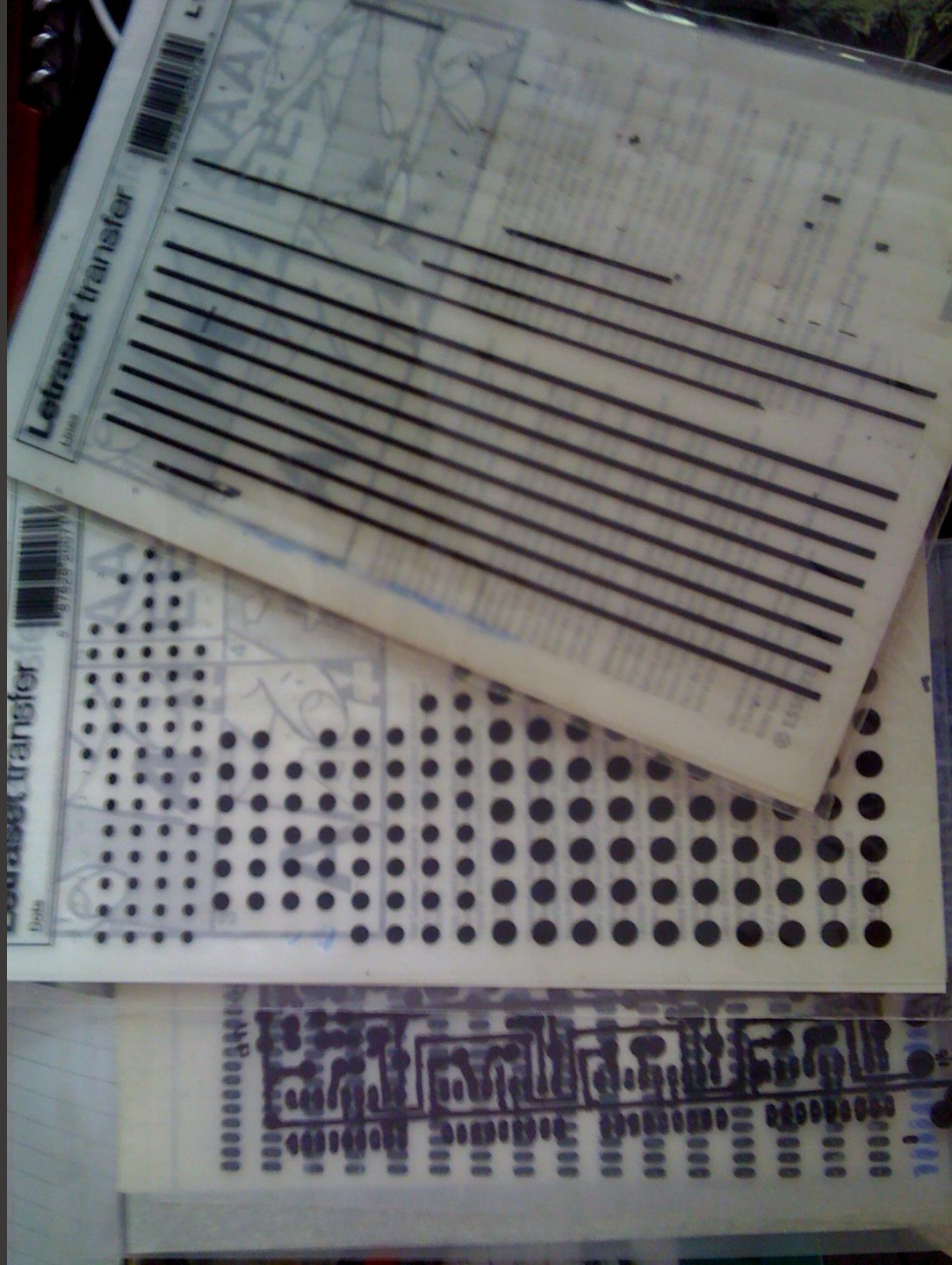


1960



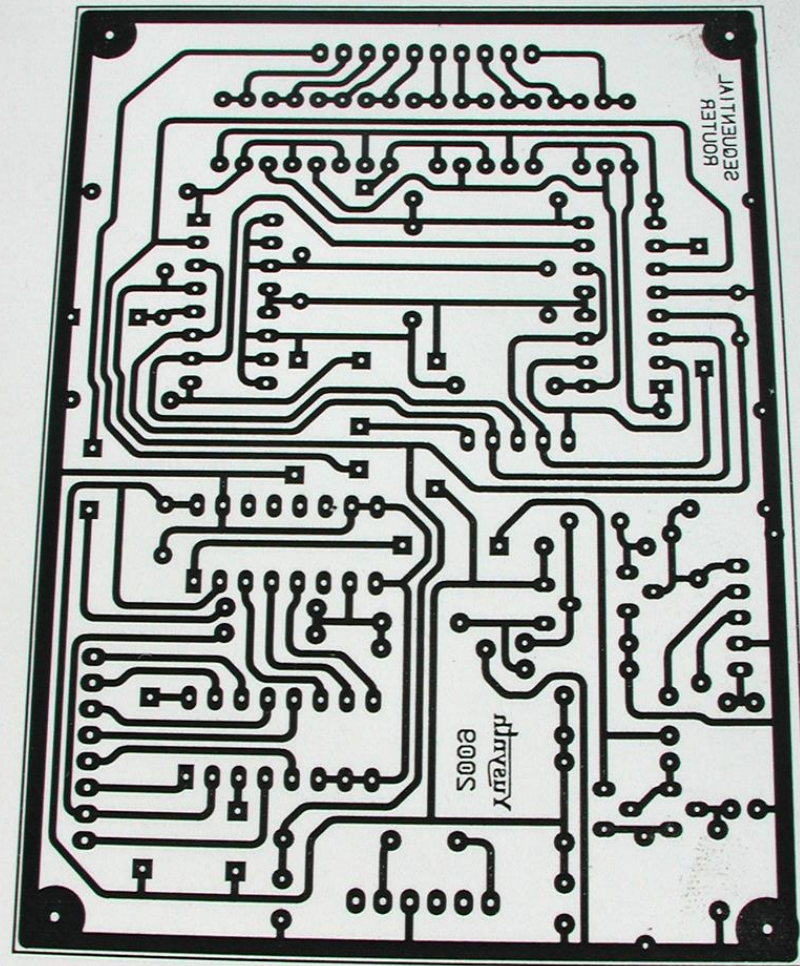
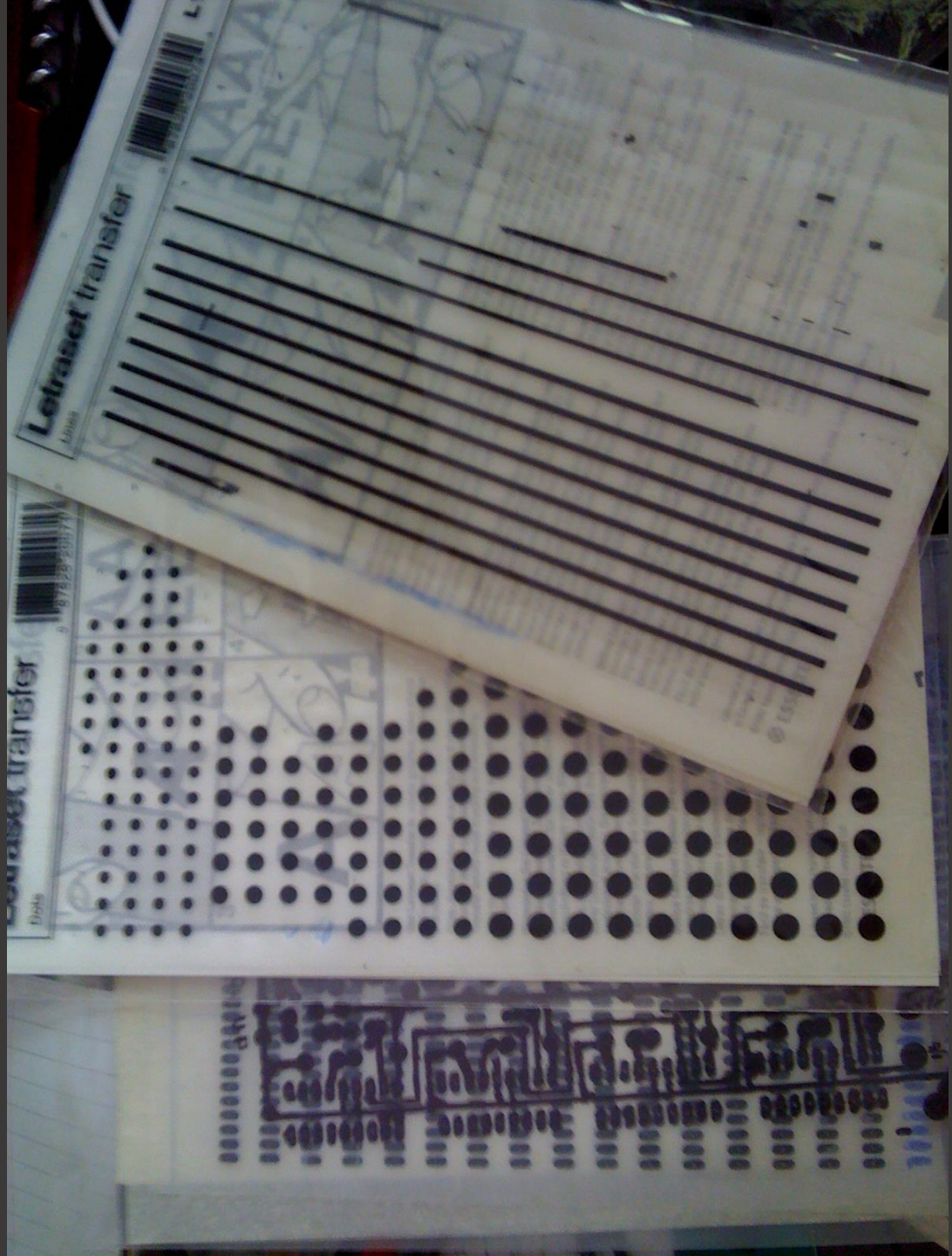


1960





1960





1970

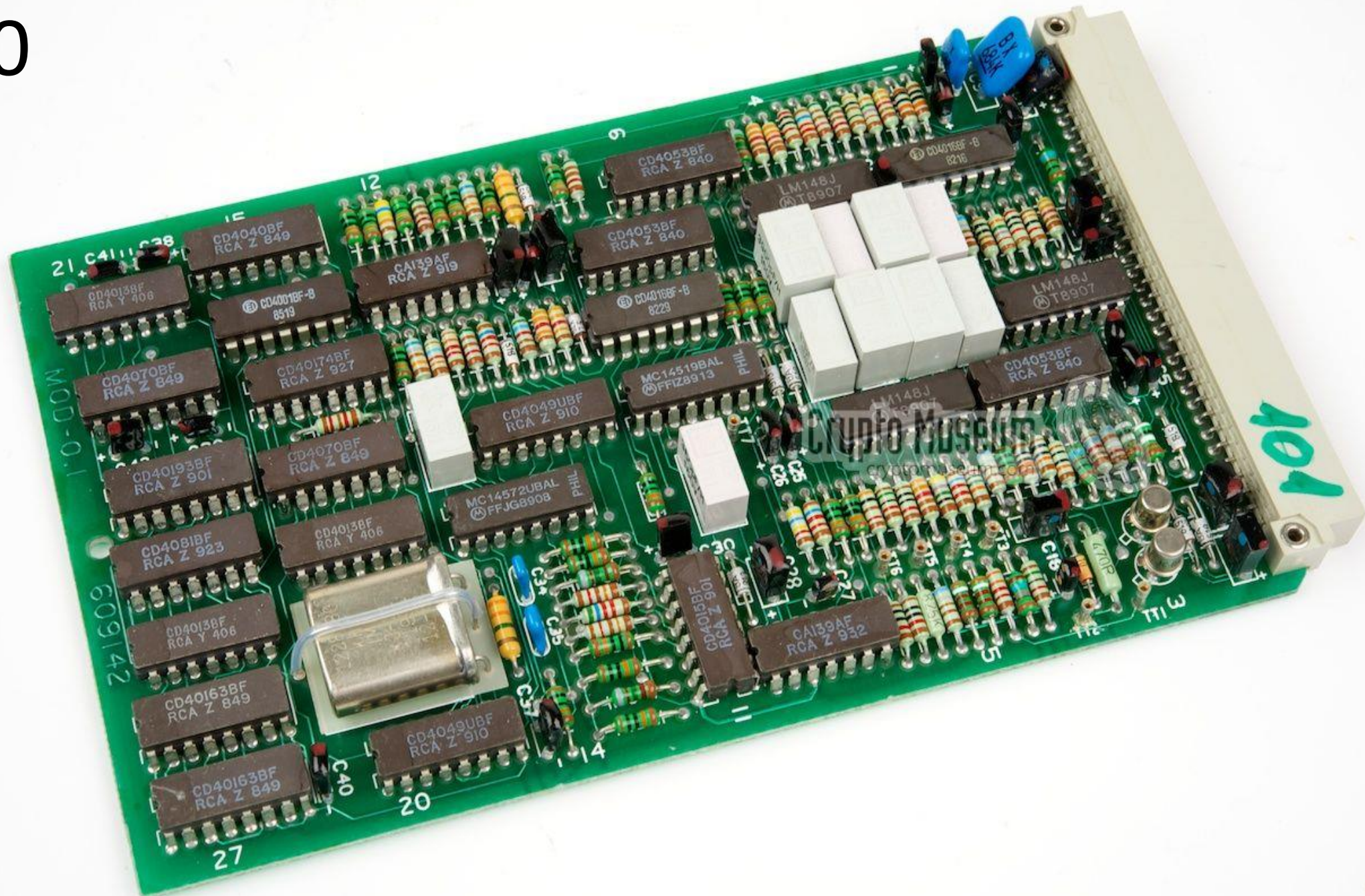




LOOP  
LOAD  
SPOOL



1980





1990



# 2015: Frontline InCAM



109905@pcb1@Action Area

InCAM v3.02SP3 (182283) PID: 39496 User: crv Job: 109905 Step: pcb1 Subsystem: 1-Up Editor Checked Out by: crv

File Edit View Step Layer Tools Netlist Actions Settings Scripts Window Help

Step: pcb1

Global State: 0/40 0/40 2/40 38/40

State	Instruction	User	Start Time	End Time
1	orig	zoran	16/09/2017 07:58	16/09/2017 ...
2	Input_Files_List...	zoran	16/09/2017 07:58	16/09/2017 ...
3	Register_Layers...	zoran	16/09/2017 07:58	16/09/2017 ...
4	Save	zoran	16/09/2017 07:58	16/09/2017 ...
5	PCBx1	crv	13/12/2018 07:15	
6	Run_Script_create_step_pcbx1	zoran	16/09/2017 07:58	16/09/2017 ...
7	Create_Profile...	zoran	16/09/2017 08:01	16/09/2017 ...
8	Datum_Point...	zoran	16/09/2017 08:01	16/09/2017 ...
9	Origin...	zoran	16/09/2017 08:01	16/09/2017 ...
10	Drill_Tool_Manager...	zoran	16/09/2017 08:01	16/09/2017 ...
11	Set_Reference...	zoran	16/09/2017 08:03	16/09/2017 ...
12	duplicate_layers	zoran	16/09/2017 08:06	16/09/2017 ...
13	Clip_Area...	zoran	16/09/2017 08:06	16/09/2017 ...
14	north_touch_copper	zoran	16/09/2017 10:19	16/09/2017 ...
15	Features_Histogram...	zoran	16/09/2017 08:12	16/09/2017 ...
16	Save	zoran	16/09/2017 08:15	16/09/2017 ...
17	Checklists...	crv	13/12/2018 07:16	
18	Compare_Netlists...	zoran	16/09/2017 10:55	16/09/2017 ...
19	Save	zoran	16/09/2017 10:55	16/09/2017 ...
20	RAZSIRI_VEZI	zoran	16/09/2017 12:46	18/09/2017 ...
21	prezent_izolacio	zoran	18/09/2017 14:29	18/09/2017 ...
22	Compare_Netlists...	zoran	18/09/2017 14:30	18/09/2017 ...
23	UL_logo_&oznake	zoran	18/09/2017 14:38	18/09/2017 ...
24	Add_Datum	zoran	18/09/2017 14:38	18/09/2017 ...
25	Save & Delete "*" layers	zoran	18/09/2017 14:38	18/09/2017 ...
26	PCB	zoran	18/09/2017 14:44	18/09/2017 ...
27	Run_Script_start_delivery_panel.csh	zoran	16/09/2017 12:37	16/09/2017 ...
28	Automatic_Part_Placement...	zoran	18/09/2017 14:44	18/09/2017 ...
29	Create_DXF	zoran	18/09/2017 14:44	18/09/2017 ...
30	PANEL	zoran	18/09/2017 14:47	18/09/2017 ...
31	Panelizacia	zoran	18/09/2017 14:47	18/09/2017 ...

Layer

- paste
- tte
- slc
- se
- 12n
- 13
- 14n
- 15
- 16n
- 17n
- 18
- 19n
- 110n
- ss
- sls
- tts
- pastss
- drill\_fin
- ldi

NC Layers

- drf
- rout
- rez
- 109905D
- score
- drf\_pdn

Document Layers

- 109905\_drf

Non-Board Layers

- se\_no\_detch
- 13\_no\_detch
- 15\_no\_detch
- 18\_no\_detch
- 110\_no\_detch
- ss\_no\_detch

Temporary Layers

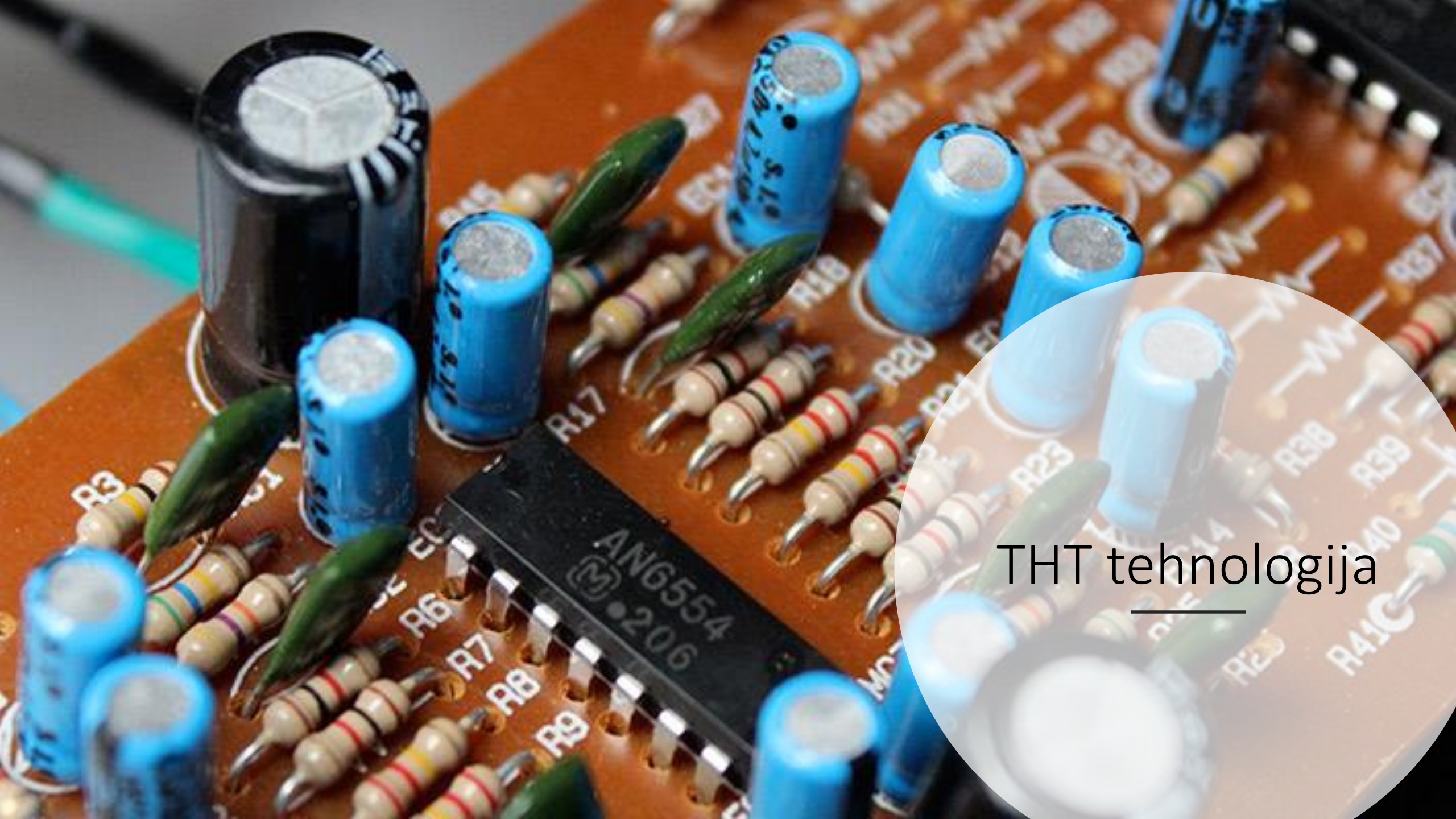
Selected: 0

Scripts:



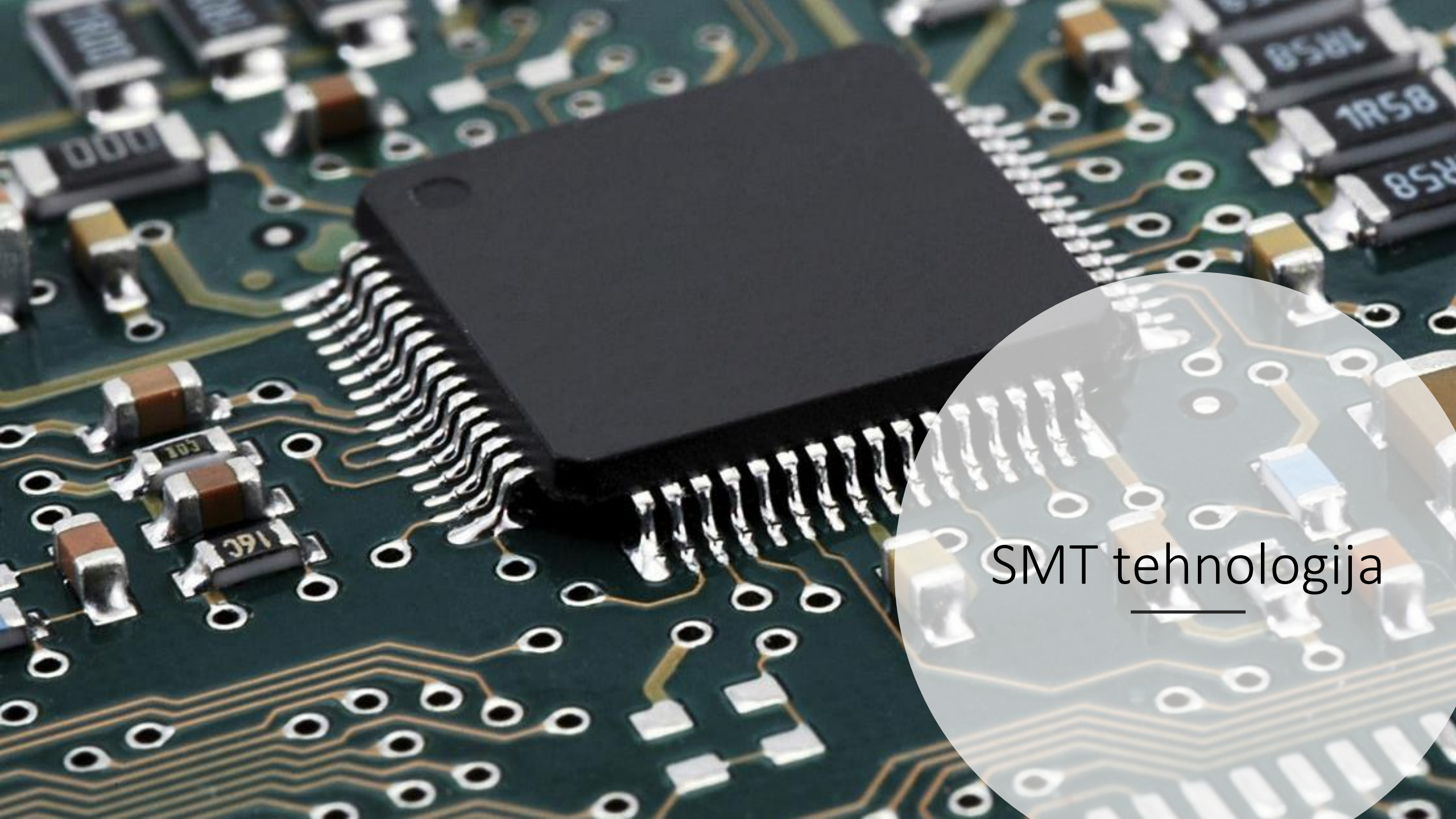
# Razvoj tehnologije montaže elektronskih komponent





THT tehnologija

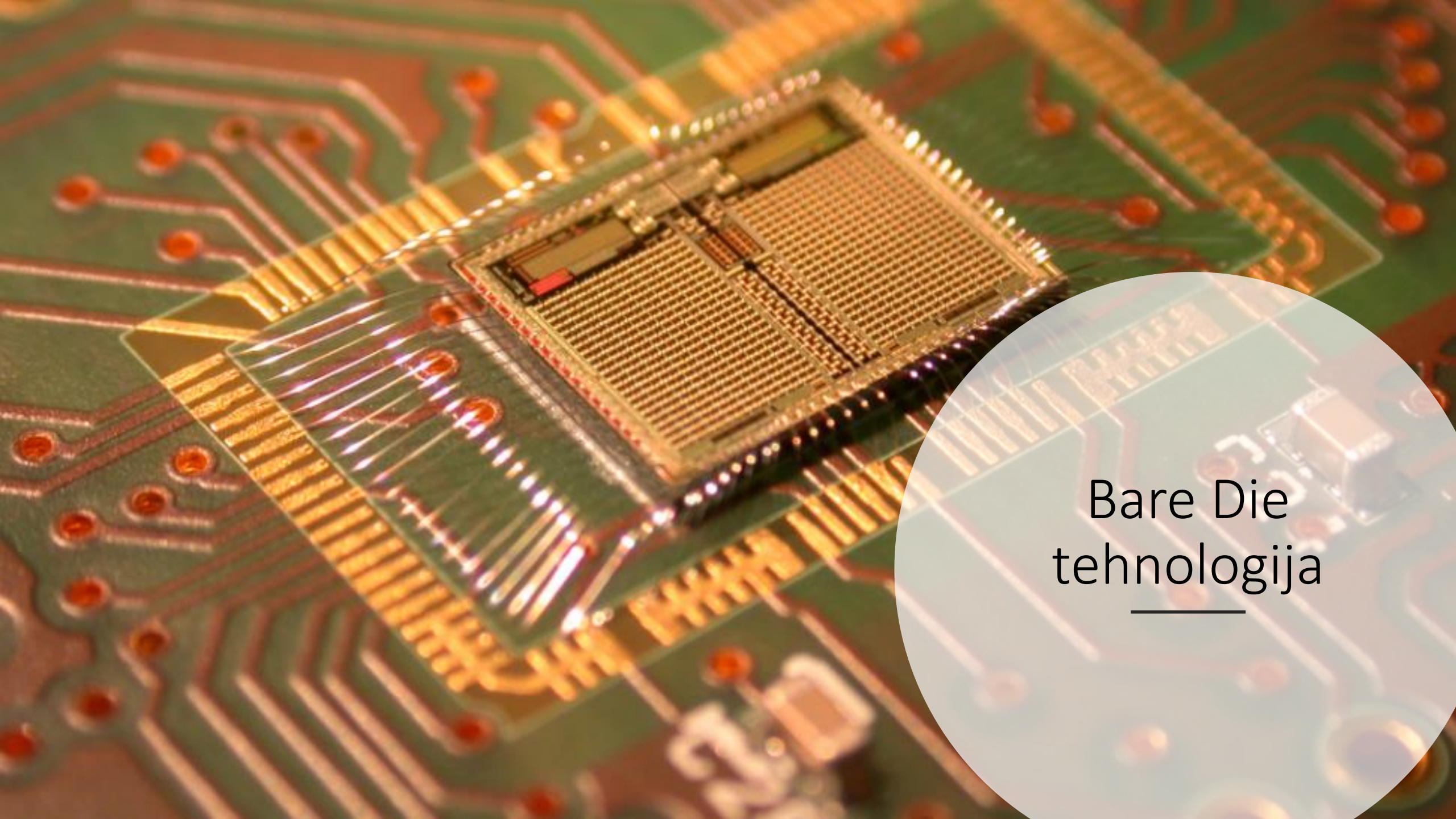




SMT tehnologija

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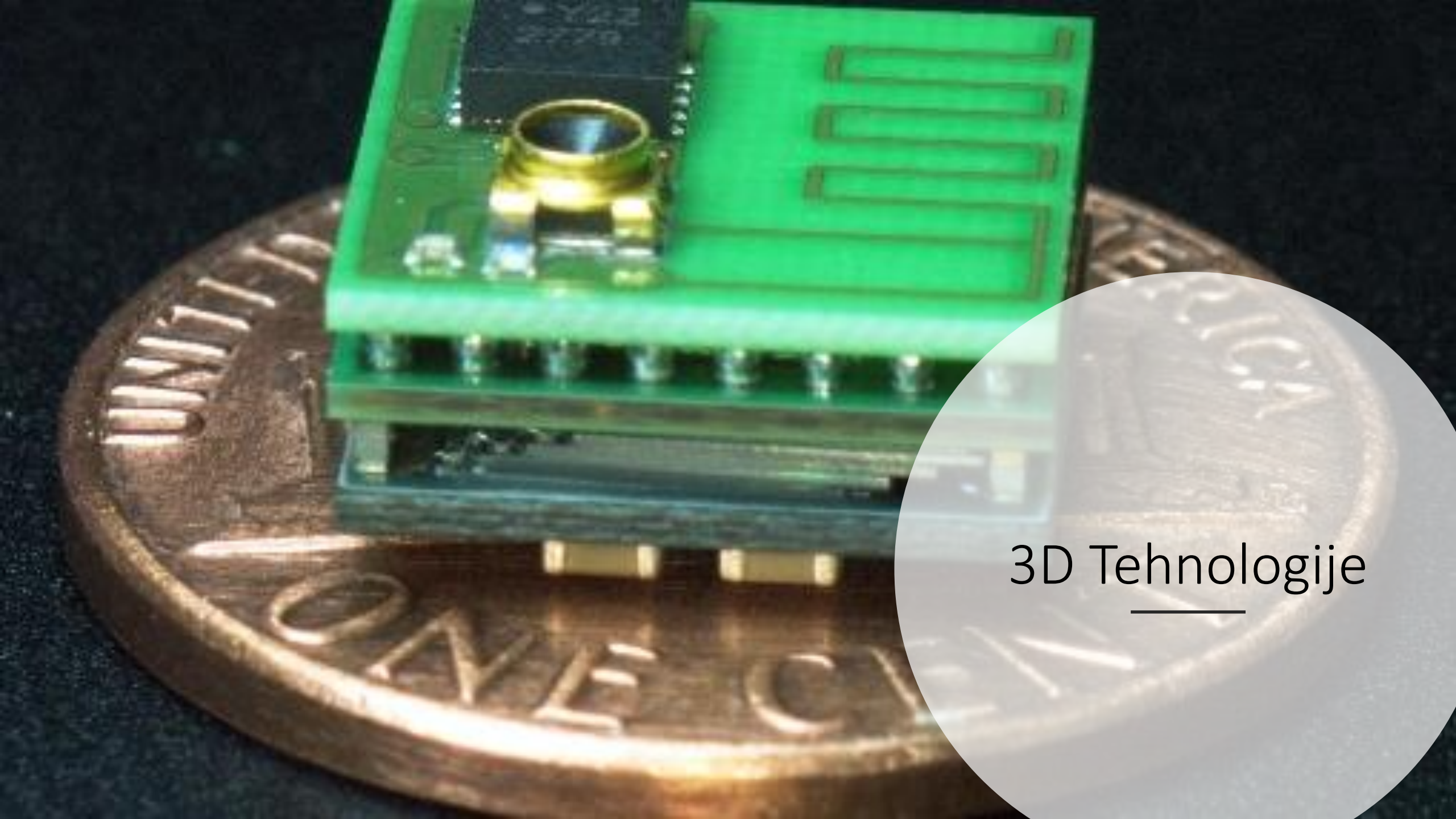




Bare Die  
tehnologija

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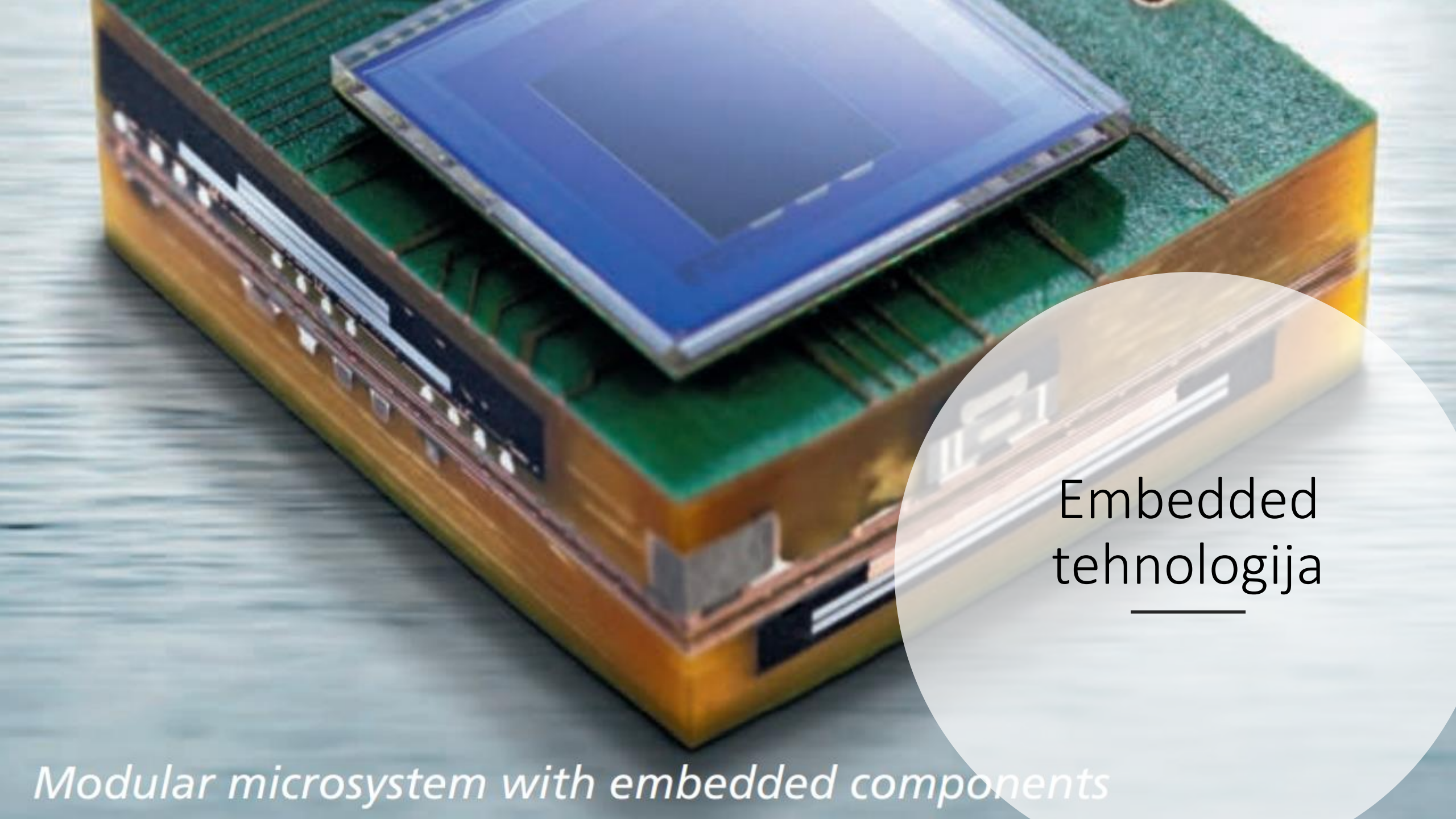




3D Tehnologije

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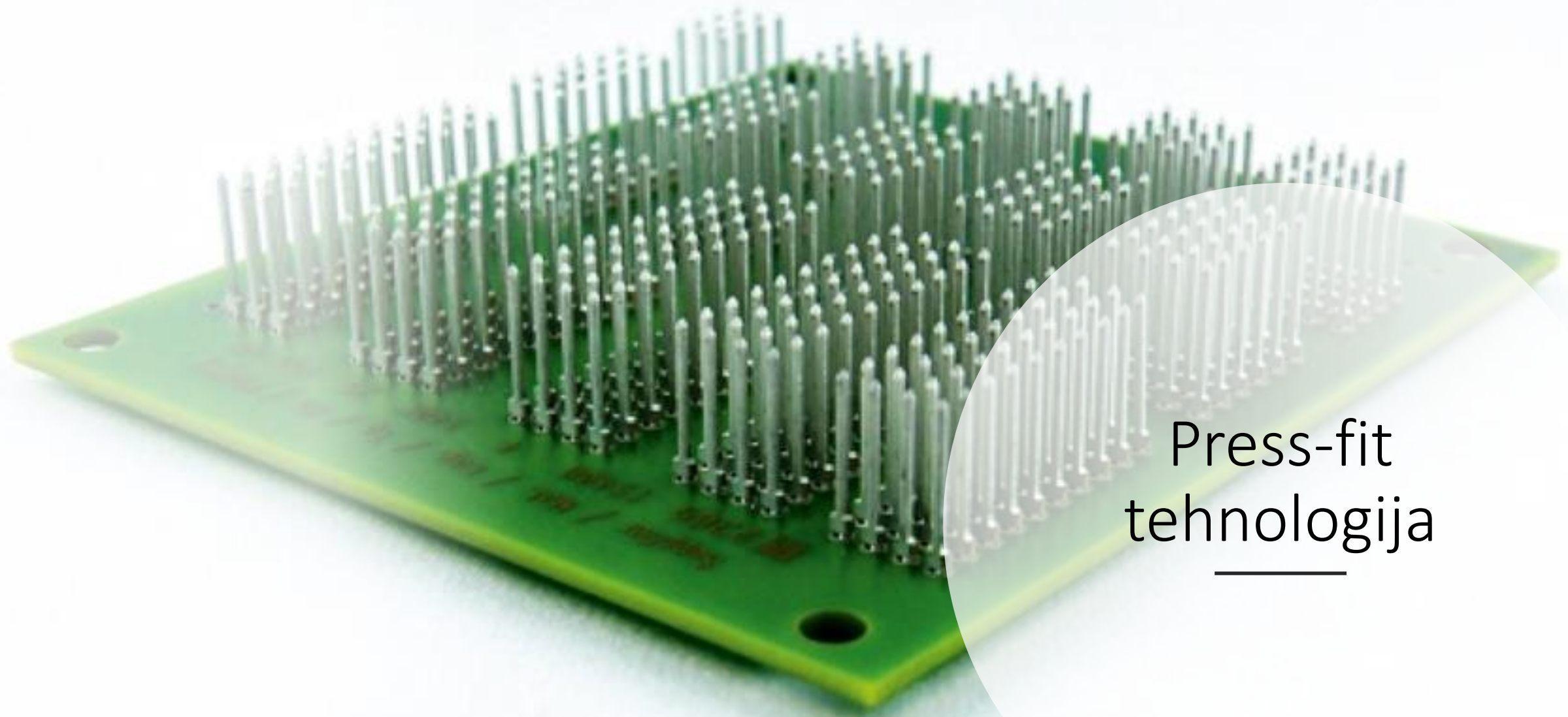


Embedded  
tehnologija

---

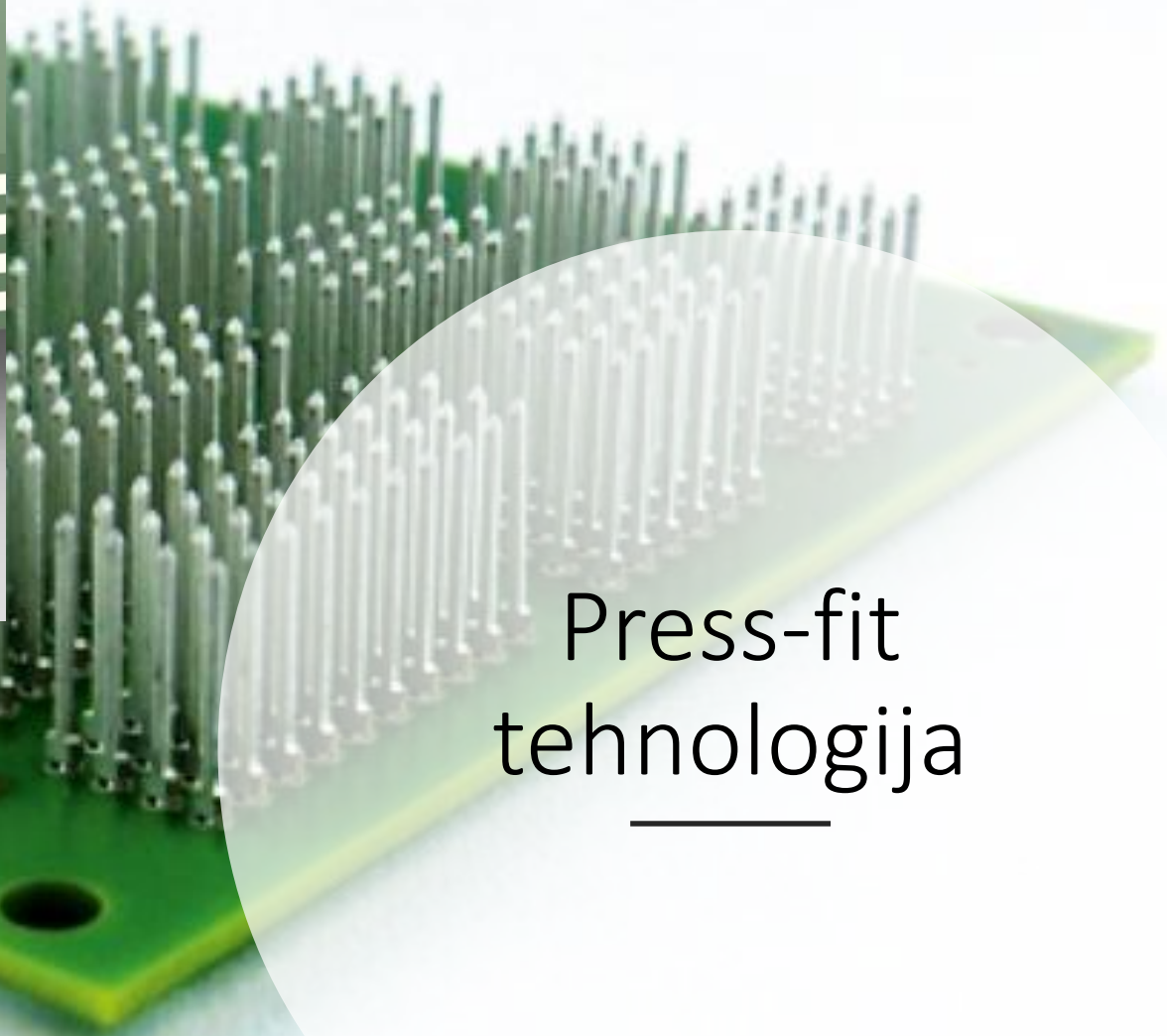
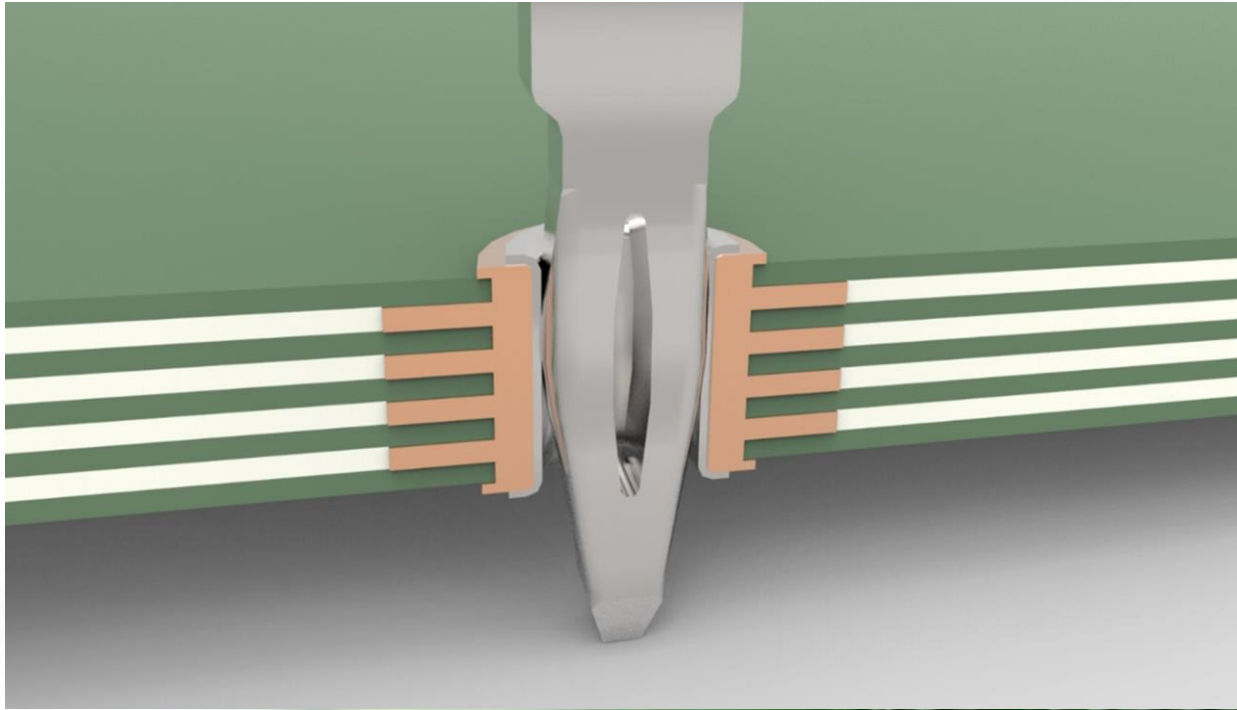
*Modular microsystem with embedded components*





Press-fit  
tehnologija





Press-fit  
tehnologija

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## HDI SBU

High Density Interconnection Sequential Build Up

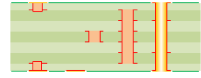


# ML8 HDI SBU struktura

(2x stiskanje)

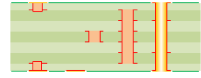


ML8 HDI SBU



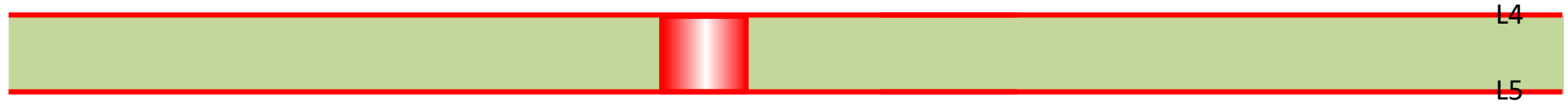
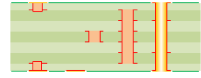


ML8 HDI SBU

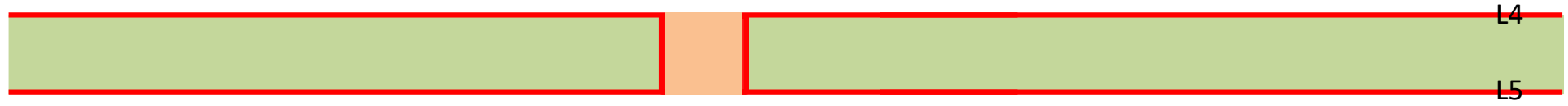
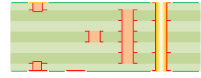




ML8 HDI SBU

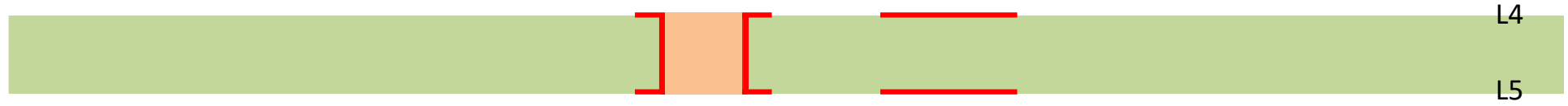
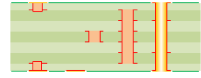


ML8 HDI SBU

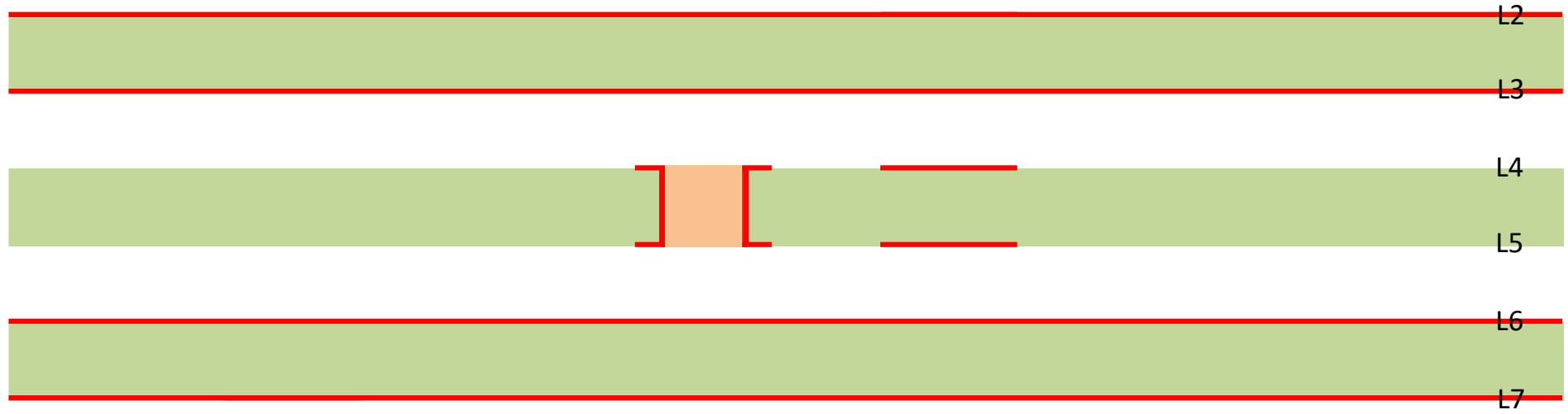
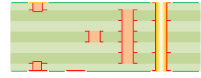




ML8 HDI SBU

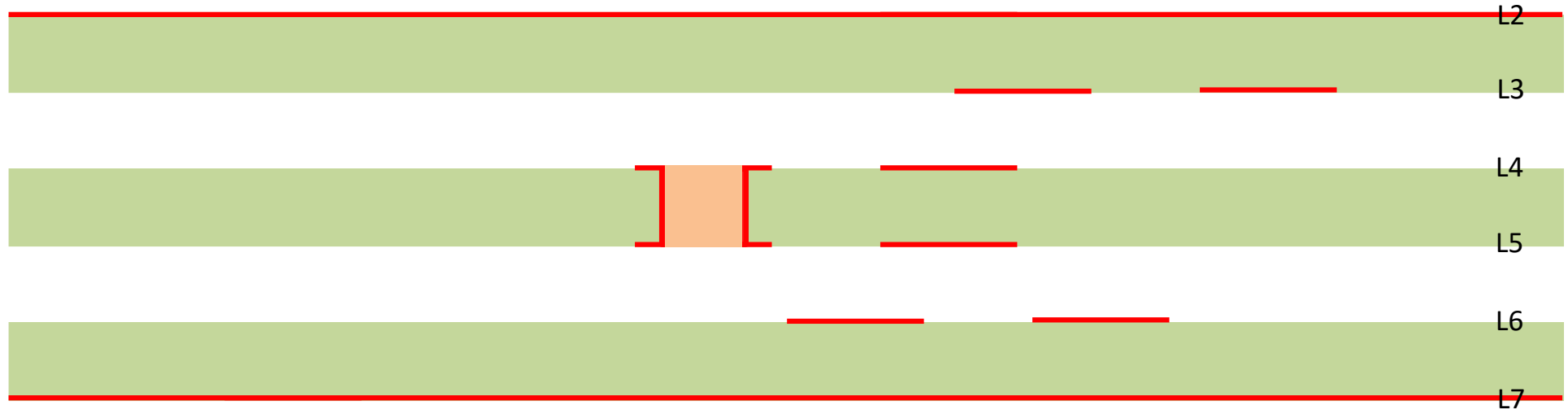
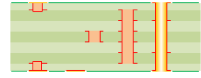


# ML8 HDI SBU

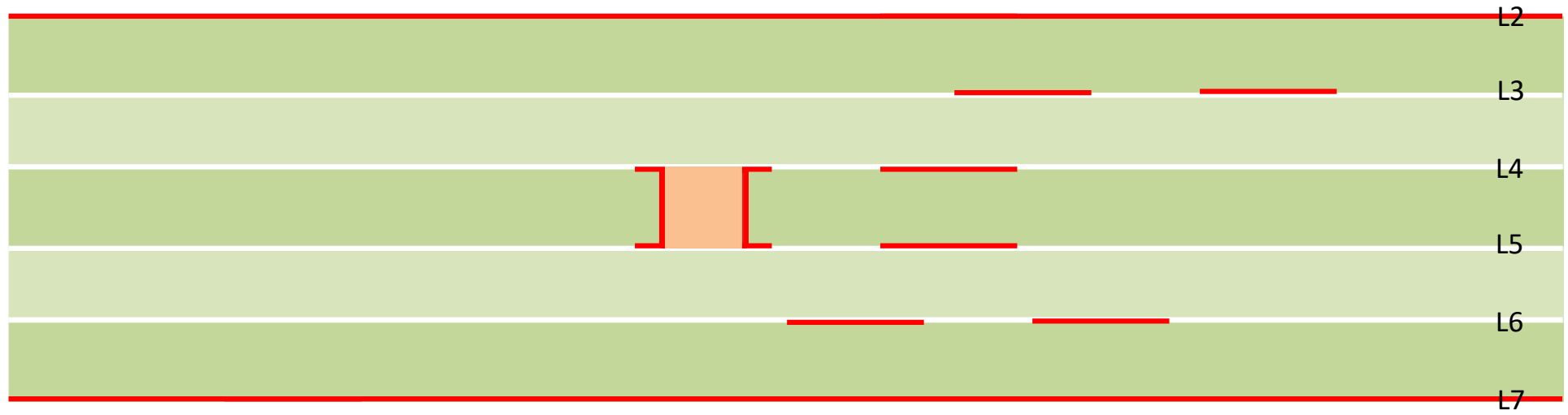
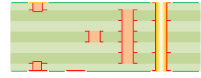




# ML8 HDI SBU

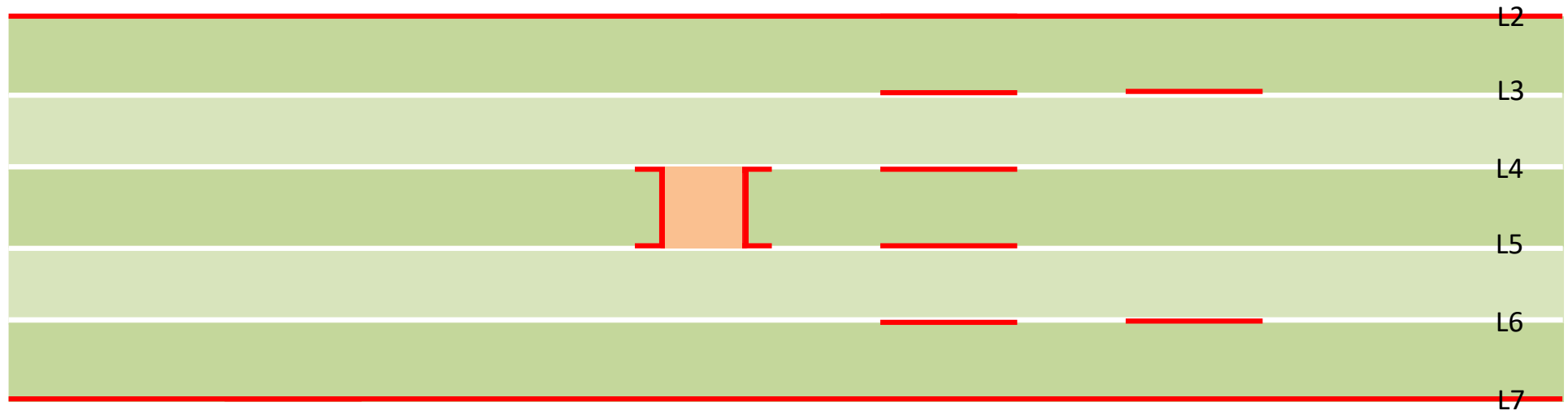
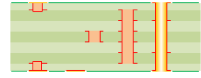


# ML8 HDI SBU

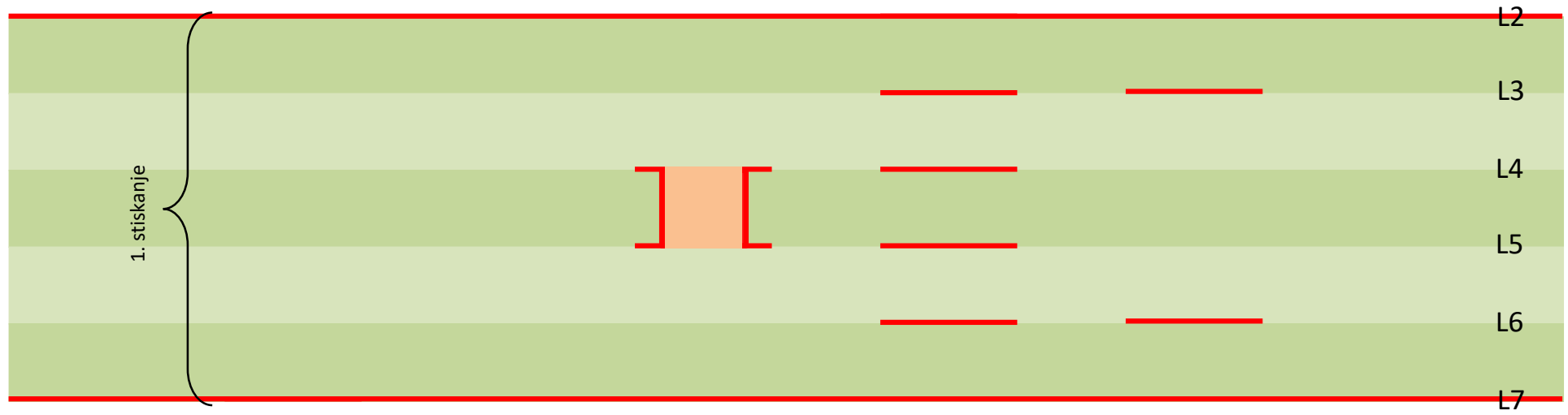
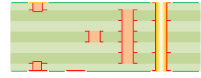




# ML8 HDI SBU

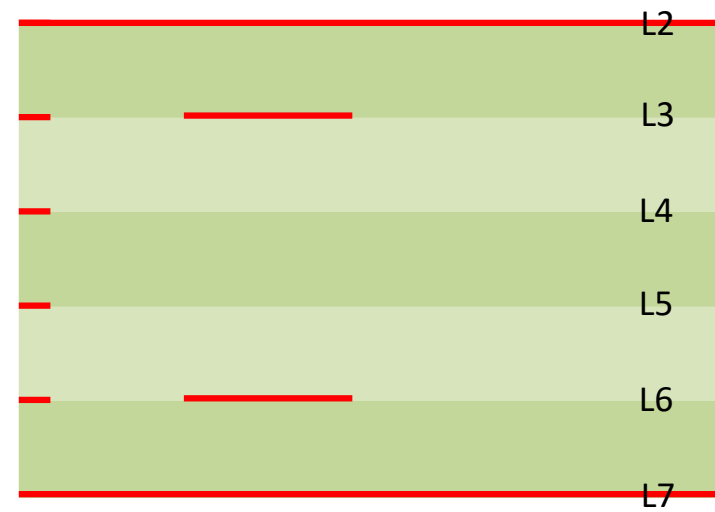
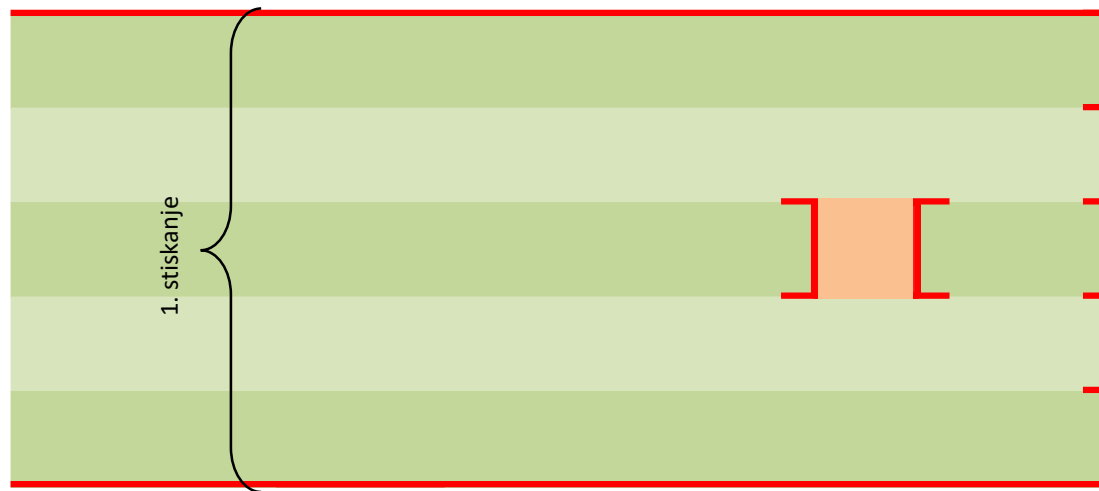
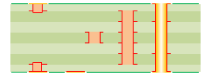


# ML8 HDI SBU

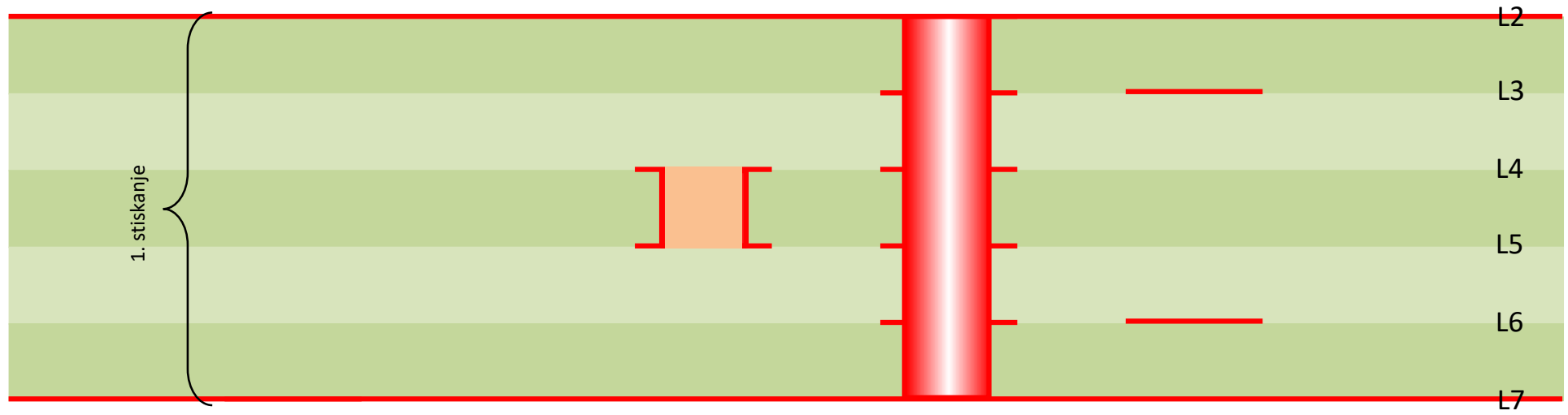
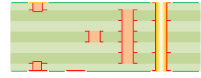




# ML8 HDI SBU

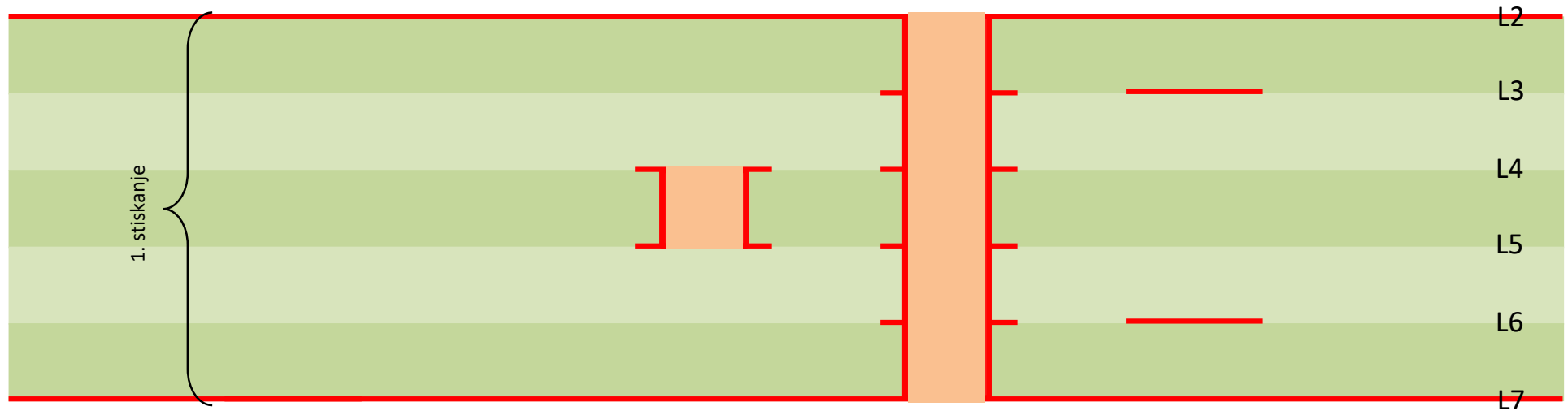
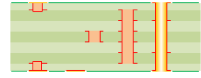


# ML8 HDI SBU

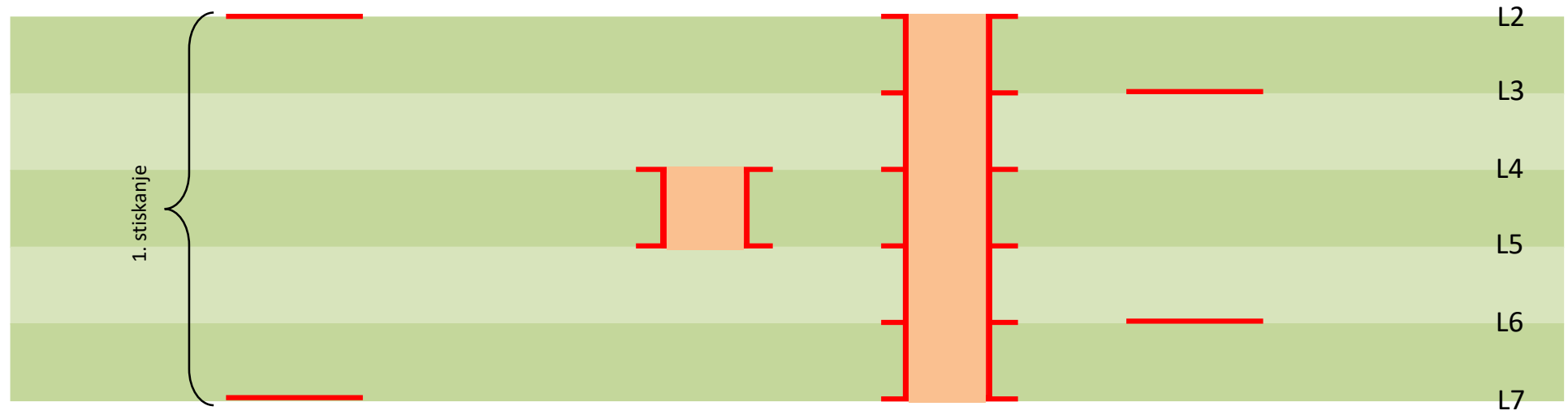
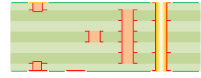




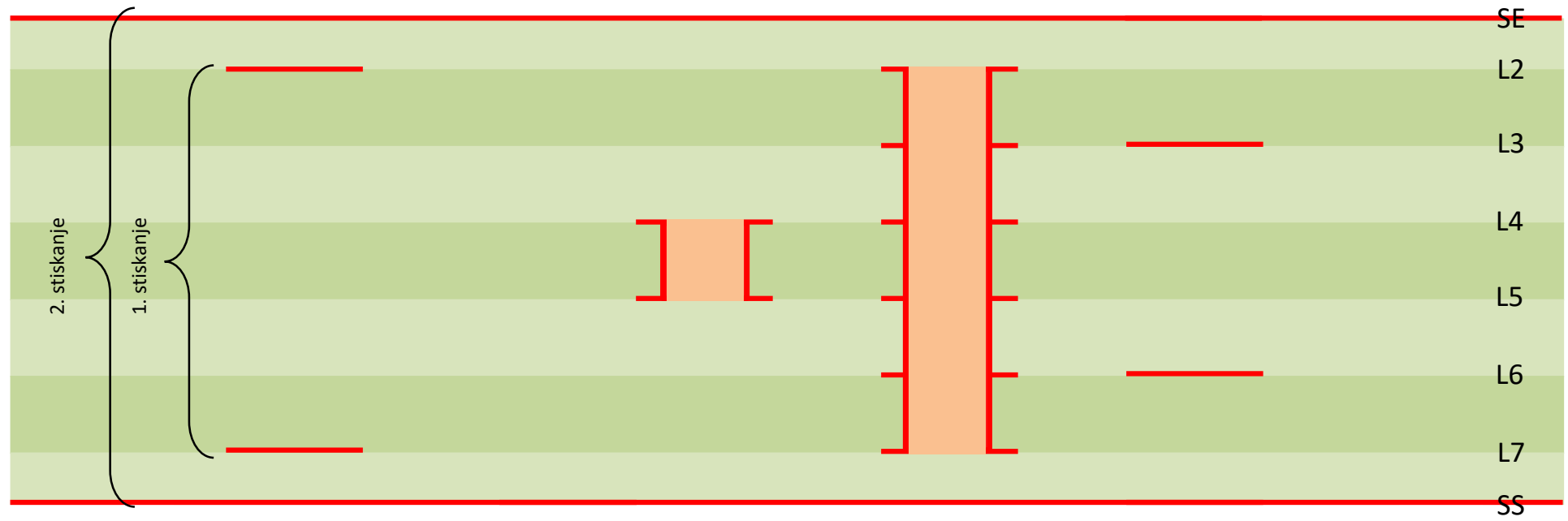
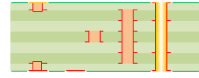
# ML8 HDI SBU



# ML8 HDI SBU



# ML8 HDI SBU



SE

L2

L3

L4

L5

L6

L7

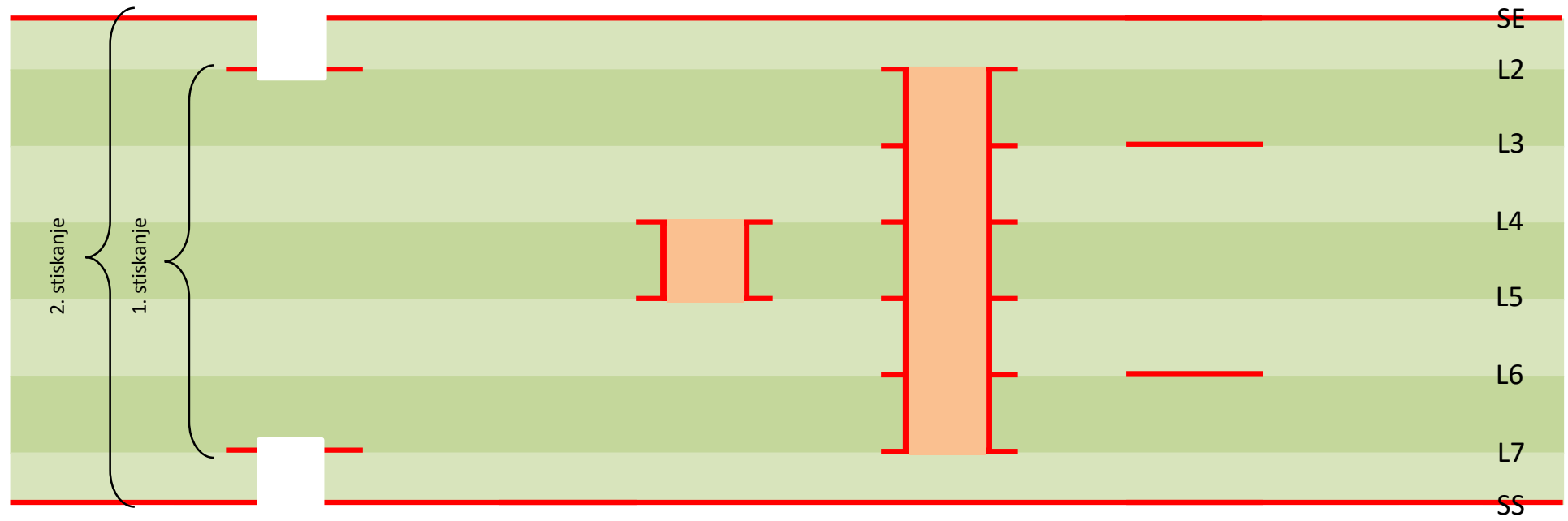
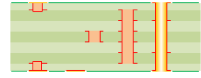
SS

2. stiskanje

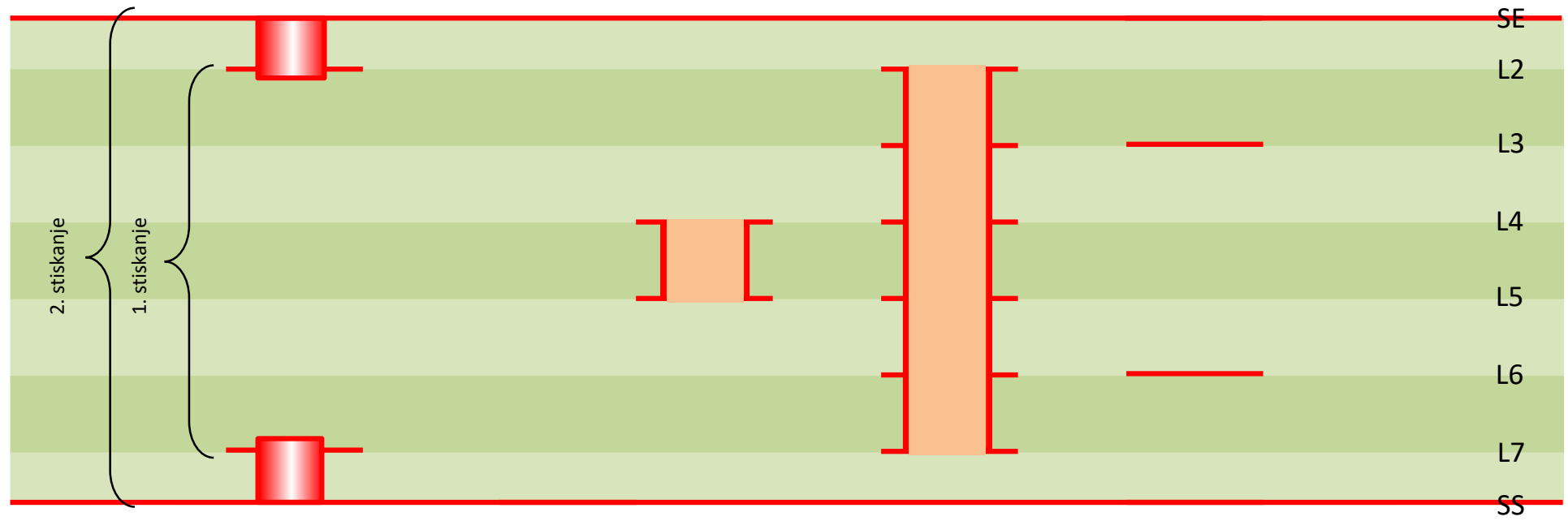
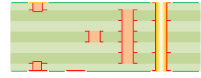
1. stiskanje



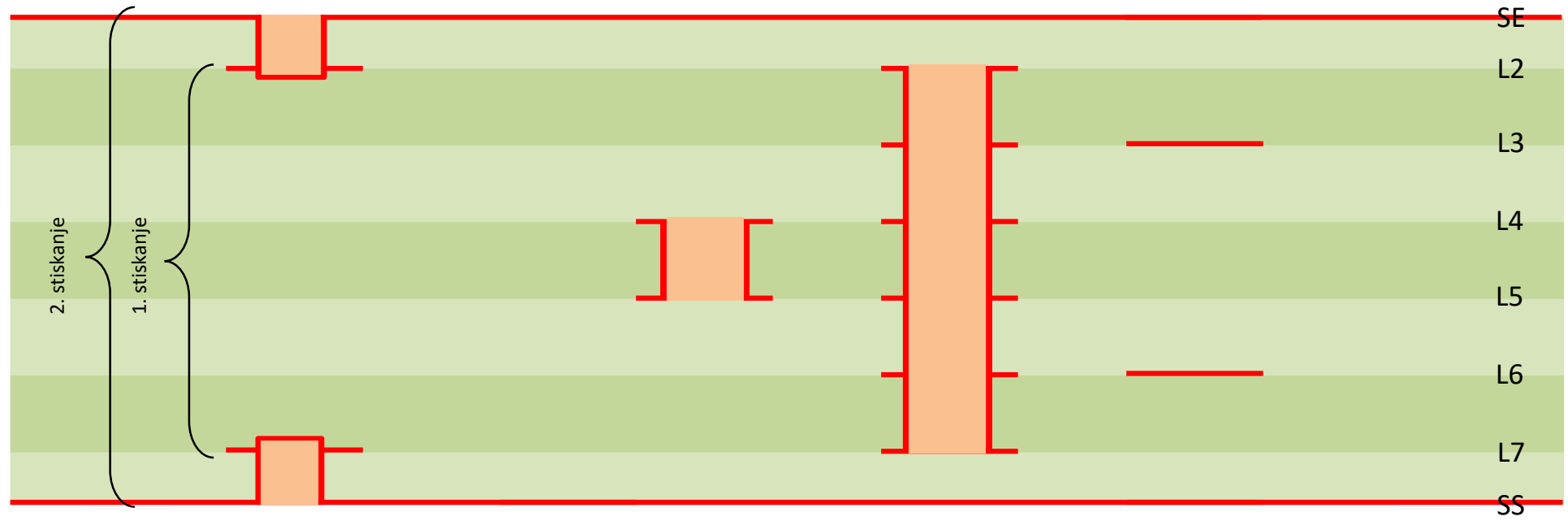
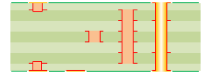
# ML8 HDI SBU



# ML8 HDI SBU

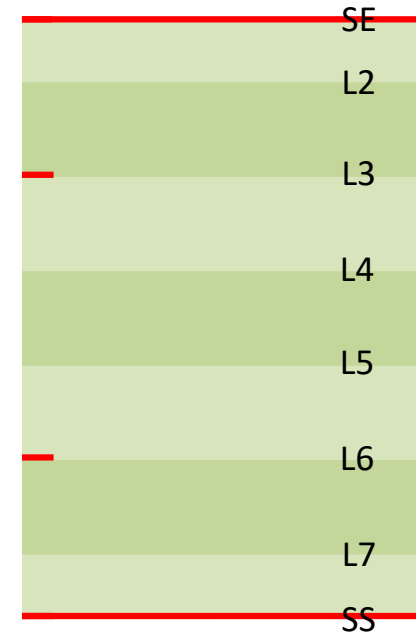
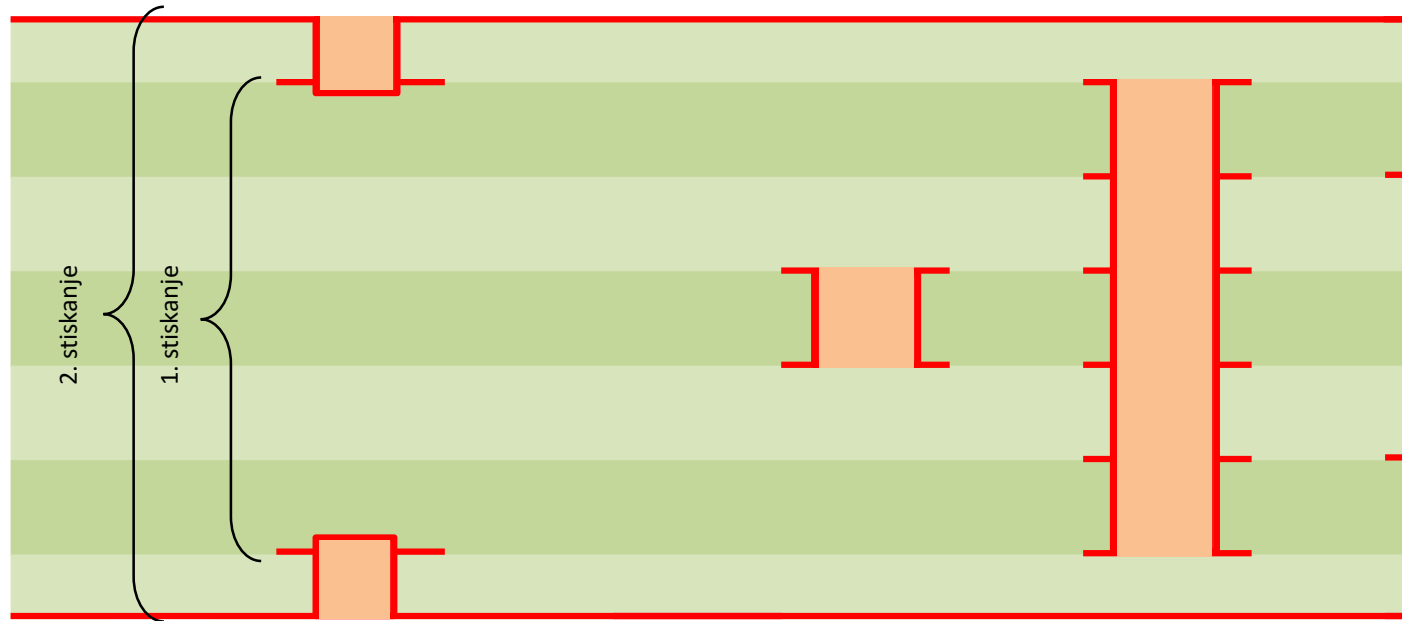
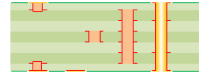


# ML8 HDI SBU

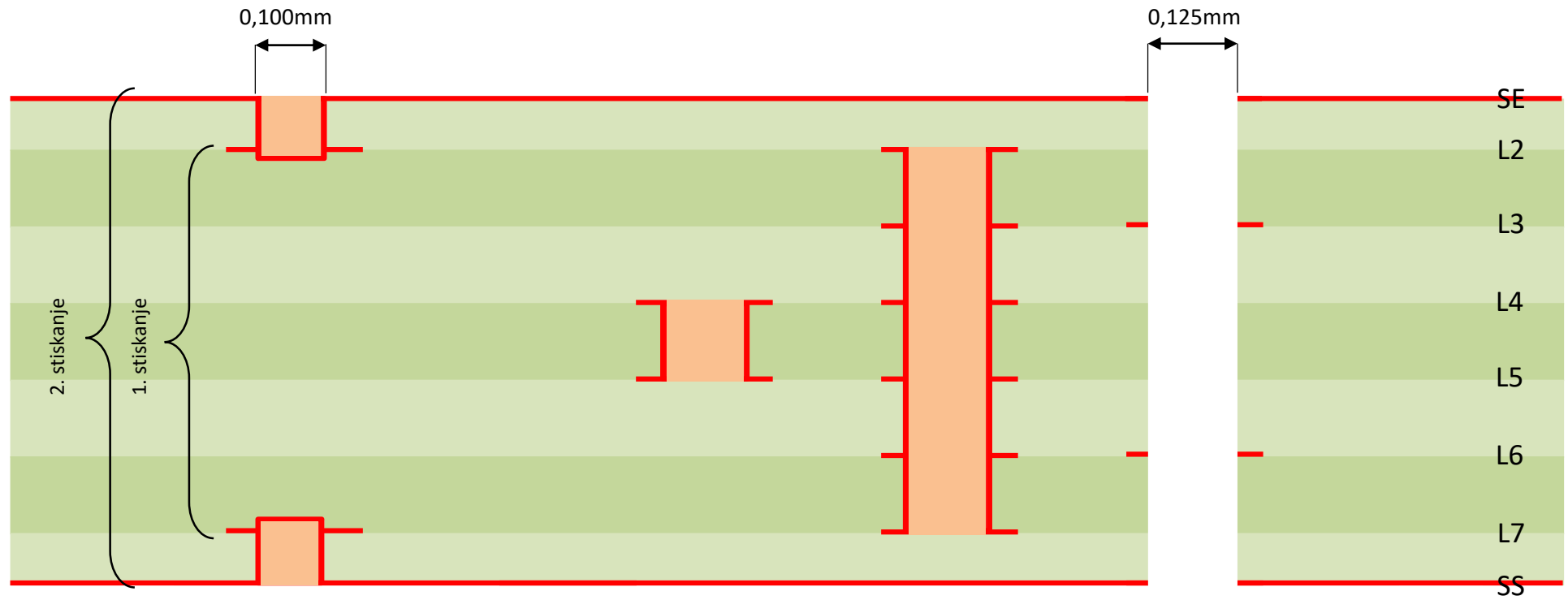
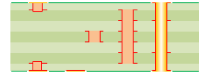




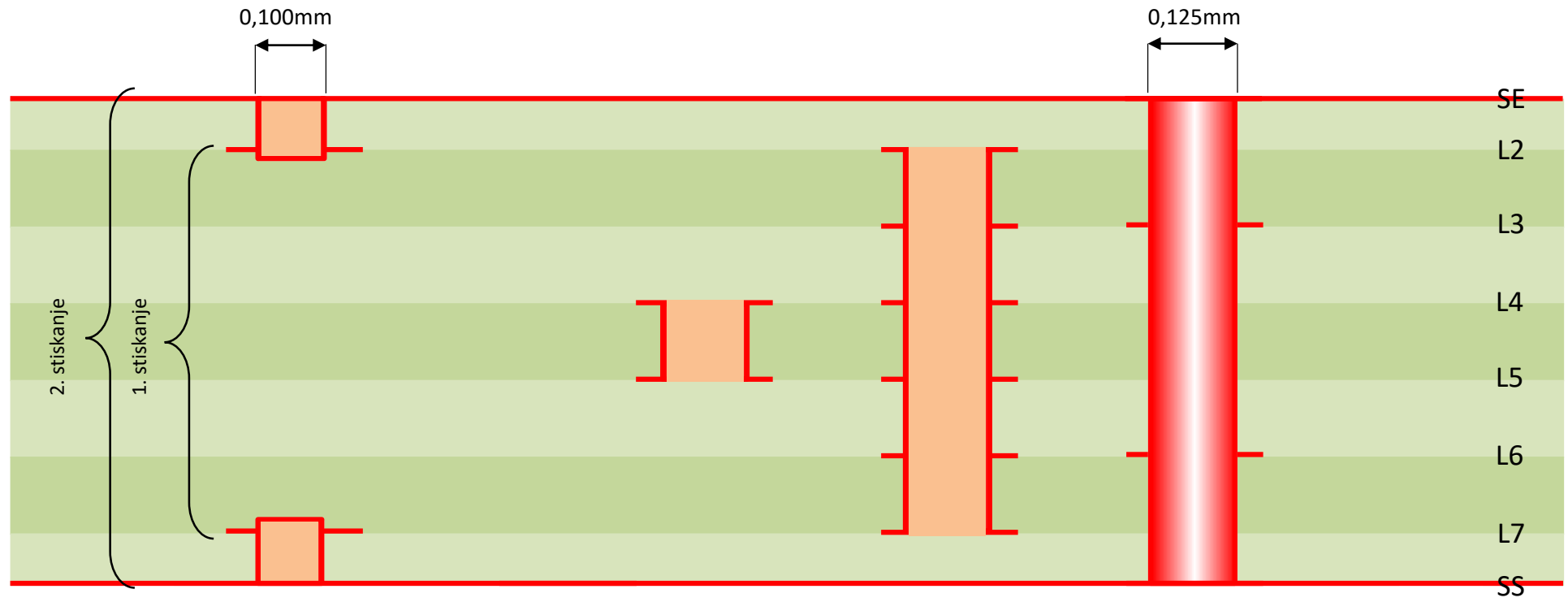
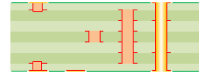
# ML8 HDI SBU



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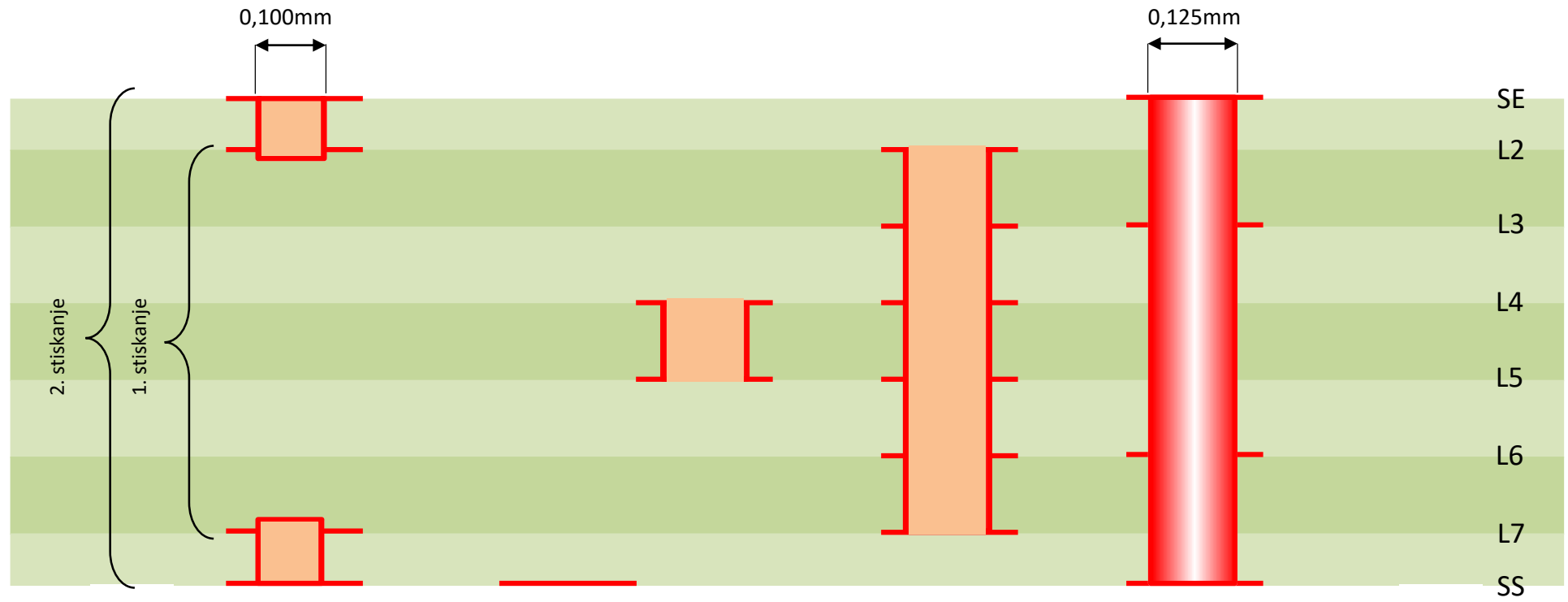
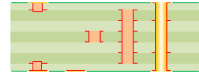


# ML8 HDI SBU

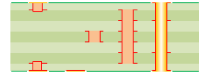




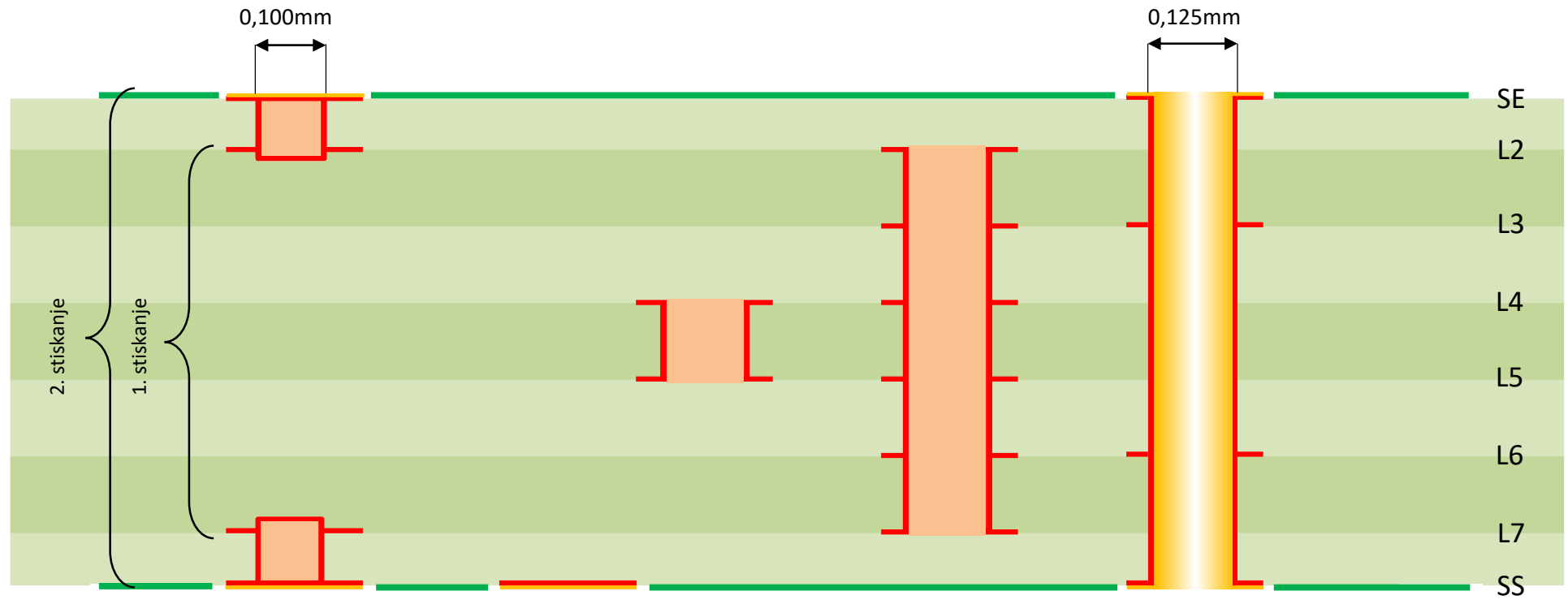
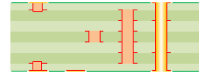
# ML8 HDI SBU



# ML8 HDI SBU

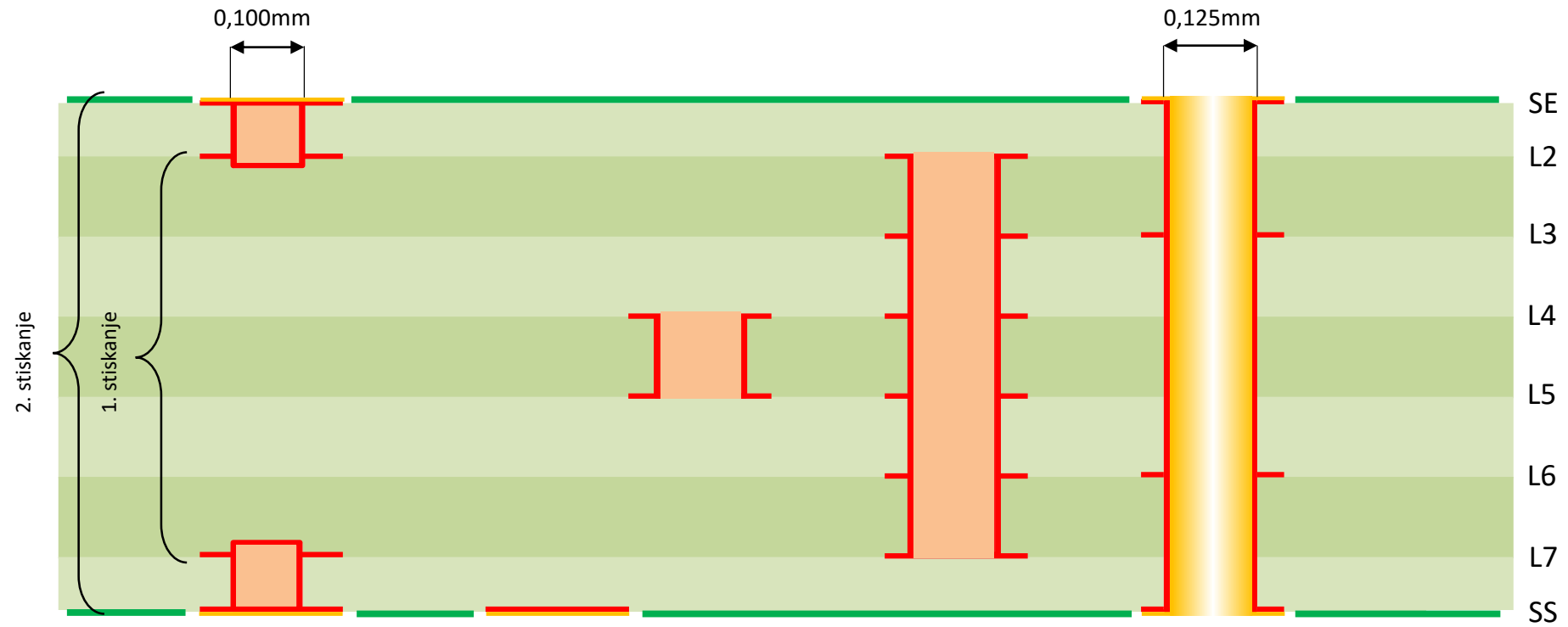
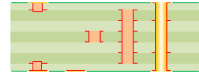


# ML8 HDI SBU

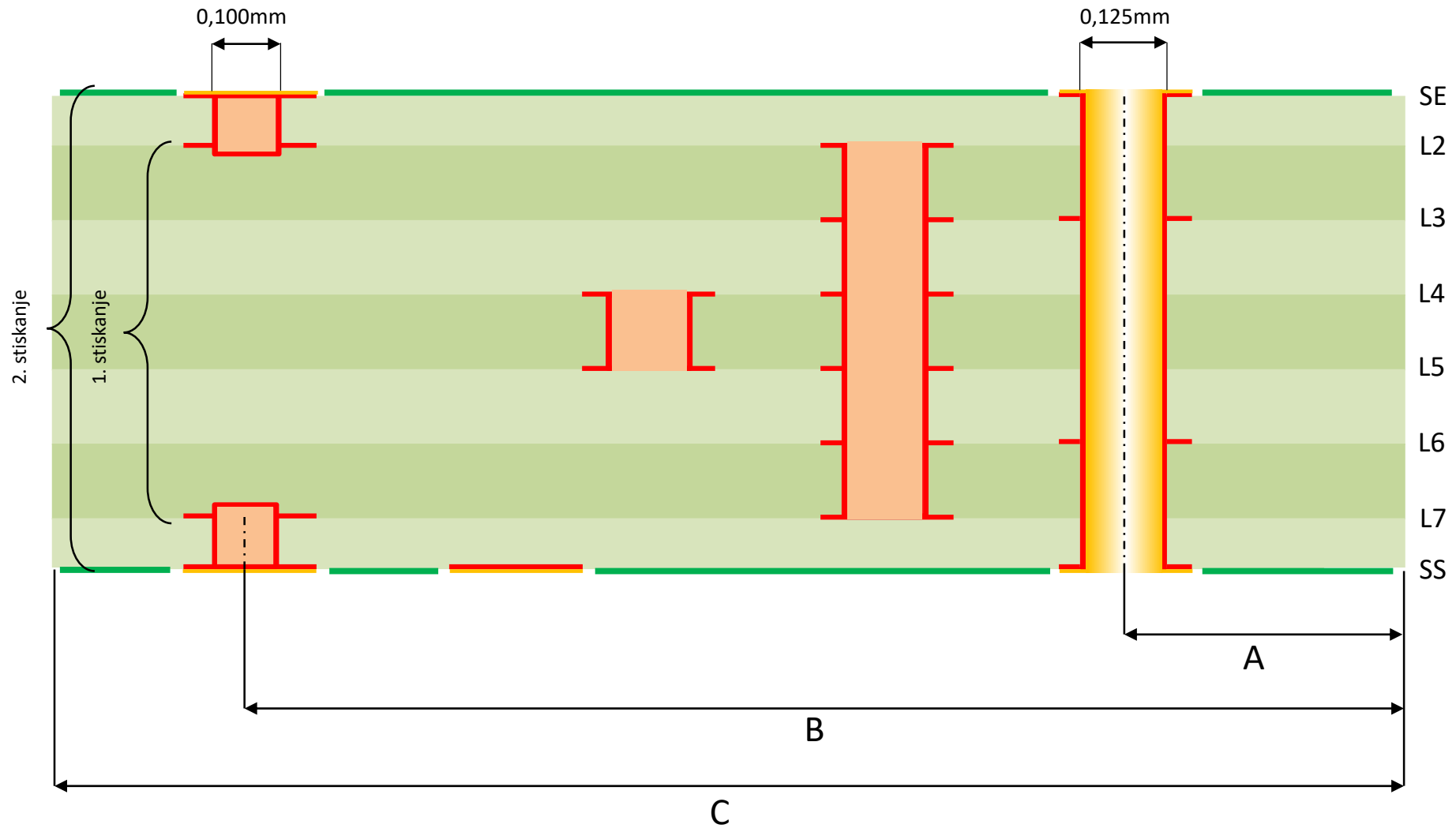
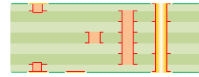




# ML8 HDI SBU



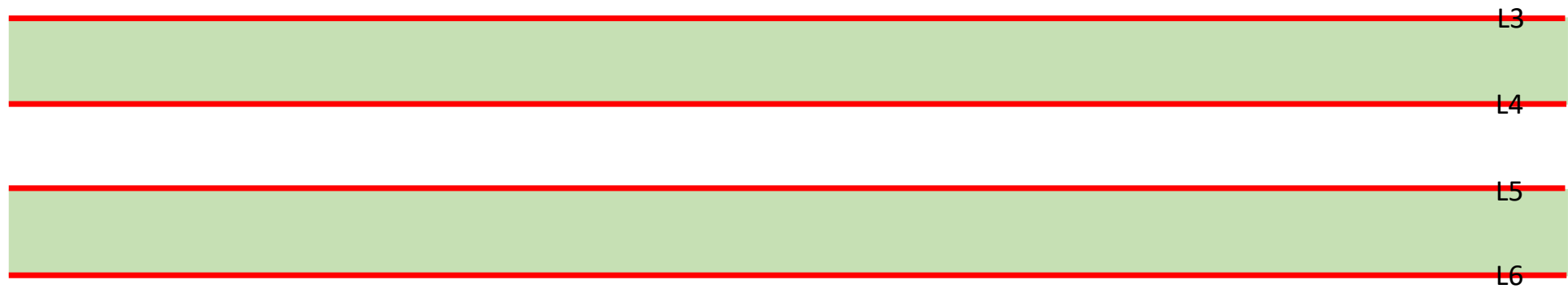
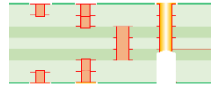
# ML8 HDI SBU



# ML8 HDI SBU struktura

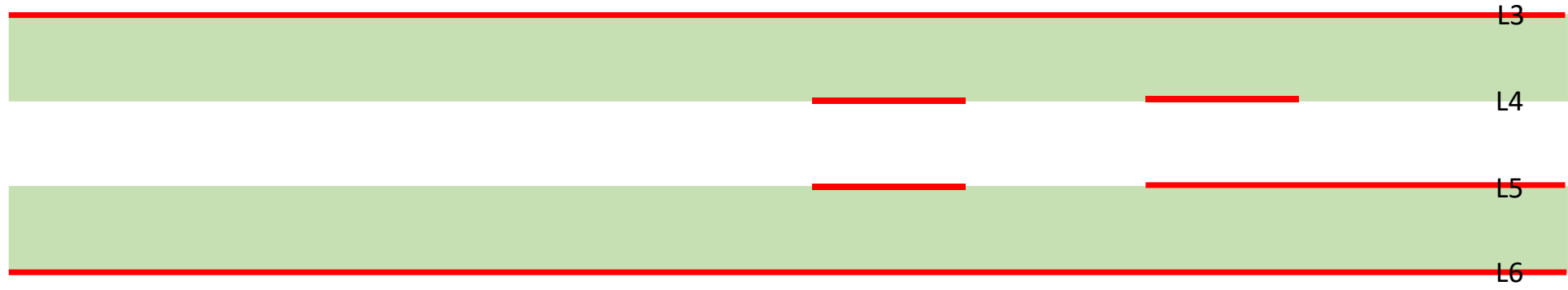
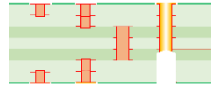
(3x stiskanje)

ML8 HDI SBU

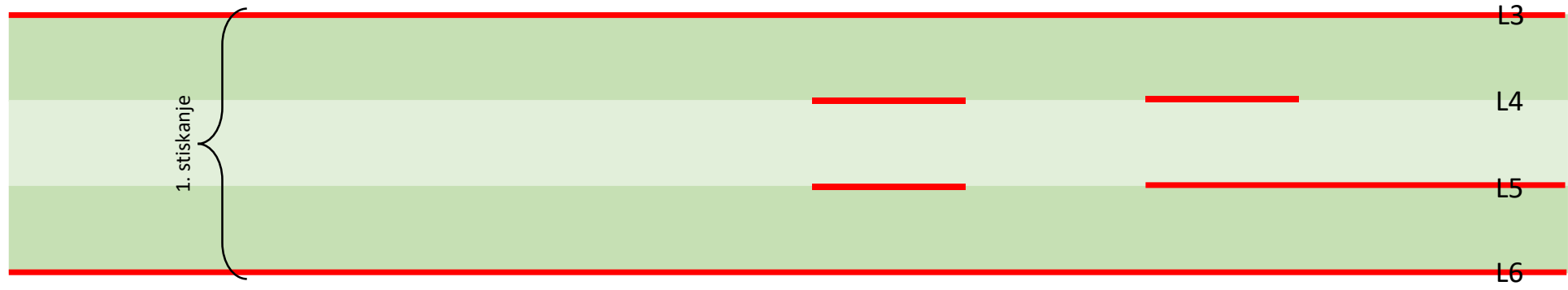
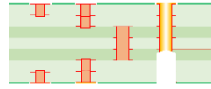




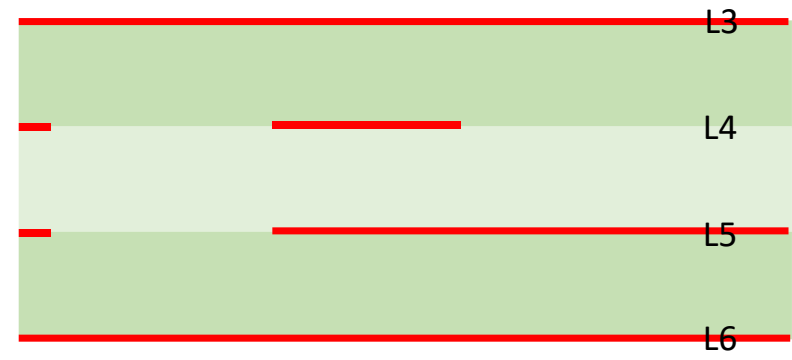
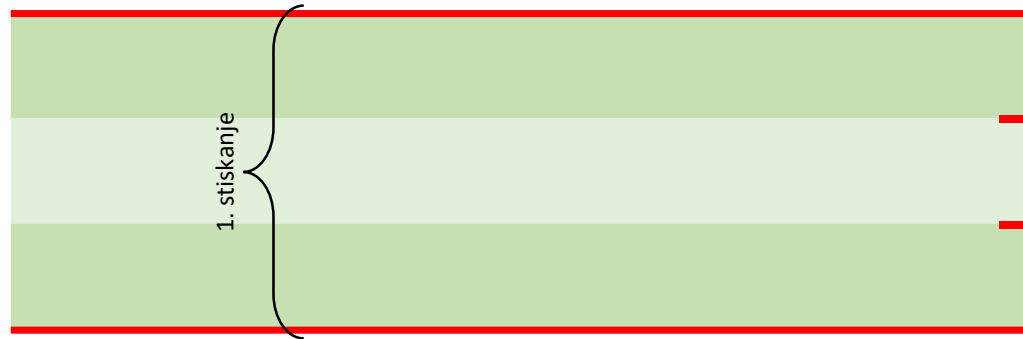
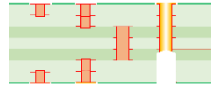
ML8 HDI SBU



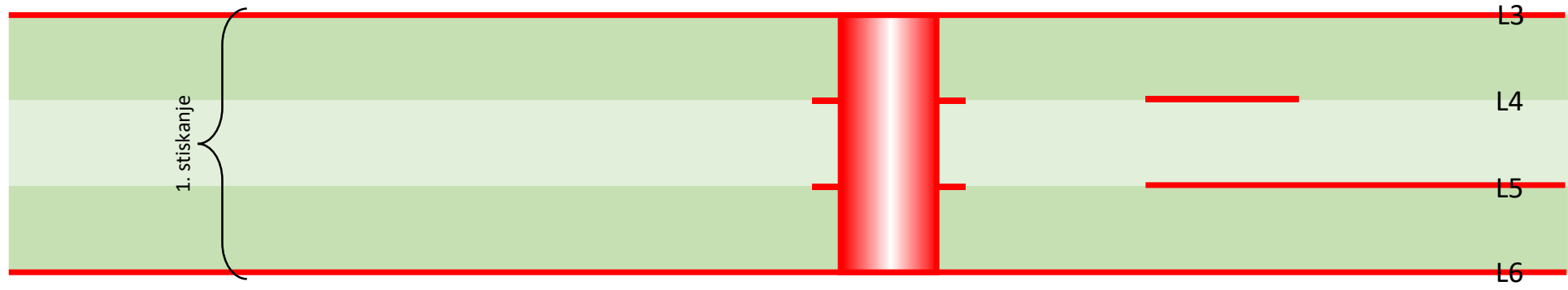
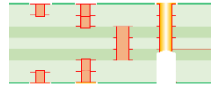
# ML8 HDI SBU



# ML8 HDI SBU

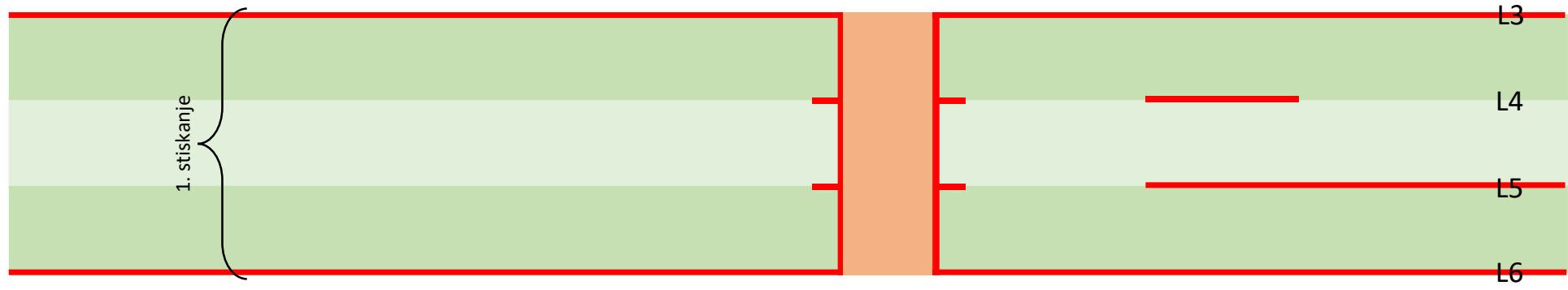
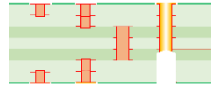


# ML8 HDI SBU

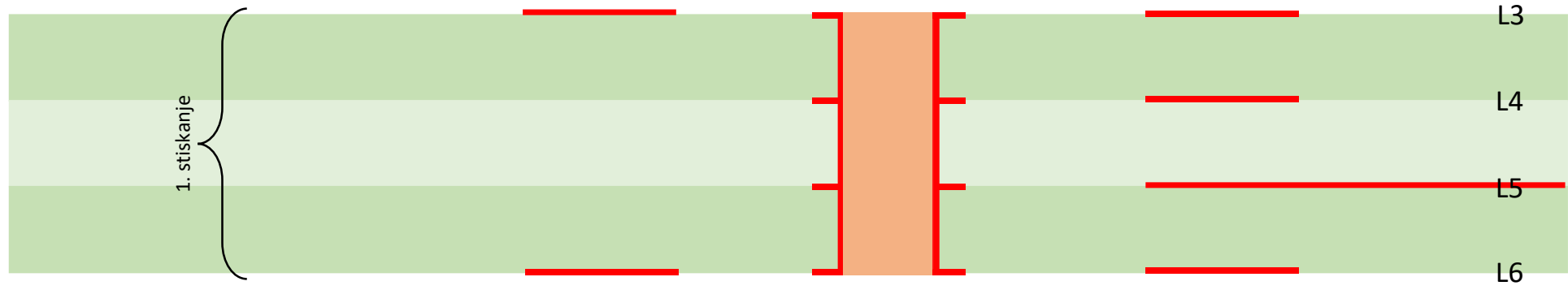
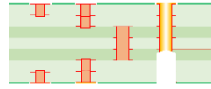




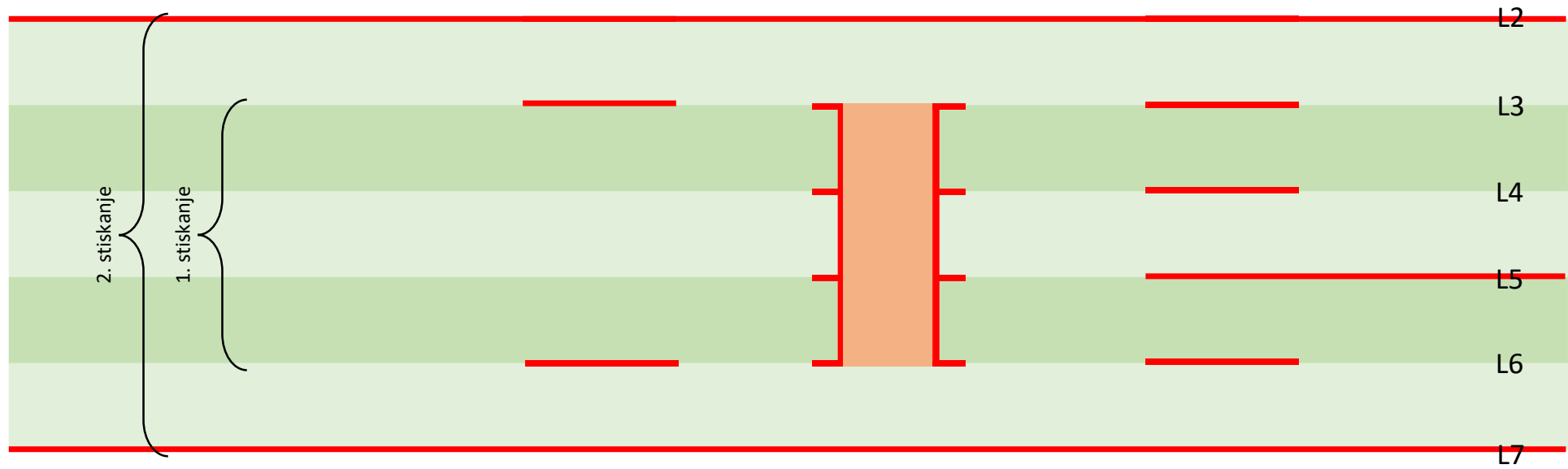
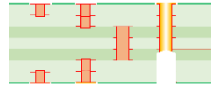
# ML8 HDI SBU



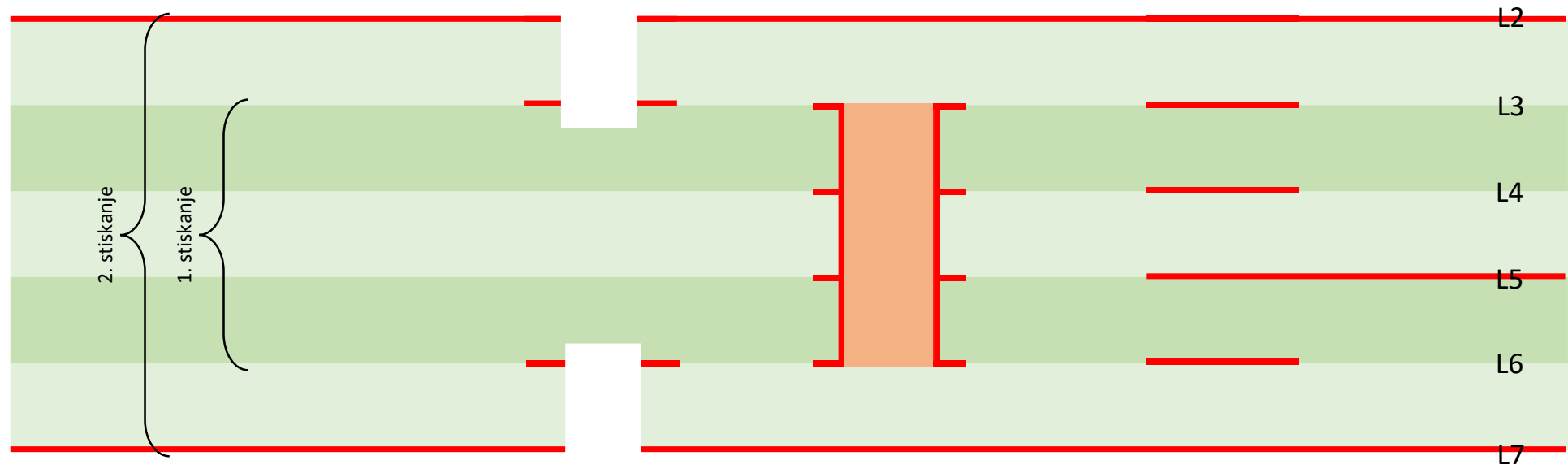
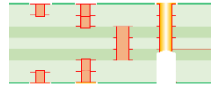
# ML8 HDI SBU



# ML8 HDI SBU

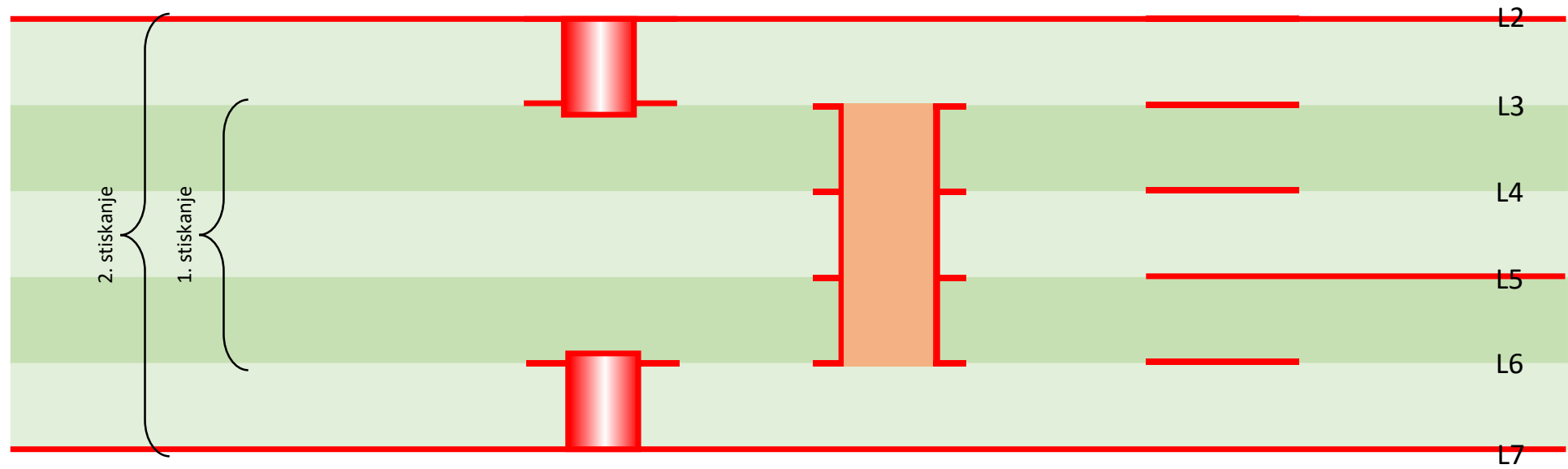
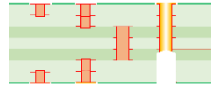


# ML8 HDI SBU

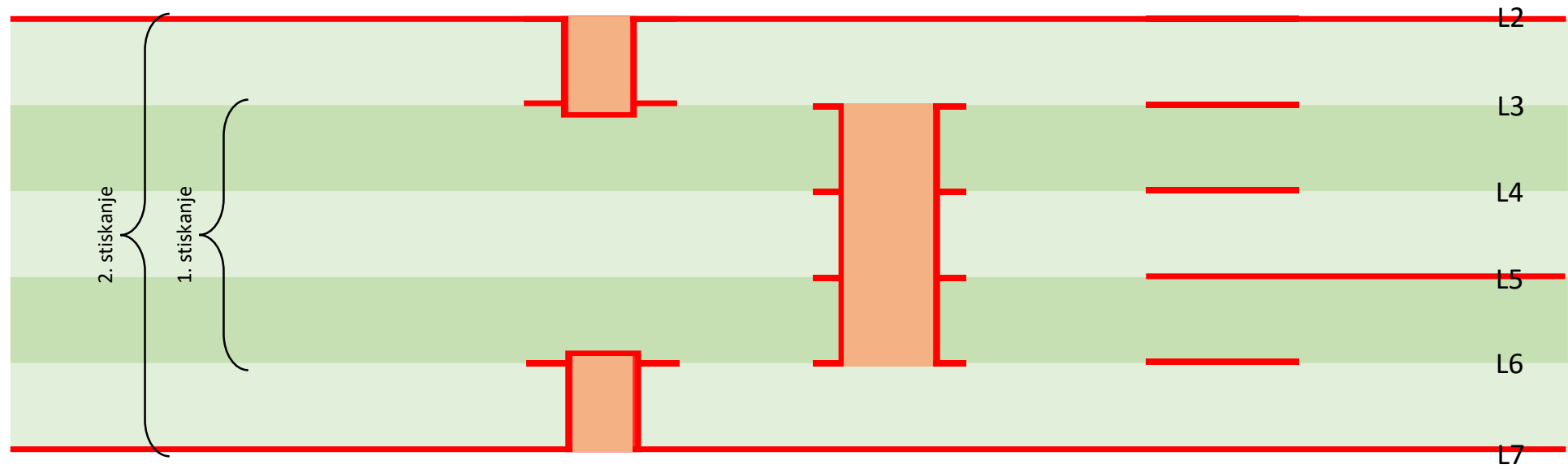
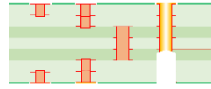




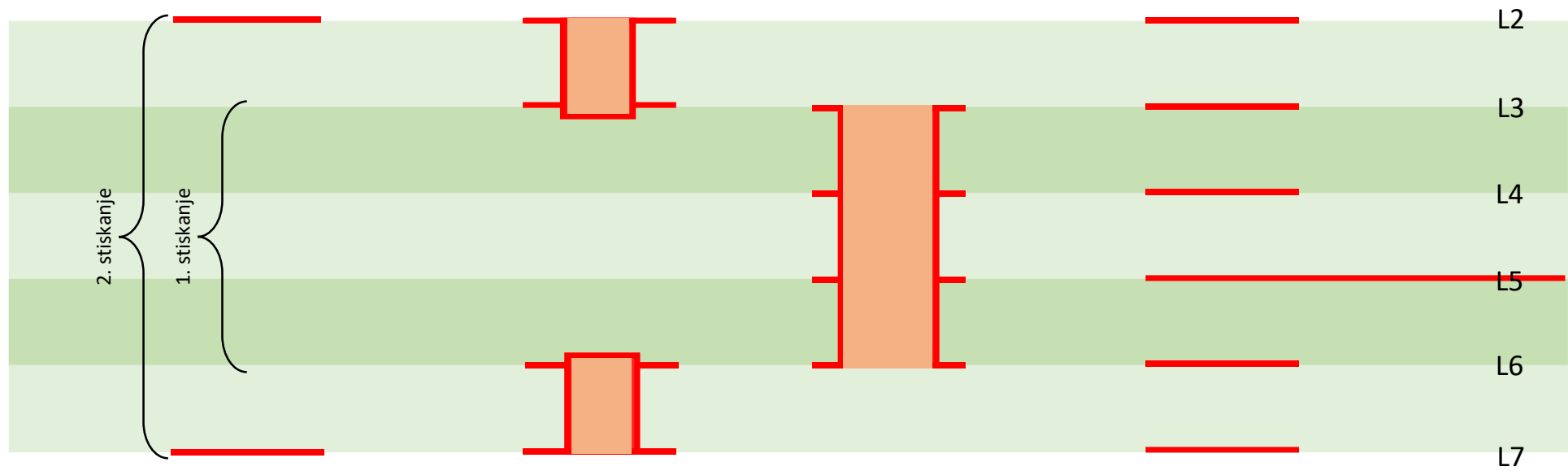
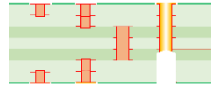
# ML8 HDI SBU



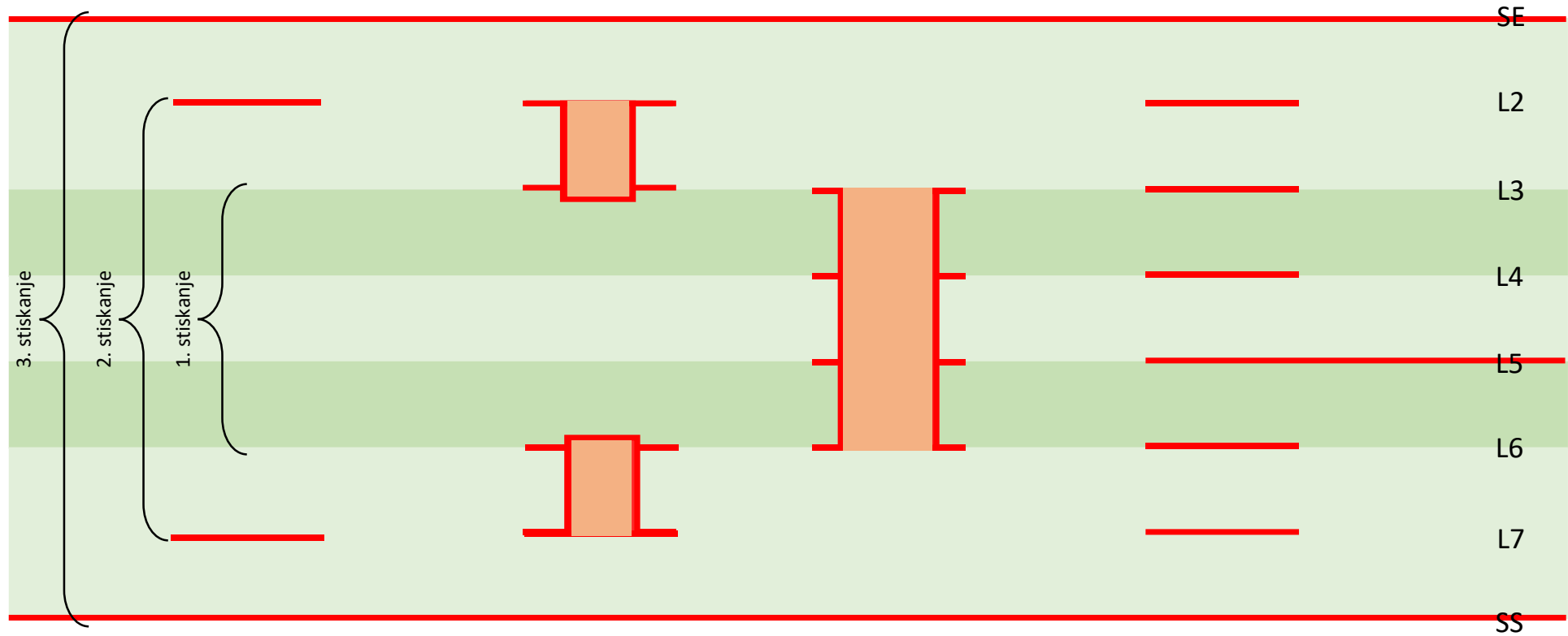
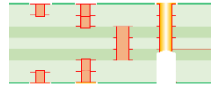
# ML8 HDI SBU



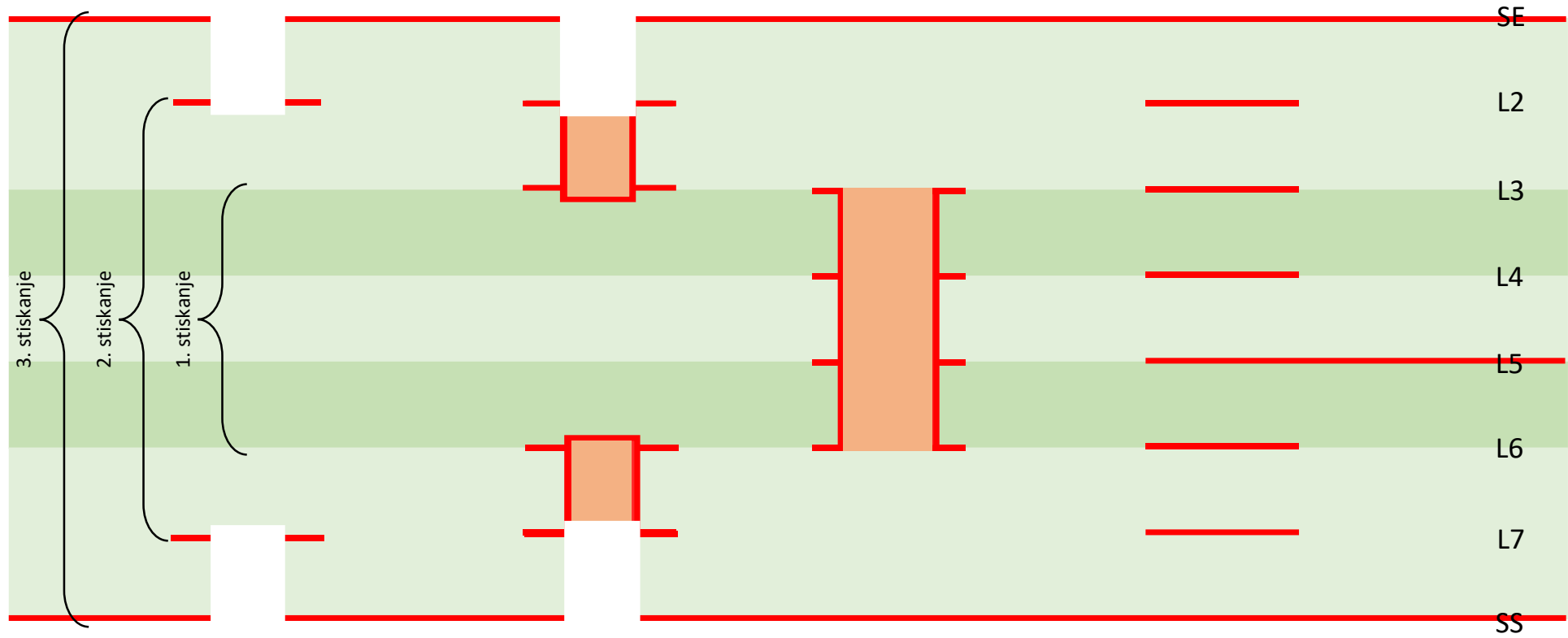
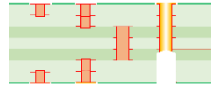
# ML8 HDI SBU



# ML8 HDI SBU

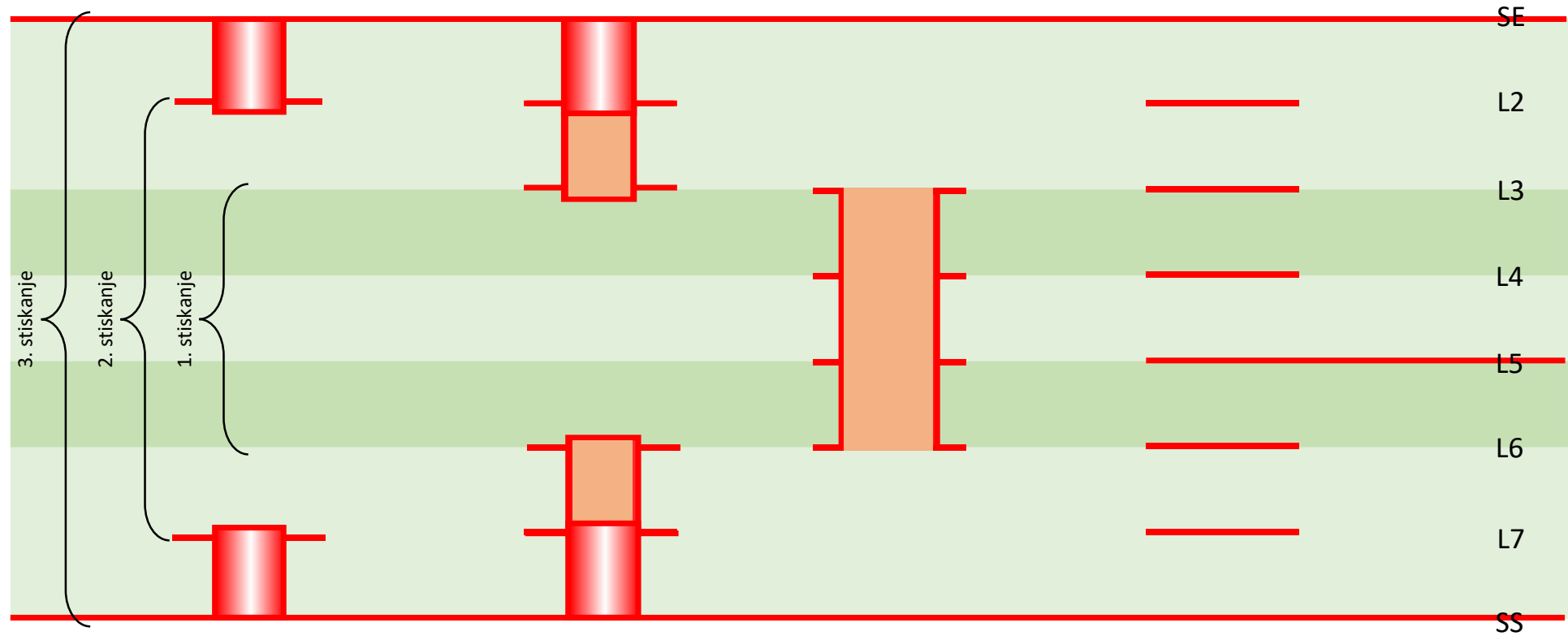
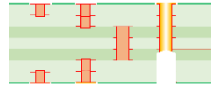


# ML8 HDI SBU

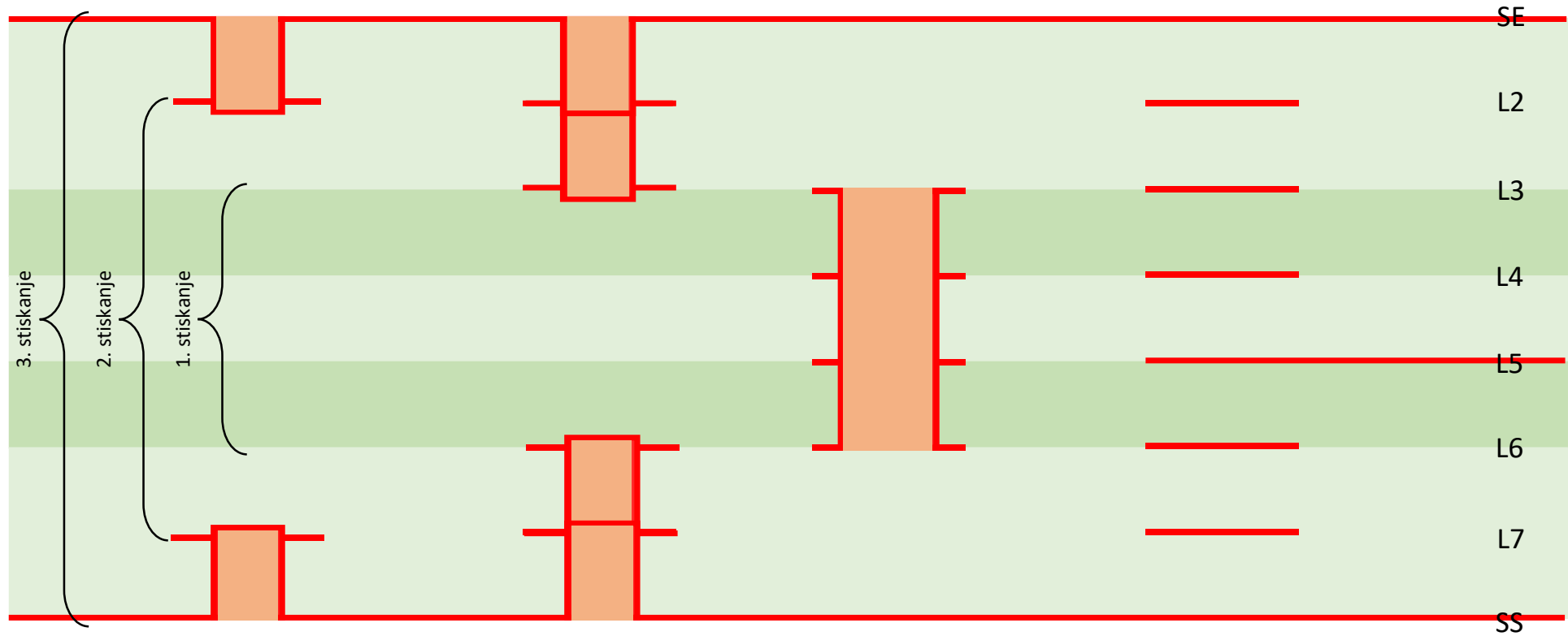
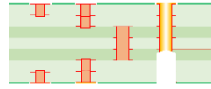




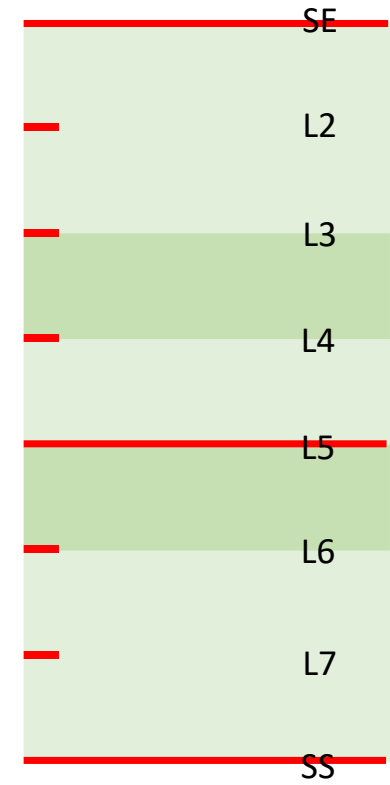
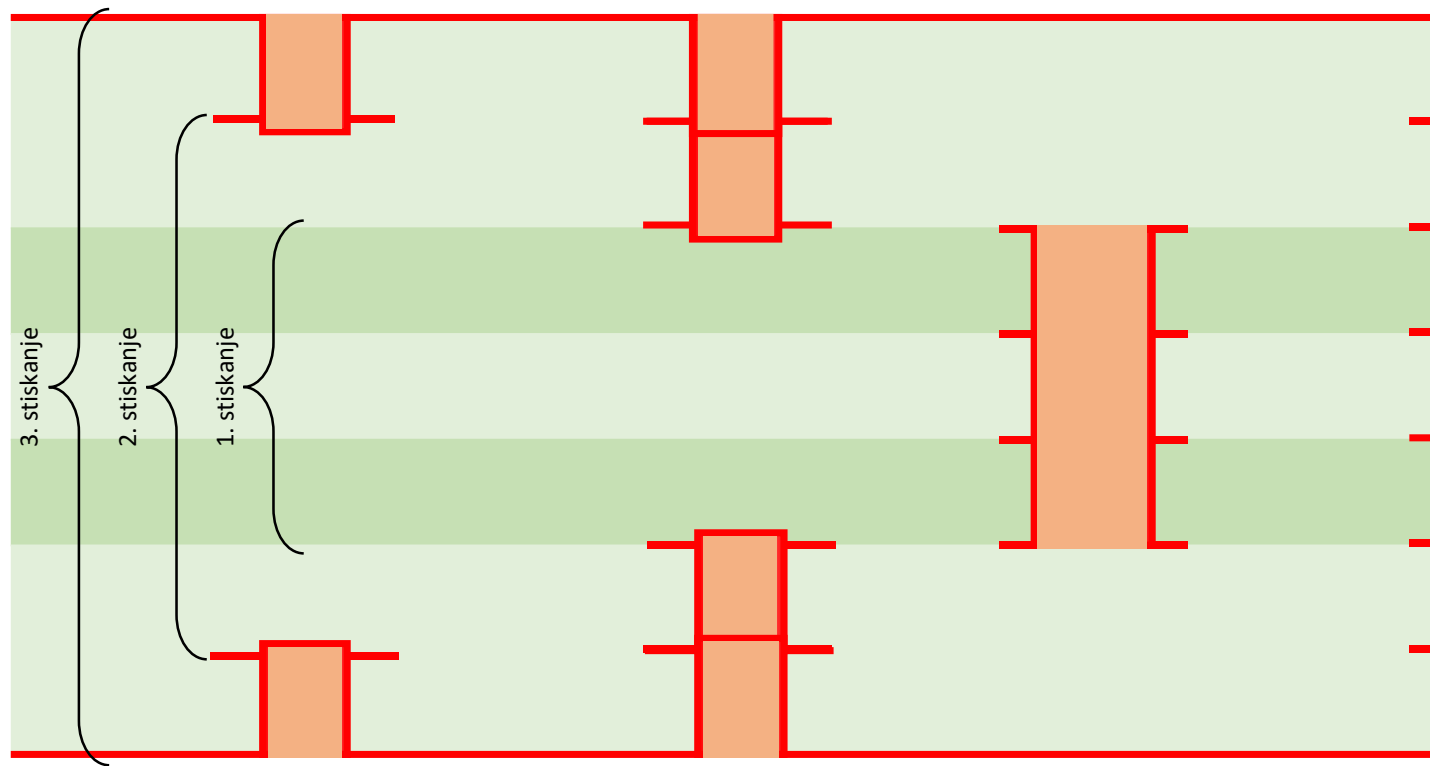
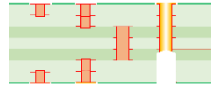
# ML8 HDI SBU



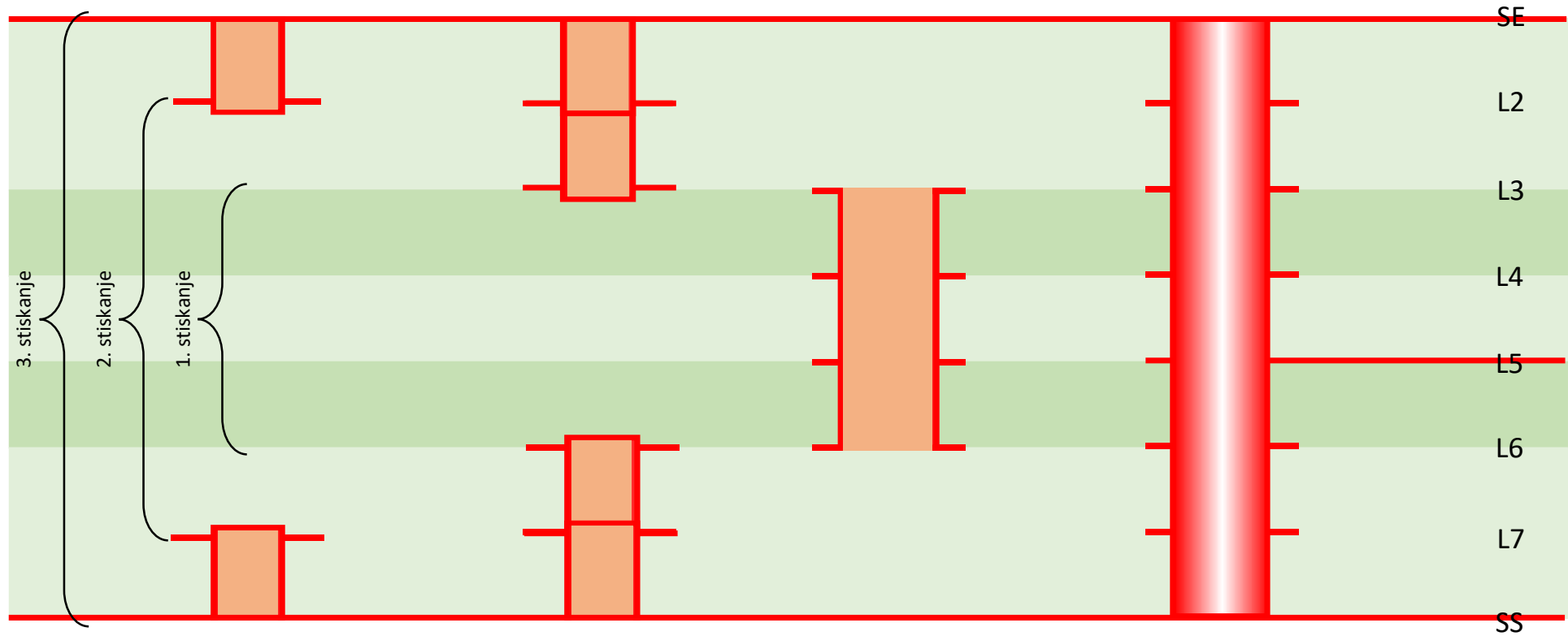
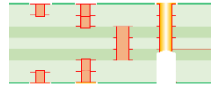
# ML8 HDI SBU



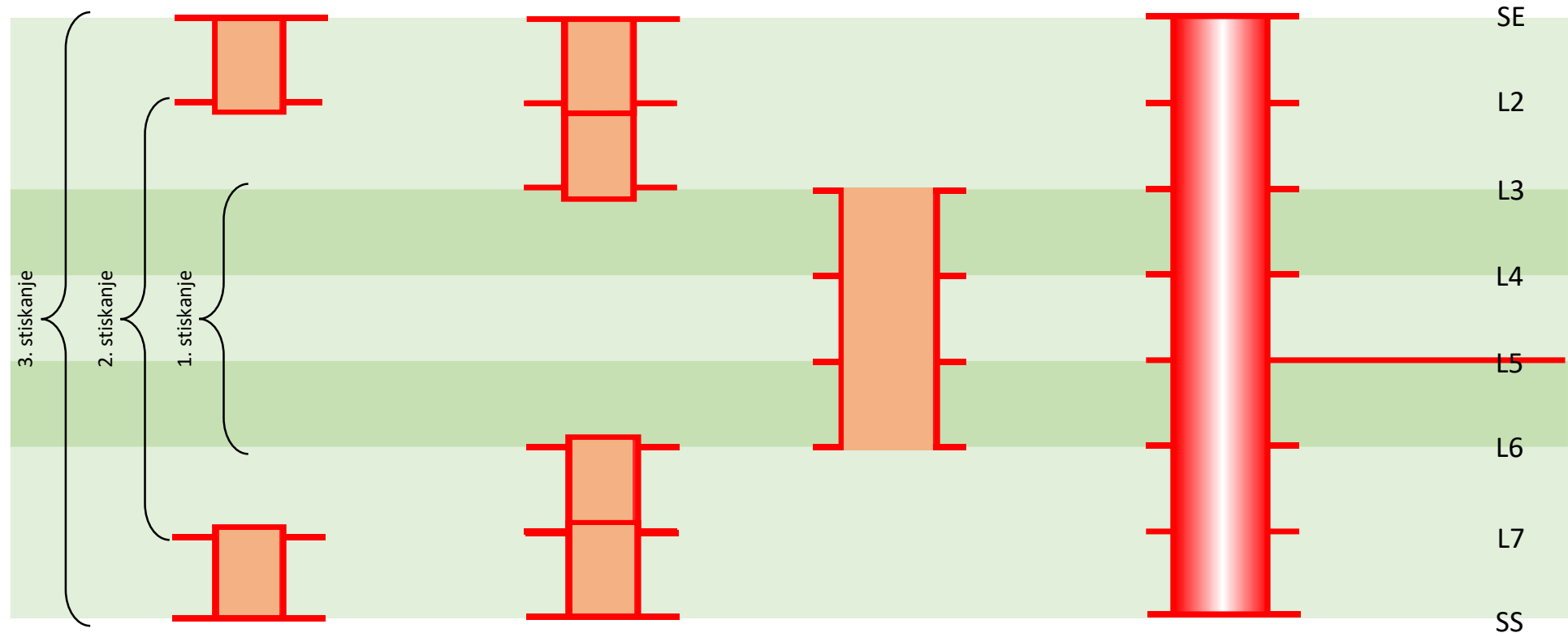
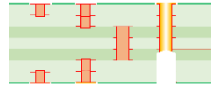
# ML8 HDI SBU



# ML8 HDI SBU

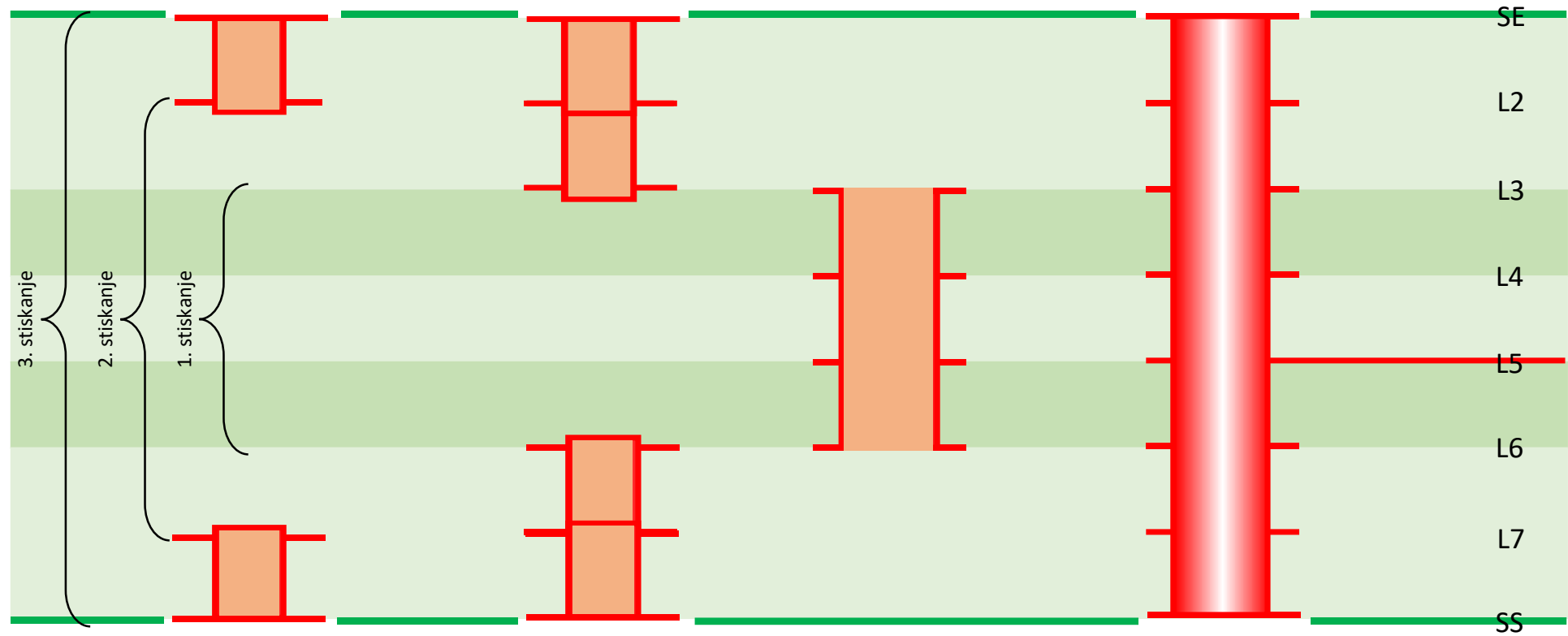
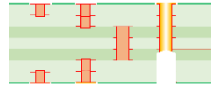


# ML8 HDI SBU

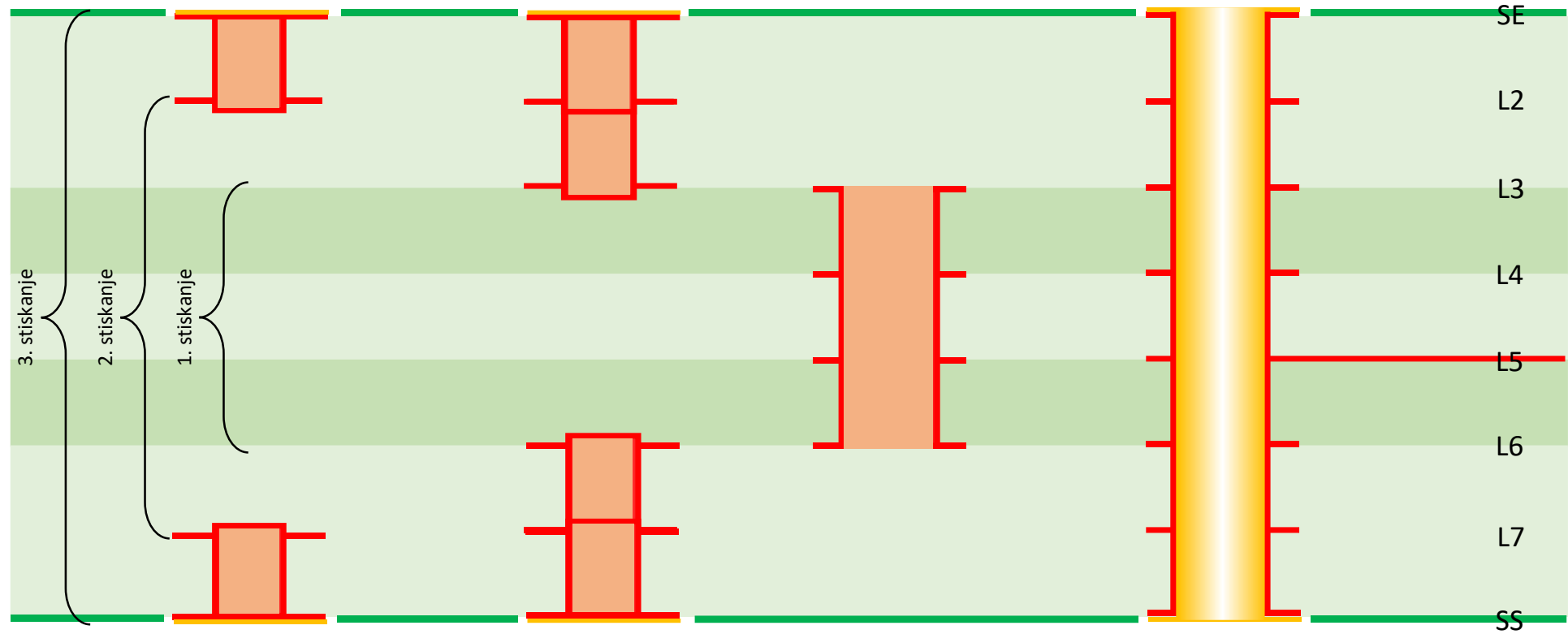
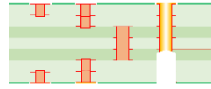




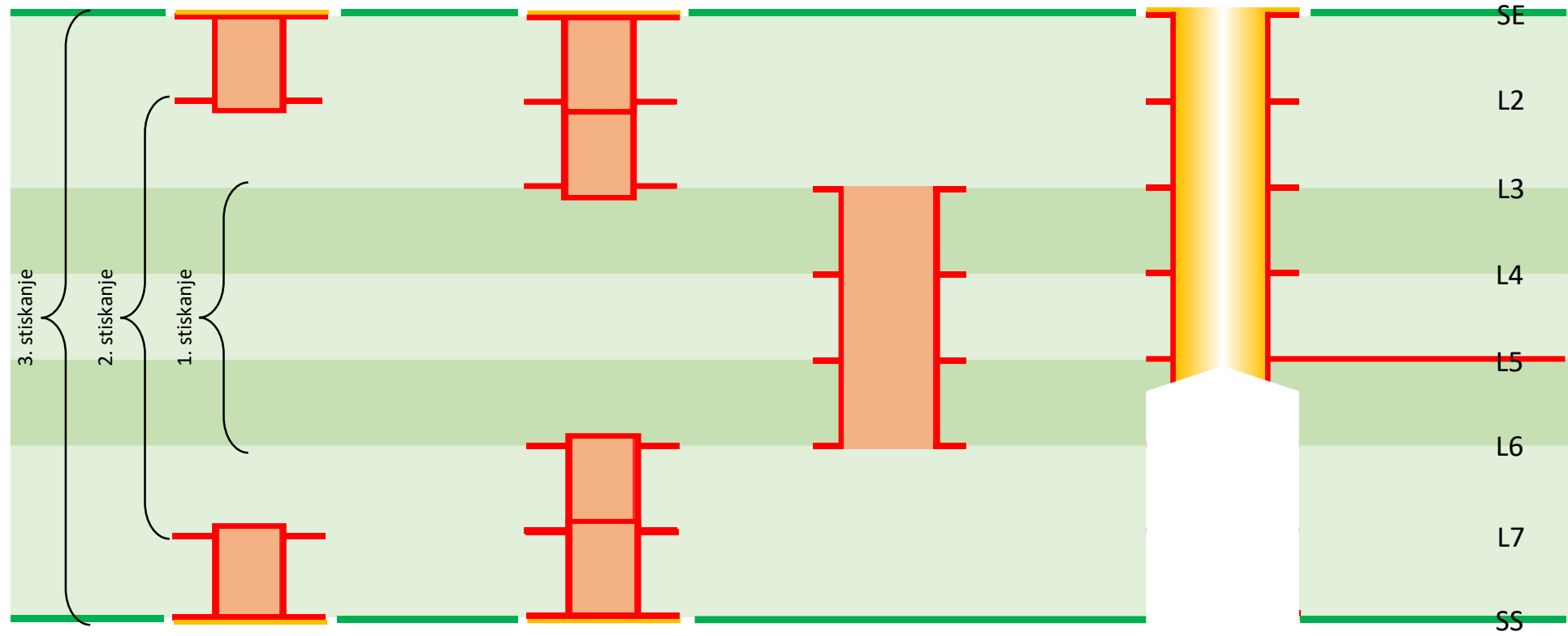
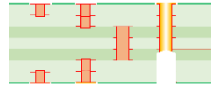
# ML8 HDI SBU

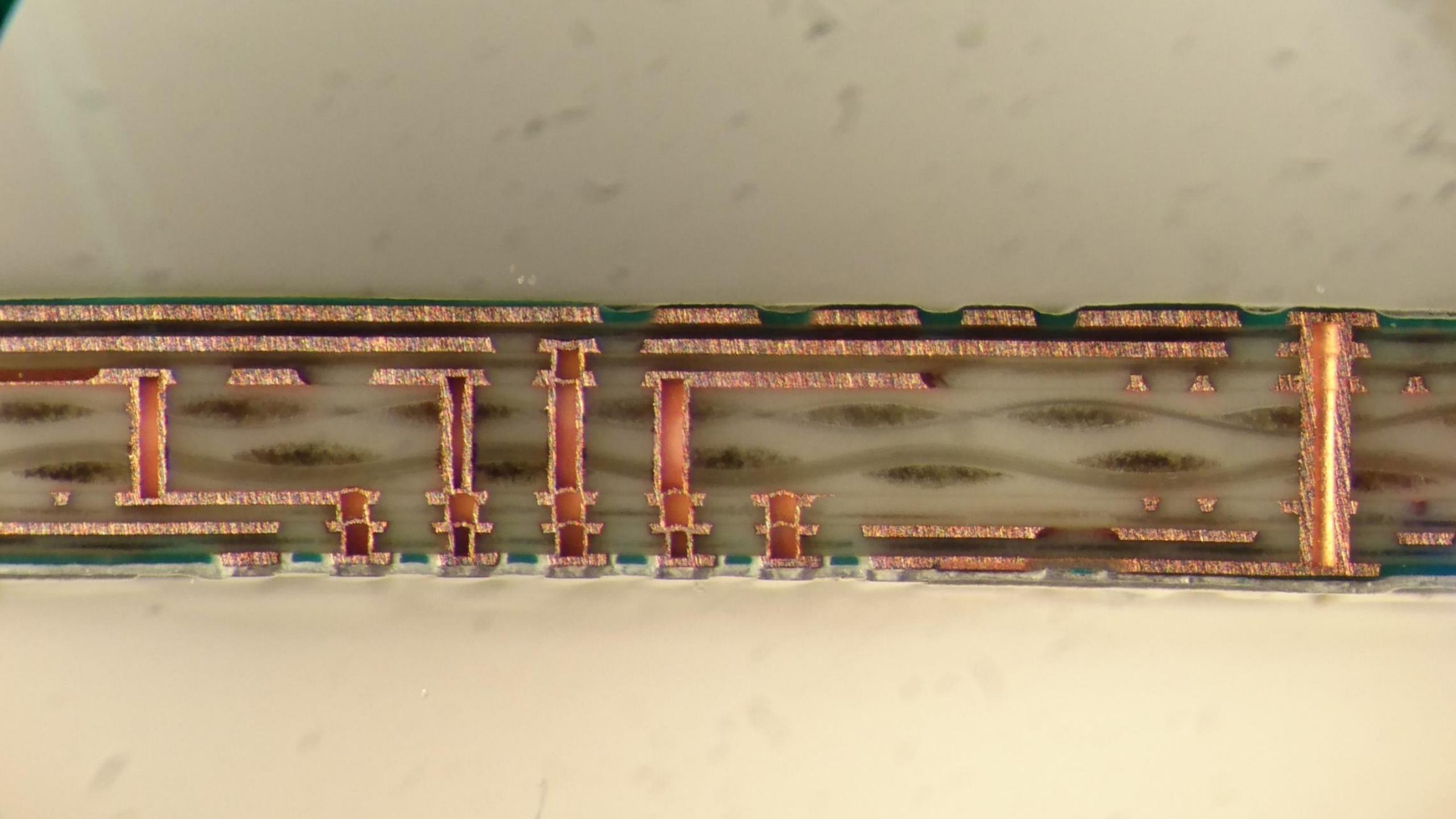



# ML8 HDI SBU



# ML8 HDI SBU





DS 





20 \*\*\*\*\* 12.12.2016 C4

Imat	1054747	KODD	navrhilo	0
Imat	PCB 20000	Partner	101703740	
Laserno	1 df / 1 mf / 1	KOS		
Zastek	12.12.2016	Delavnost		
Opomba		Rab	Tedel	
		Naravnost	KOS	


<b>tehnologija</b>	
op	A
odkajanje	NiAu
verifikacija	12.12.2016
tehnolog	ROZPLET ALU5
konst. predpis	PC-A-6008 CLAS13
veljavna opn	MPJ 17.0000
Opomba DN:	

<b>konvencija na regulirano količina delovnega sloga</b>			
SEST. SLOG	EN	količina	Meljskovec
105484 PCB 110000191	KOS	24,00	12.12.2016 DNE, Travnica Dravnica LLC
105484 PCB 52817	KOS	15,00	12.12.2016 DNE, dr. dravnica

<b>delovni postopki</b>											
DC	St. op.	Naziv	Norma (h / 1 kos)	DF	MF	TV	DF	MF	TV	datum	podpis
13	CAM	CAM	1,00								
41	MAK	IZGATA OSNOVNEGA MATERIALA	0,00								
8	POZ	VRTANJE POZITIVNEGA IZVETAJA	0,03								
9	VRZ	VRTANJE CNC 3P	0,60								
40	RZP	KAZOLENJE DS	0,00								
24	PILO	BALEZENJE PULU 1,1X 10mm/20mm	100,00								
11	FOD	FOTOTISK DS	0,01								
42	ZDIA	KHLO NEK EN ODIT KEE 18 MIC DS R	0,03								
4	AKU	AKU TESTIRANJE R	0,00								
10	MEC	KEMENJE ETHERNE CU POVRHNE MEC	0,48								
10	PKZD	ZAVESNI NADOS POK DS R	0,02								

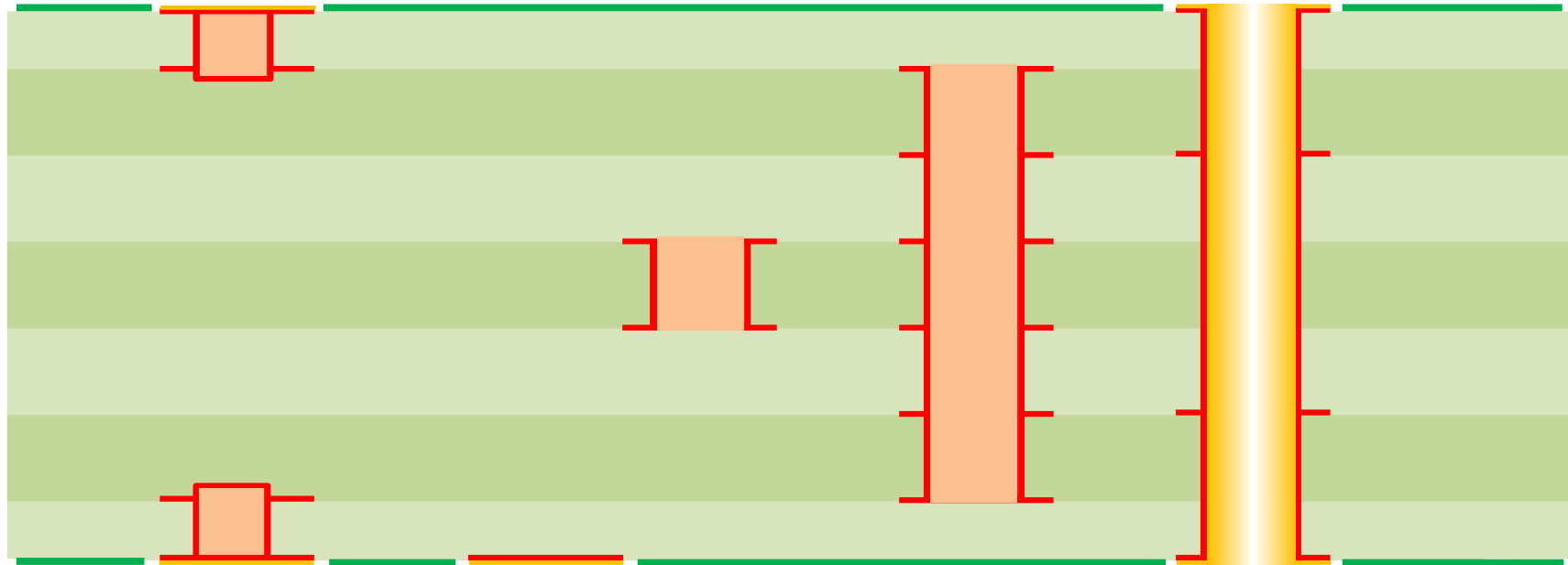
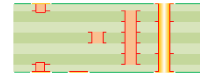
30	DITE	DRITALNI MET ES	0,01								
146	NAG	KEMENJE NAGAU-SL Smer: An 0,05-G. Iamc	0,01								
2	ETV	ELEKTRENO TESTIRANJE Sposob-Fyng	0,11								
1	MEVS	MEKHTVENA MICHROPOVSON-SONA	100,00								
20	ZACN	ZAKREPOVANJE CNC	0,18								
10	VEJ	VEJANJE CNC 3P 20 20mm	0,13								
15	PREK	PREKANJE PLOHE	0,02								
1	KK	KONISA KONTROLA KAHY	0,04								
24	ENG	EMBALIRANJE	0,01								

<b>opremljenj</b>					
vrsta	vrsta	delni	datum	podpis	

DS 



ML8 HDI SBU



Ime TV, d.o.o. Kranj	194765	12.12.2016	DH 1700	C9
Ime: PCB F001W11266	naravnost: 201608228	Forma: 5300	PCB Cesalet OY	
Ime: PCB F001W11266	Proizvajal: 5300	PCB Cesalet OY		
Letnik: 22 let	uf: 88	KOS		
Začetek: 12.12.2016	Delovna sm.: 2.12.2016			
Opomba: sp-74 4017091-1	Podlaga: DNE 1700 F001W11266 PCB CONDUCT O			
	Rak: 12.12.2016	Tiskanje: 10		
	Novice: 49	KOS		

Izjava o tehnologiji				
tip	A	Niau	Imenik	previla
osnovec	REZ		DF	0,1304
verifikacija	12.12.2016			
tehnolog	EMER MARKO		Co odčitava	13,21
konstrukcija	PC-A-AMONTEKALNO DEKLANE		Co odčitava	6,00
izjava o op.:	MP1 IMPEDANČNI PROTOKOL, COC izdelaj po tabeli: P0130100021.1, je vsebilo 1		Emu An efekt	0,13
				0,13
Opomba DNI:			postavitev:	2
			merila:	2

Izjava za razpisno obliko delovnega naloga				
Ime: Niau	EM	izjava	izjava	
12011 COPPERFOIL 18*CM 800L	KOS	46,57		
8118 PREPROG 140*81511W-R-C9P-R-480	KOS	46,00		
9769 PREPROG 2116*81511W-R-C9P-R-480	KOS	22,00		

DC	Šif. op.	Naime	Norma (B / I) in	Deleci	Stane
DF	MP	TVY	DF	MP	TVY
115	CAM	CAM		80,00	
41	DIAT	DIATA OSGOVNOGA MATERIALA	0,00		
140	KSI	KONDUKCIJSKORVANJE	4,49		
8	POZ	VRTANJE POZICIONIRANJE EVENTIS	2,23		
9	VRI	VRTANJE CNC TERMOLO LEVIŠNI 3P	5,28		
11	FOV	FOTOTERMSKI DV-AM 140	1,23		
42	DIH	DIHOLO REZKI DV ODSTREZ 18 MIC DS	2,44		
4	AOV	AOV TESTIRANJE - VP	0,26		

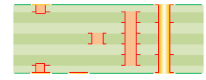
41	OXS	OKSIDACIJA CU POVRŠINE	440,00		
15	STI	STRUKANJE PLOŠE 404*0,01mm	40,04		
27	OBZ	OBREZ NA GROBO	0,41		
9	KRCC	X-RAY-POZICIONIRANJE-manje-PAZI	8,80		
20	ZIV	ZIGOGANJE	12,17		
10	REG	REZKANJE CNC NA GROBO 4P	4,93		
40	RZD	RAZGLEJENJE DS	0,22		
43	JATA	AMONTEKALNO DEKLANE	1.460,80		
9	VRI	VRTANJE CNC	121,53		
9	VRI	VRTANJE CNC	14,87		
40	RZD	RAZGLEJENJE DS	0,22		
151	KEL	KEMENJO EBERENJE LUKENI	0,02		
34	P110	BAKRENJE PPCI 0,5A/0,4m2-110mm-10mic	8.800,00		
11	FOV	FOTOTERMSKI DV-POZORI AM150	1,23		
31	DIKX	DIKXENJE EV SI PPCI	8.800,00		
32	ODSD	ODSTRANJEVANJE SA	5,27		
43	JATD	AMONTEKALNO DEKLANE 18 MIC DS	14,41		
33	ODSN	ODSTRANJEVANJE SA	5,27		
4	AOV	AOV TESTIRANJE - VP	0,26		
17	SKO	TRKANJE SI, V SKOZINDE	2,35		
2	ETS	ELEKTRENO TESTIRANJE-Spedy-Flytag	9,78		
41	OXS	OKSIDACIJA CU POVRŠINE	440,00		

151	KEL	KEMENJO EBERENJE LUKENI	0,02		
34	P110	BAKRENJE PPCI 0,5A/0,4m2-110mm-10mic	8.800,00		
11	FOV	FOTOTERMSKI DV-POZORI AM150	1,23		
31	DIKX	DIKXENJE EV SI PPCI	8.800,00		
43	JATD	AMONTEKALNO DEKLANE 18 MIC DS	14,41		
33	ODSN	ODSTRANJEVANJE SA	5,27		
4	AOV	AOV TESTIRANJE - VP	0,26		
17	SKO	TRKANJE SI, V SKOZINDE	2,35		
40	RZD	RAZGLEJENJE DS	0,22		
151	KEL	KEMENJO EBERENJE LUKENI	0,02		
34	P110	BAKRENJE PPCI 0,5A/0,4m2-110mm-10mic	8.800,00		
10	REG	REZKANJE CNC NA GROBO	4,93		
4	OE	VMEŠNO OBNI PREGLED	1,23		
11	FOV	FOTOTERMSKI DV-AM150	1,23		
40	BRP	BRUŠENJE PLANETNO DS	22,00		
11	FOV	FOTOTERMSKI DV-AM150	1,23		

31	DIKX	DIKXENJE EV SI PPCI	8.800,00		
32	ODSD	ODSTRANJEVANJE REZISTA DS	0,56		
43	JATD	AMONTEKALNO DEKLANE 18 MIC DS	14,41		
33	ODSN	ODSTRANJEVANJE SA	5,27		
4	AOV	AOV TESTIRANJE - VP	0,26		
2	ETS	ELEKTRENO TESTIRANJE-Spedy-Flytag	9,78		
41	OXS	OKSIDACIJA CU POVRŠINE	440,00		
15	STI	STRUKANJE PLOŠE 404*0,01mm	40,04		
27	OBZ	OBREZ NA GROBO	0,41		
9	KRCC	X-RAY-POZICIONIRANJE-manje-PAZI	8,80		
20	ZIV	ZIGOGANJE	12,17		
10	REG	REZKANJE CNC NA GROBO 4P	4,93		
40	RZD	RAZGLEJENJE DS	0,22		
43	JATA	AMONTEKALNO DEKLANE	1.460,80		
9	VRI	VRTANJE CNC	121,53		
9	VRI	VRTANJE CNC	121,53		
46	RI10	KEMENJO EBERENJE CU POVRŠINE	41,12		
40	RZD	RAZGLEJENJE DS	0,22		
151	KEL	KEMENJO EBERENJE LUKENI	0,02		

31	DIKX	DIKXENJE EV SI PPCI	8.800,00		
10	REG	REZKANJE CNC NA GROBO	4,93		
11	FOV	FOTOTERMSKI DV-AM150	1,23		
40	BRP	BRUŠENJE PLANETNO DS	22,00		
1	OE	VMEŠNO OBNI PREGLED	1,23		
9	VRI	VRTANJE CNC	121,53		
9	VRI	VRTANJE CNC	121,53		
40	RZD	RAZGLEJENJE DS	0,22		
151	KEL	KEMENJO EBERENJE LUKENI	0,02		
34	P110	BAKRENJE PPCI 0,5A/0,4m2-110mm-10mic	8.800,00		
11	FOV	FOTOTERMSKI DV-AM150	1,23		
31	DIKX	DIKXENJE EV SI PPCI	8.800,00		
32	ODSD	ODSTRANJEVANJE REZISTA DS	0,56		
43	JATD	AMONTEKALNO DEKLANE 18 MIC DS	14,41		
33	ODSN	ODSTRANJEVANJE SA	5,27		
4	AOV	AOV TESTIRANJE - VP	0,26		
10	REG	REZKANJE CNC NA GROBO	4,93		
11	FOV	FOTOTERMSKI DV-AM150	1,23		
146	NKA	KEMENJO SI-AU-3L SAUC AA 0,05-0,1mic	0,88		
151	DIK	DIKXENJE SI-AU-3L SAUC AA 0,05-0,1mic	0,88		

2	ETS	ELEKTRENO TESTIRANJE-Spedy-Flytag	9,78		
1	OE	VMEŠNO OBNI PREGLED	1,23		
1	MCCV	MERITVA NA MEROVNIKOV-konena	88,00		
10	REG	REZKANJE CNC NA GROBO	24,48		
1	OE	VMEŠNO OBNI PREGLED	1,23		
1	KE	KONENA KONTROLA-SAUC-POZORI	8,80		
24	EMB	EMBALIRANJE-POZORI-POZORI	0,49		

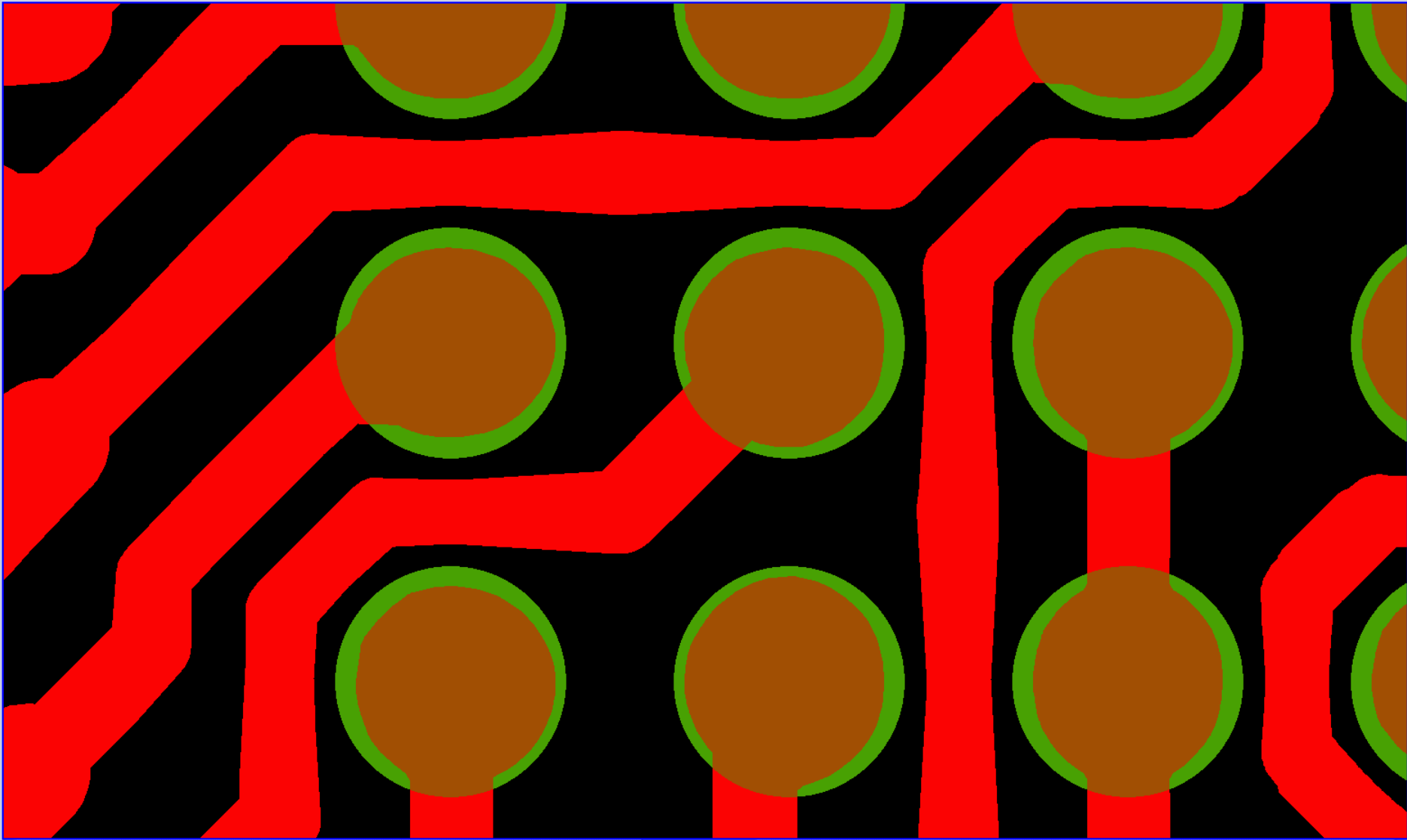


Technical drawing showing a cross-section of a PCB with a central hole and various layers and components.

# PCB Design priporočila

File Edit View Step Layer Tools Netlist Actions Settings Scripts Window Help

Step [pcbx1]



Layer

- sle
- se
- I2
- I3
- ss
- sls
- ...rss\_I3
- drill\_fin
- ldi
- ldi-vmesne

NC Layers

- drf
- drf\_2-3
- v.drf\_1-2
- v.drf\_4-3
- v.drf
- rout
- rez
- 110921dv1.rez
- 110921dv2.rez
- 110921D
- 110921DV
- 110921DV\_1-2
- 110921DVB\_4-3
- drf\_pdn

Document Layers

- 110921\_dxf\_top
- 110921\_dxf\_top\_cu
- 110921\_dxf\_bot
- 110921\_dxf\_bot\_cu

Non-Board Layers

- se\_no\_detch
- I2\_no\_detch
- I3\_no\_detch
- ss\_no\_detch

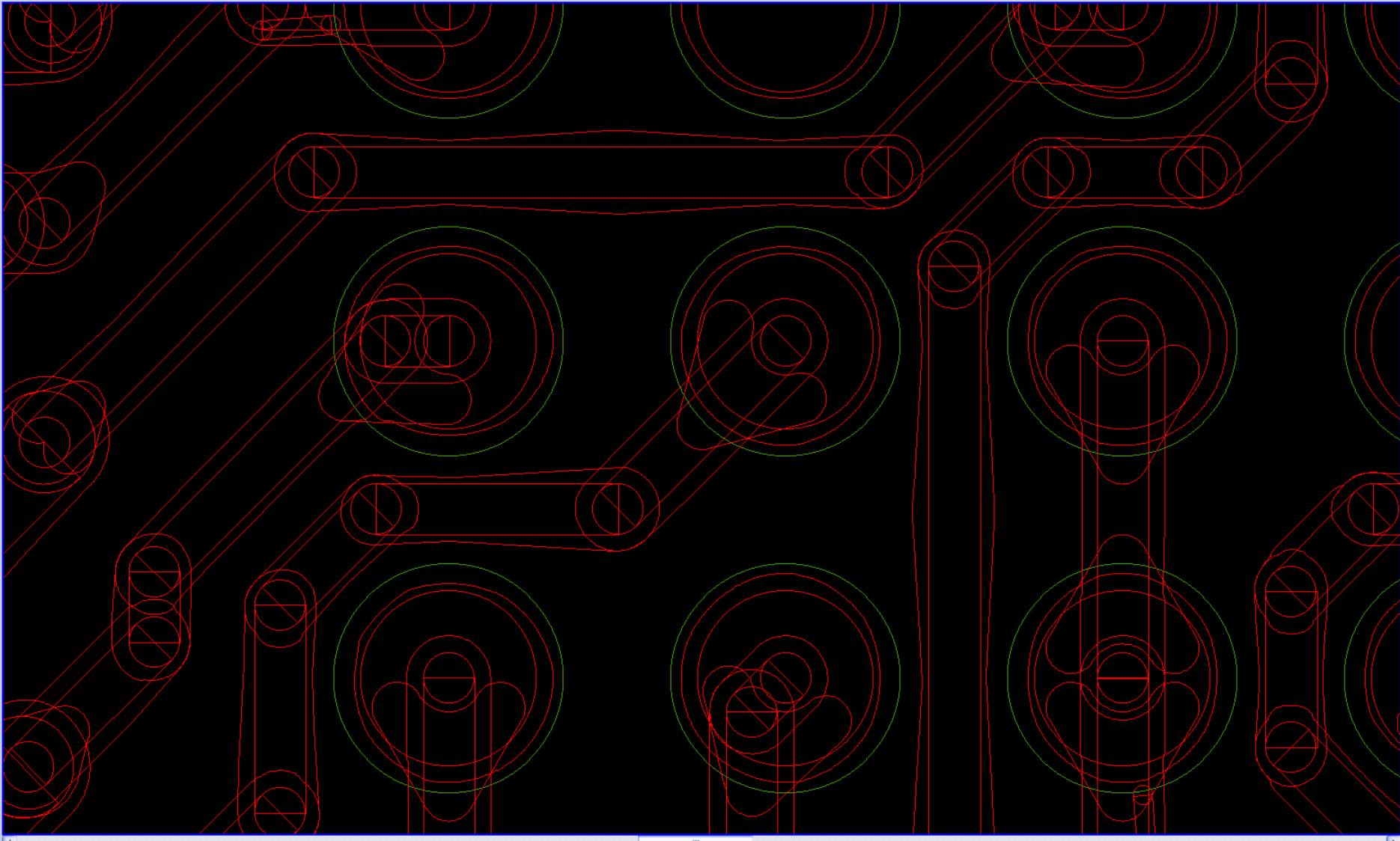
Temporary Layers

Selected: 0 | v.drf\_4-3, #13, r150, Pad, X=6.15, Y=13.825, POS, Attr(bit=0.125, .drill=via, .via\_type=laser, .combined\_size=0)

6.213160 13.811797 mm

Scripts:





Layer

- slc
- se
- I2
- I3
- ss
- sls
- ...rss\_I3
- drill\_fin
- ldi
- ldi-vmesne

NC Layers

- drf
- drf\_2-3
- v.drf\_1-2
- v.drf\_4-3
- v.drf
- rout
- rez
- 110921dv1.rez
- 110921dv2.rez
- 110921D
- 110921DV
- 110921DV\_1-2
- 110921DVB\_4-3
- drf\_pdn

Document Layers

- 110921\_dxf\_top
- 110921\_dxf\_top\_cu
- 110921\_dxf\_bot
- 110921\_dxf\_bot\_cu

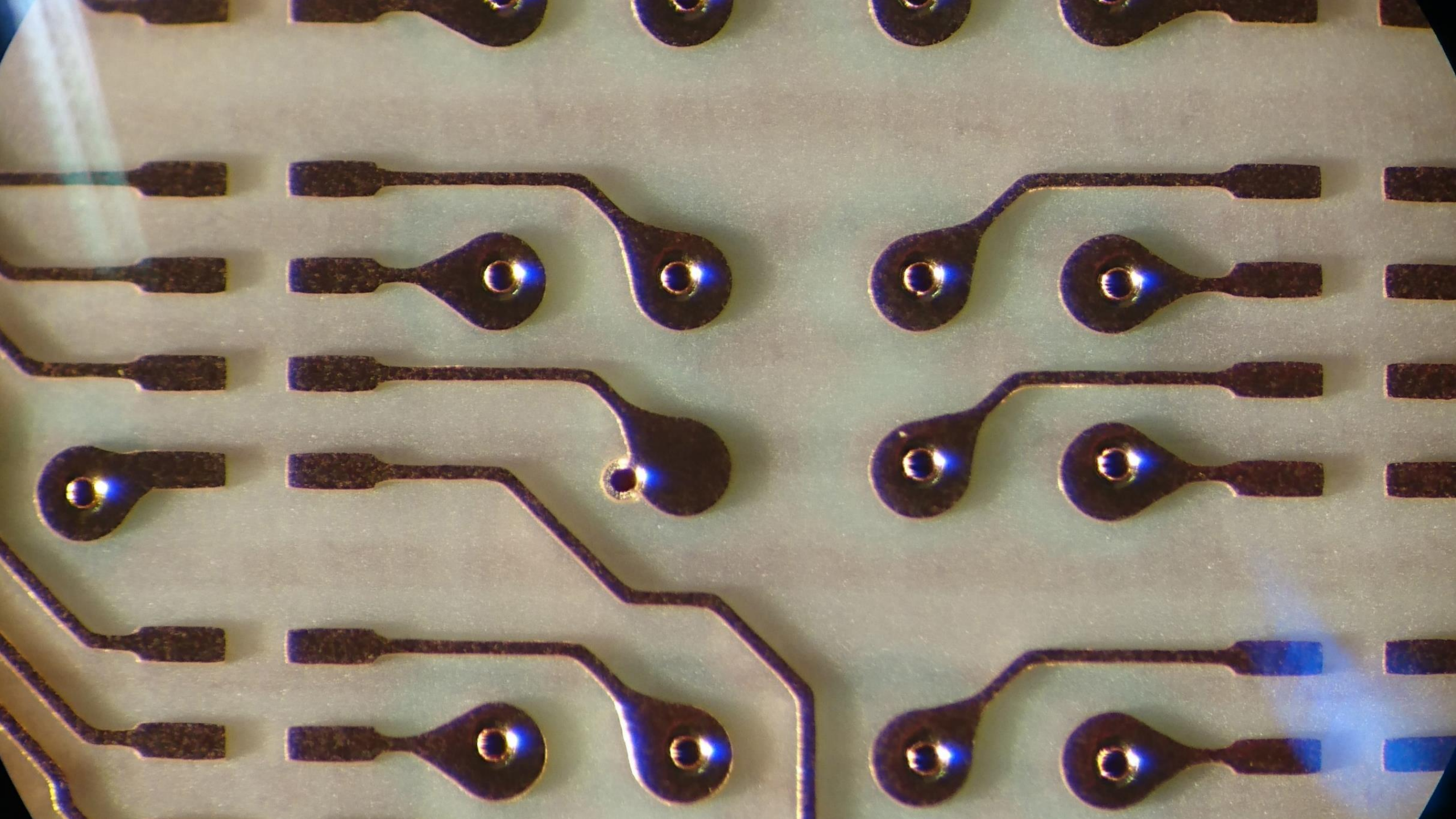
Non-Board Layers

- se\_no\_detach
- I2\_no\_detach
- I3\_no\_detach
- ss\_no\_detach

Temporary Layers

Selected: 0 | v.drf\_4-3, #13, r150, Pad, X=6.15, Y=13.825, POS, Attr(bit=0.125, drill=via, via\_type=laser, combined\_size=0)

6.213160 13.811797 | mm | Scripts: | Reference(44) | X=8.798100 Y=14.674752 mm | <M1> - Single feature selection ; <M1><...





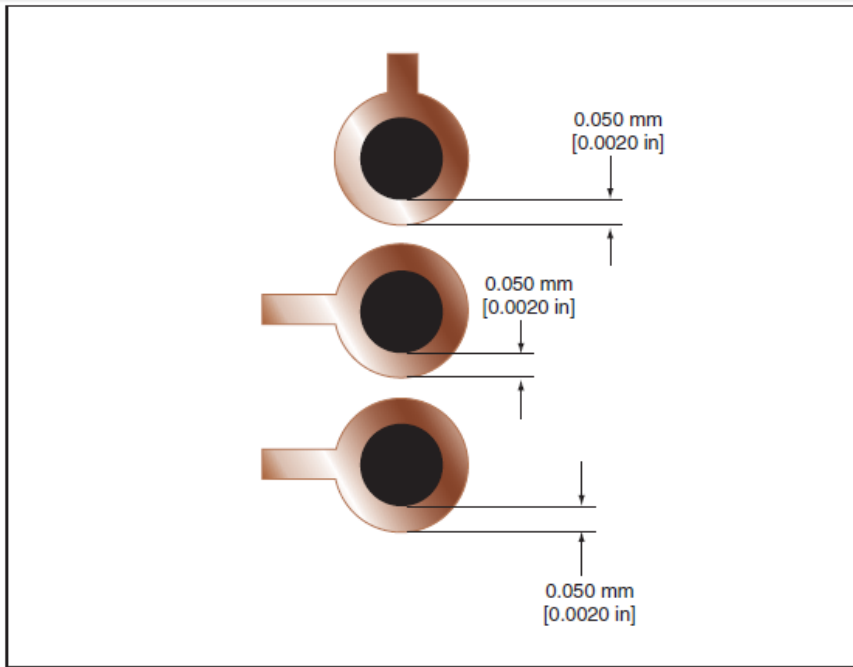


Figure 2103b

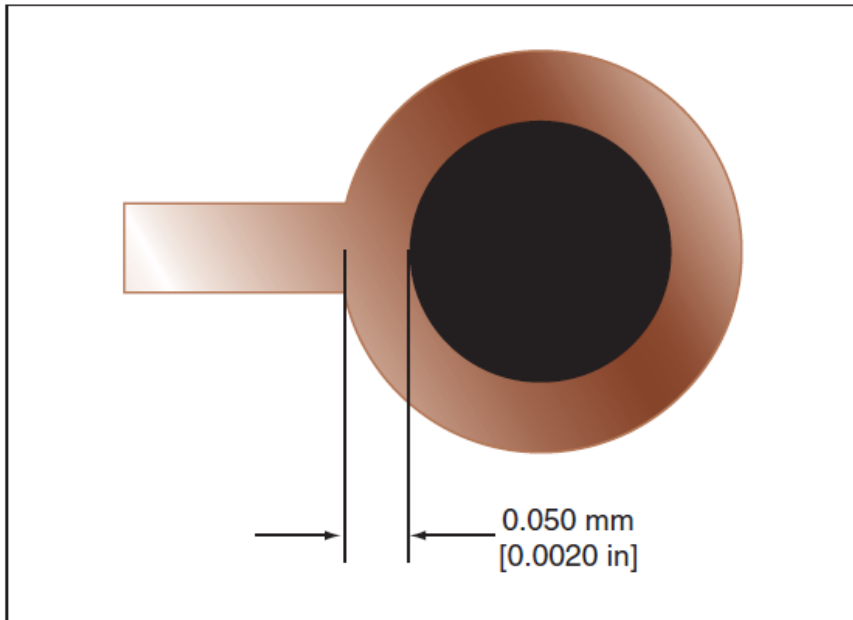


Figure 2103c

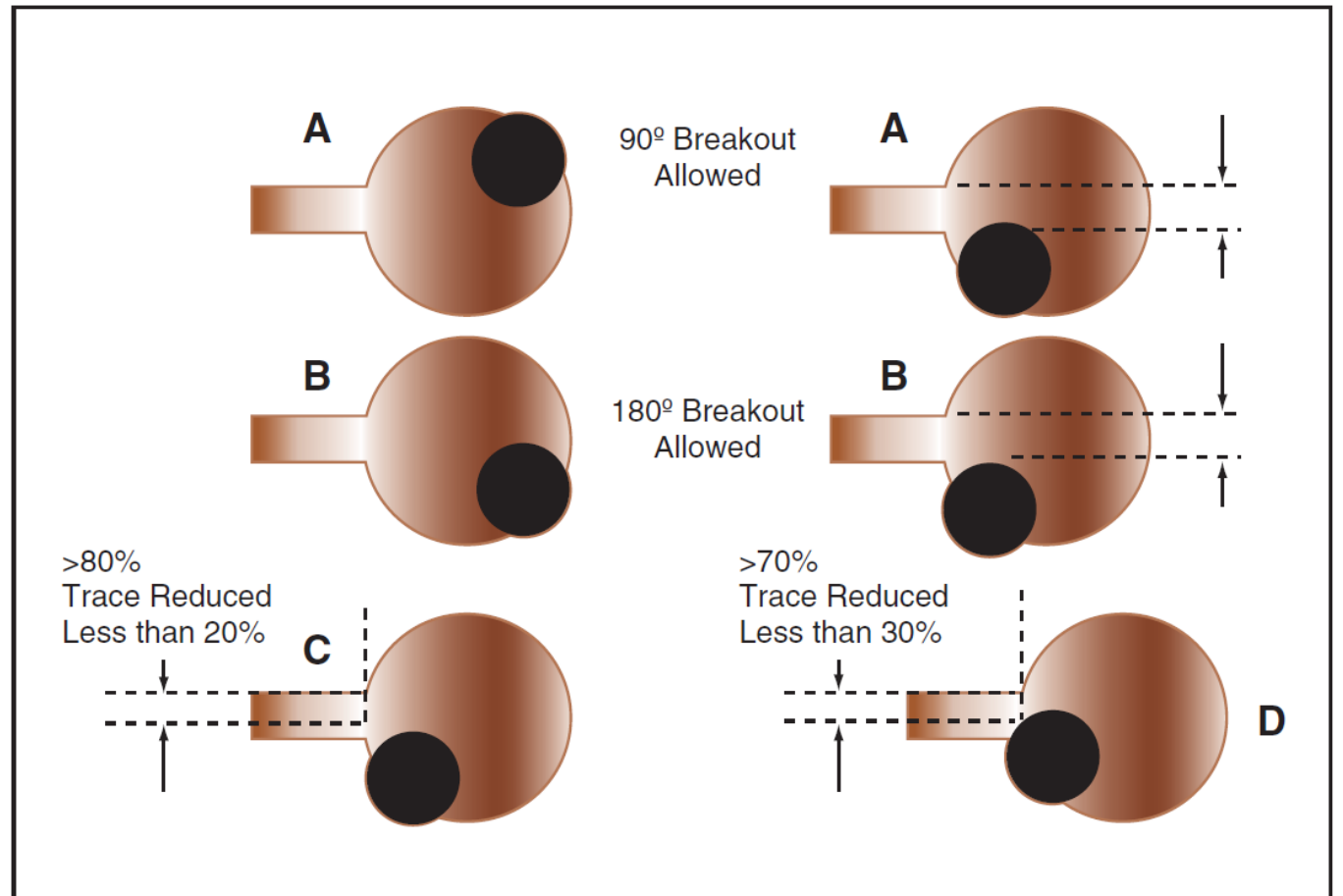
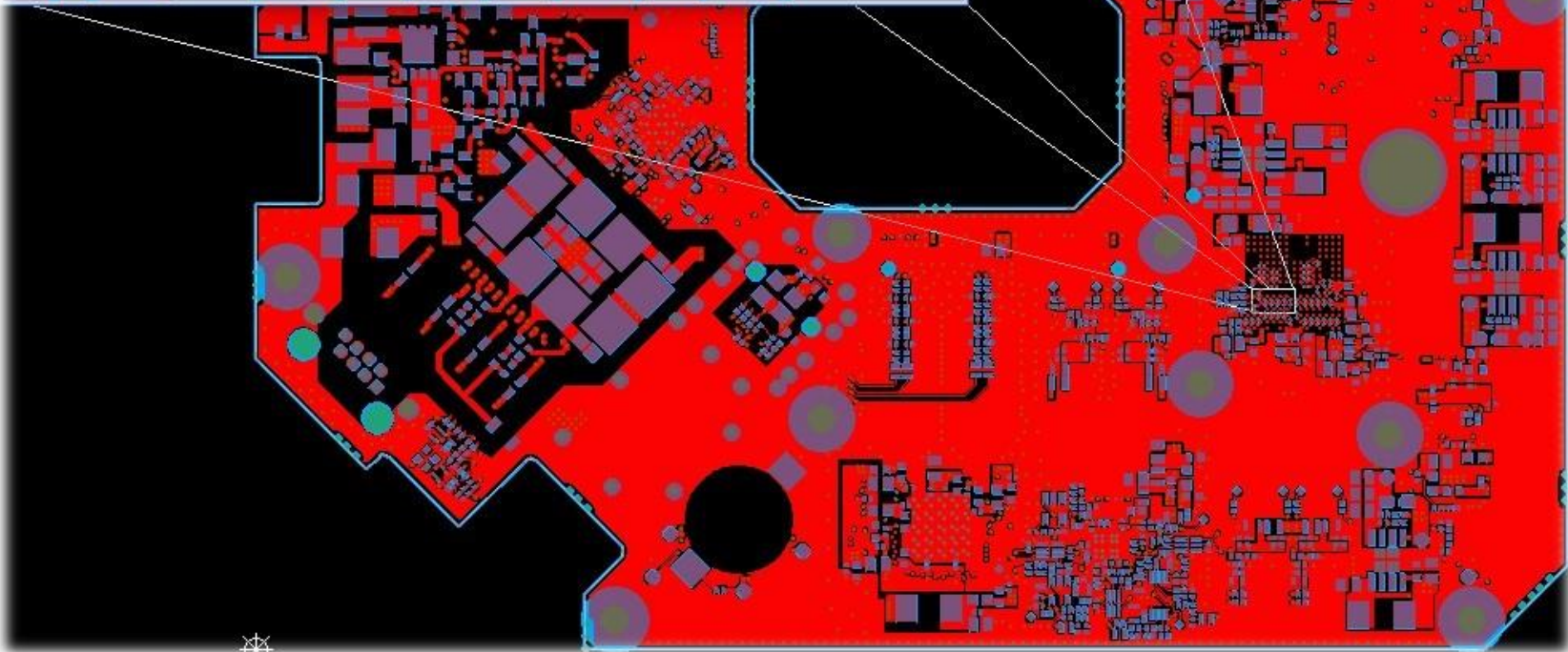
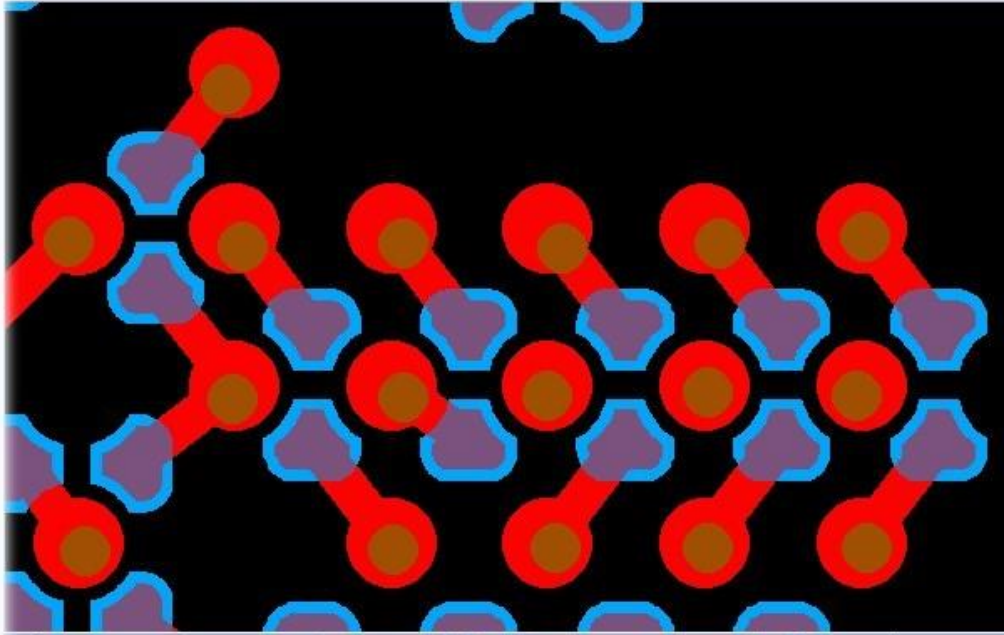
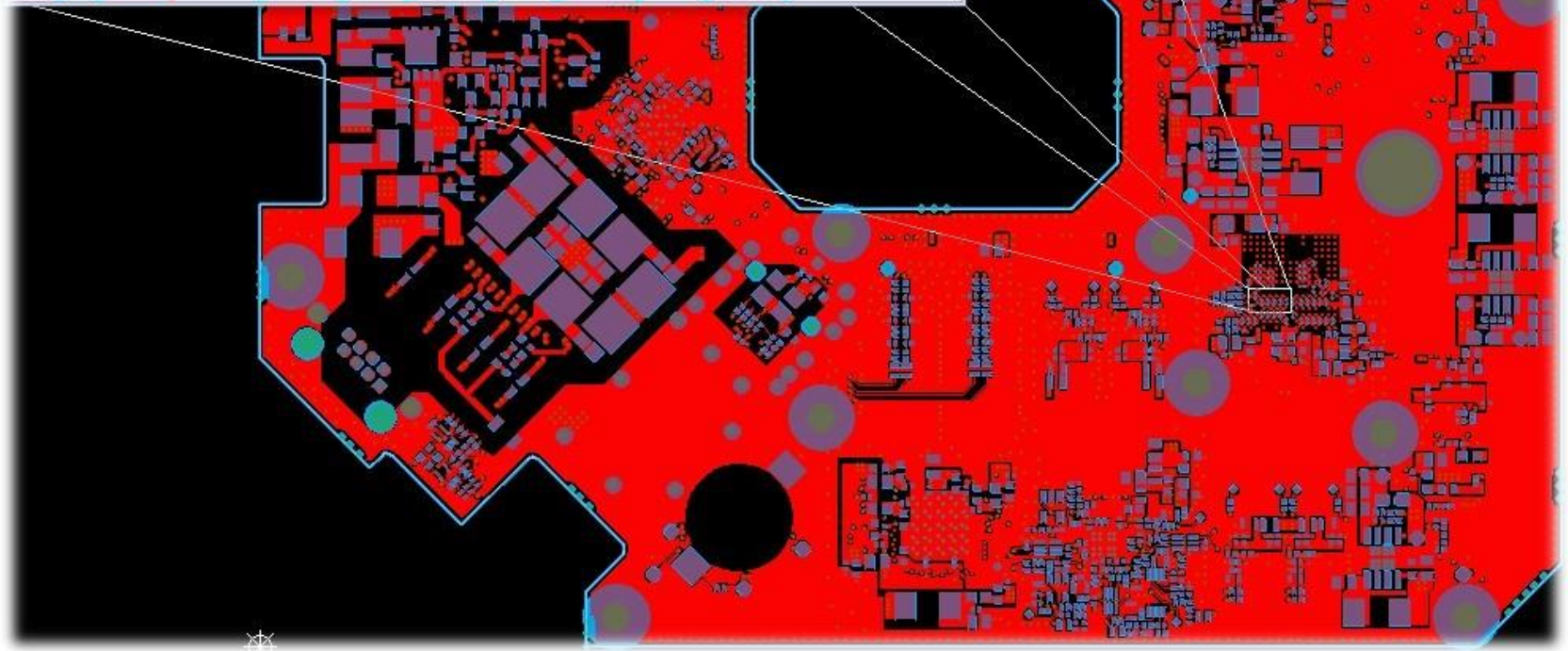
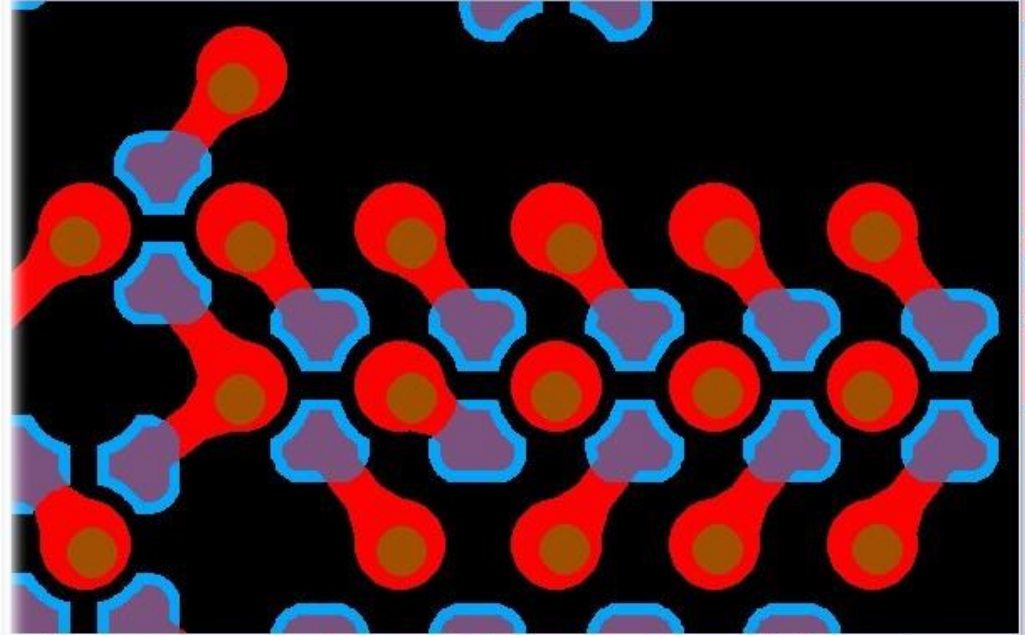


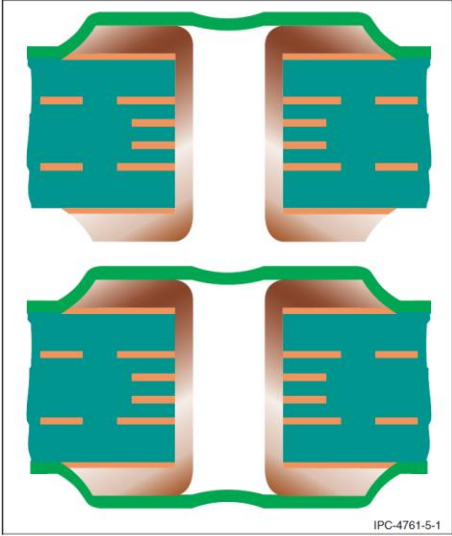
Figure 2103d





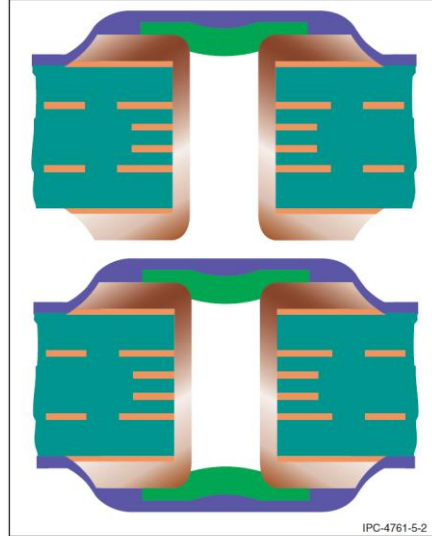


# Tipi zaščite skoznikov po standardu IPC-4761



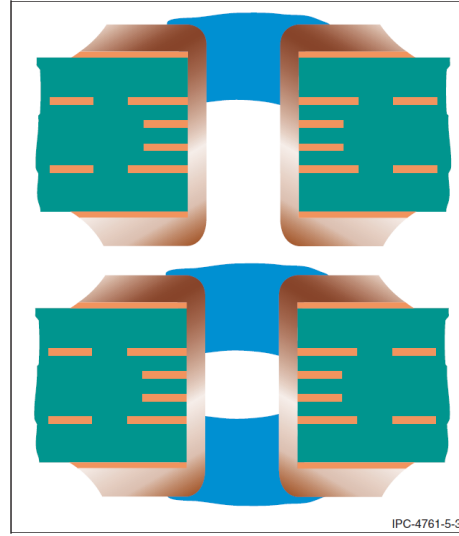
IPC-4761-5-1

Single Sided Tented Not Recommended  
Figure 5-1 Examples of Type I Tented Vias



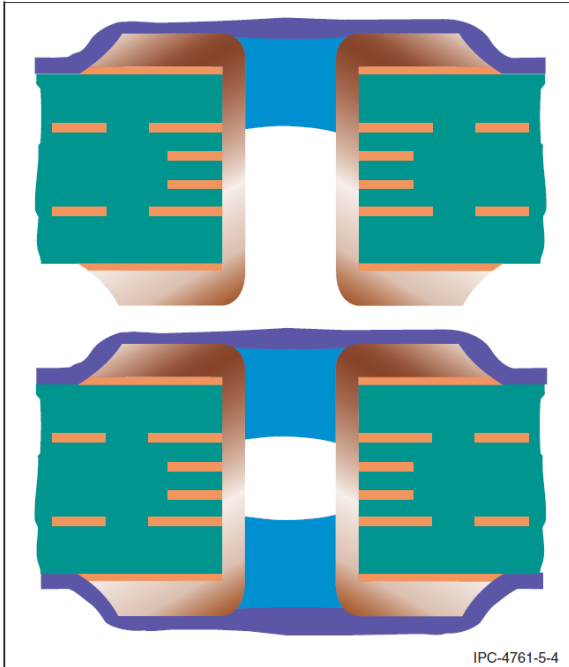
IPC-4761-5-2

Single Sided Tented and Covered Not Recommended  
Figure 5-2 Examples of Type II Tented and Covered Vias



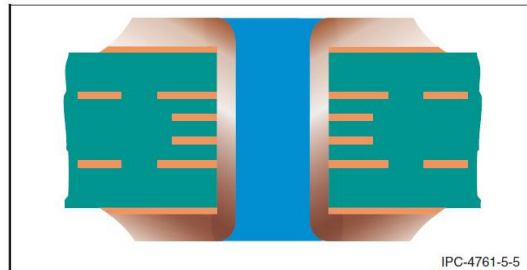
IPC-4761-5-3

Single Sided Plugged Not Recommended  
Figure 5-3 Examples of Type III Plugged Vias



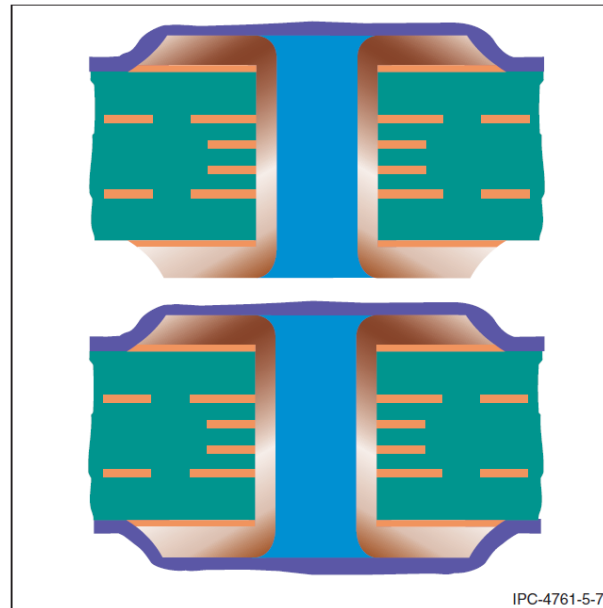
IPC-4761-5-4

Single Sided Plugged and Covered Not Recommended  
Figure 5-4 Examples of Type IV Plugged and Covered Vias



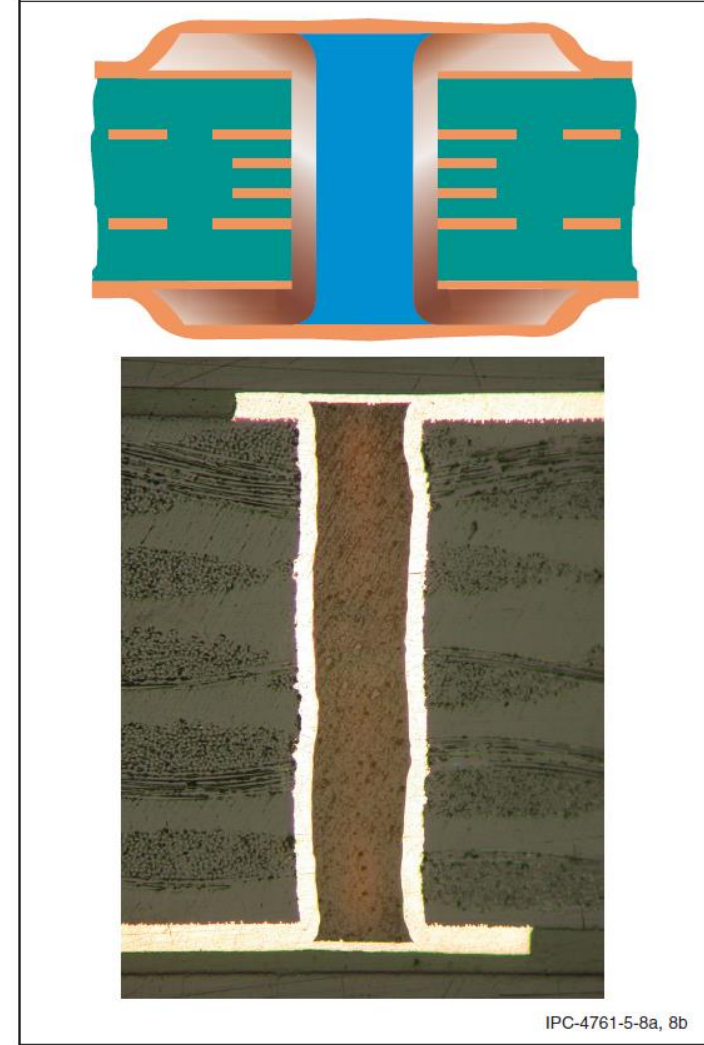
IPC-4761-5-5

Figure 5-5 Example of Type V Filled Via



IPC-4761-5-7

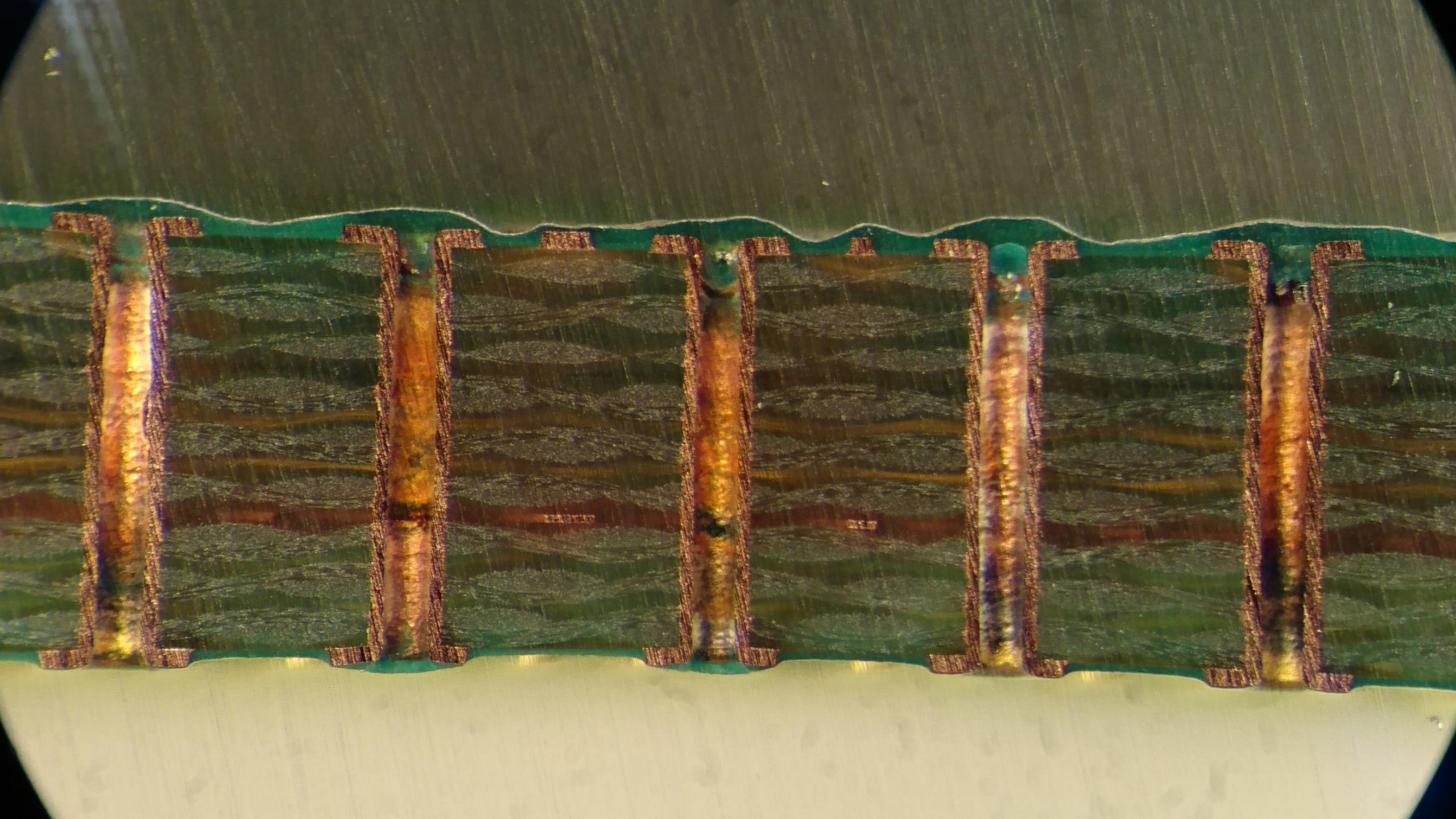
Figure 5-7 Examples of Type VI Filled and Covered Vias,  
Liquid Film Cover



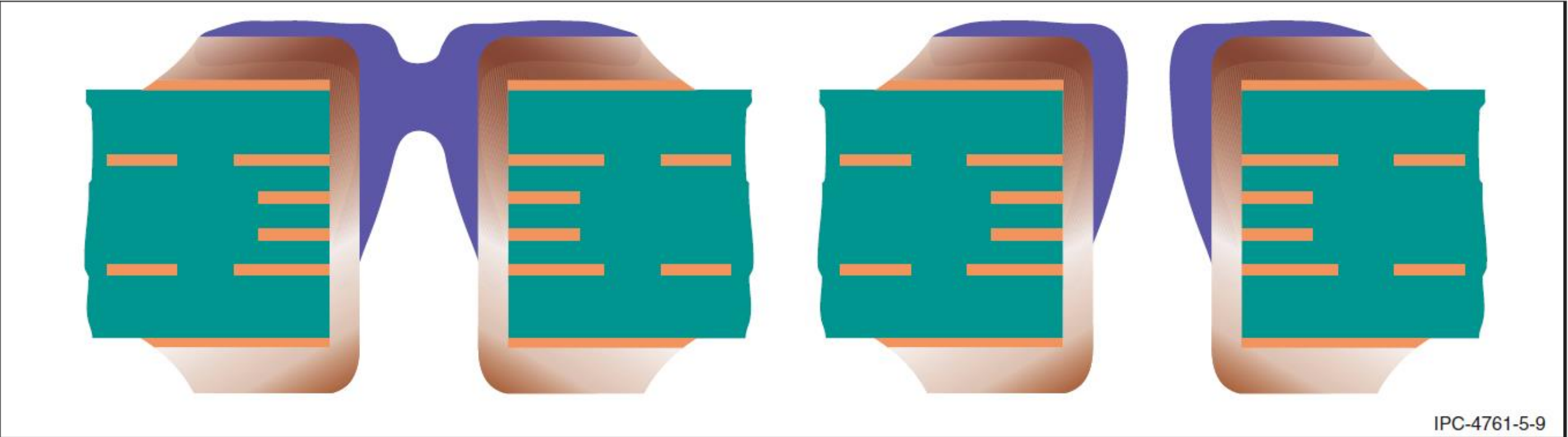
IPC-4761-5-8a, 8b

Figure 5-8 Examples of Type VII Filled and Capped Via



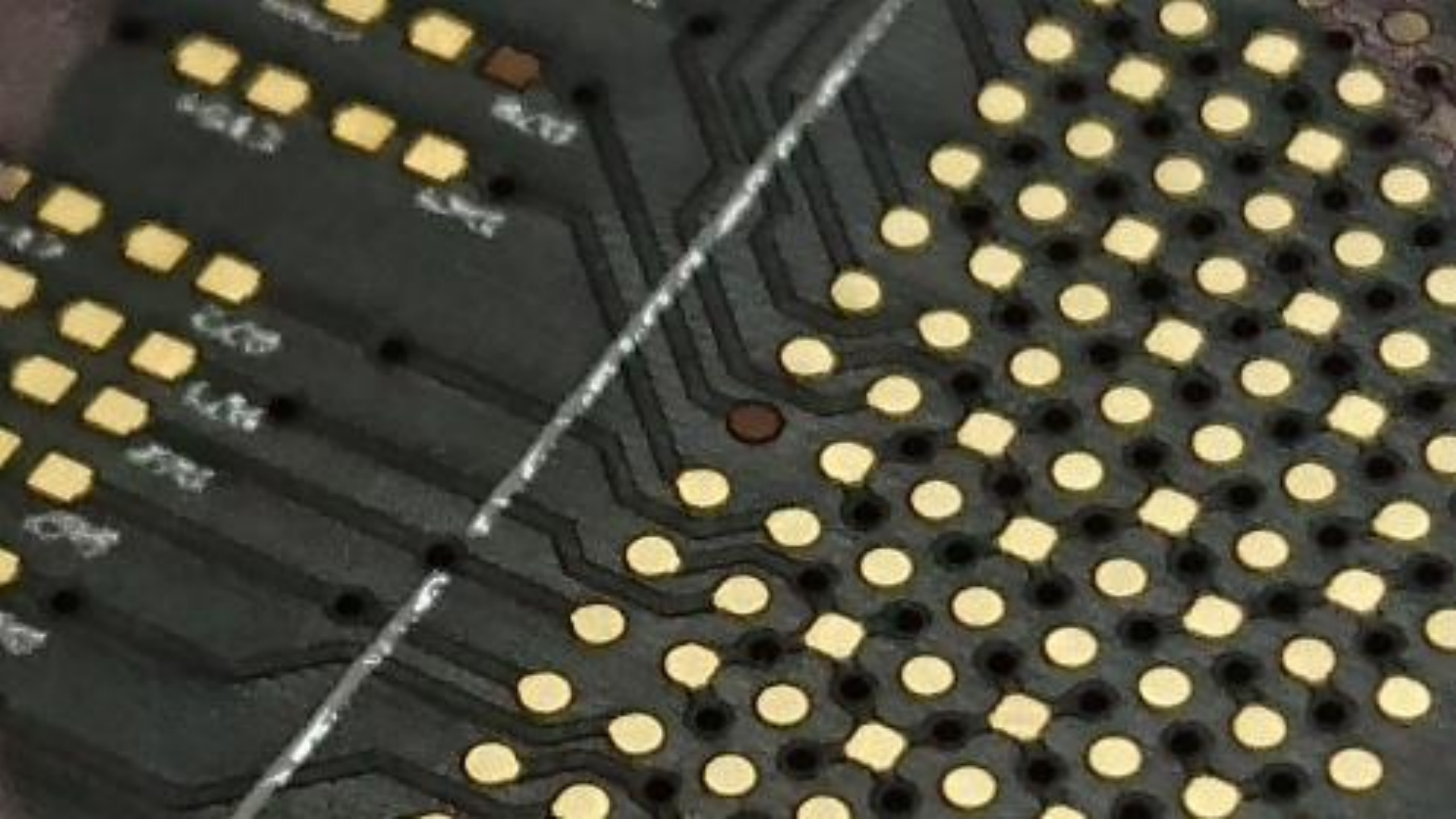




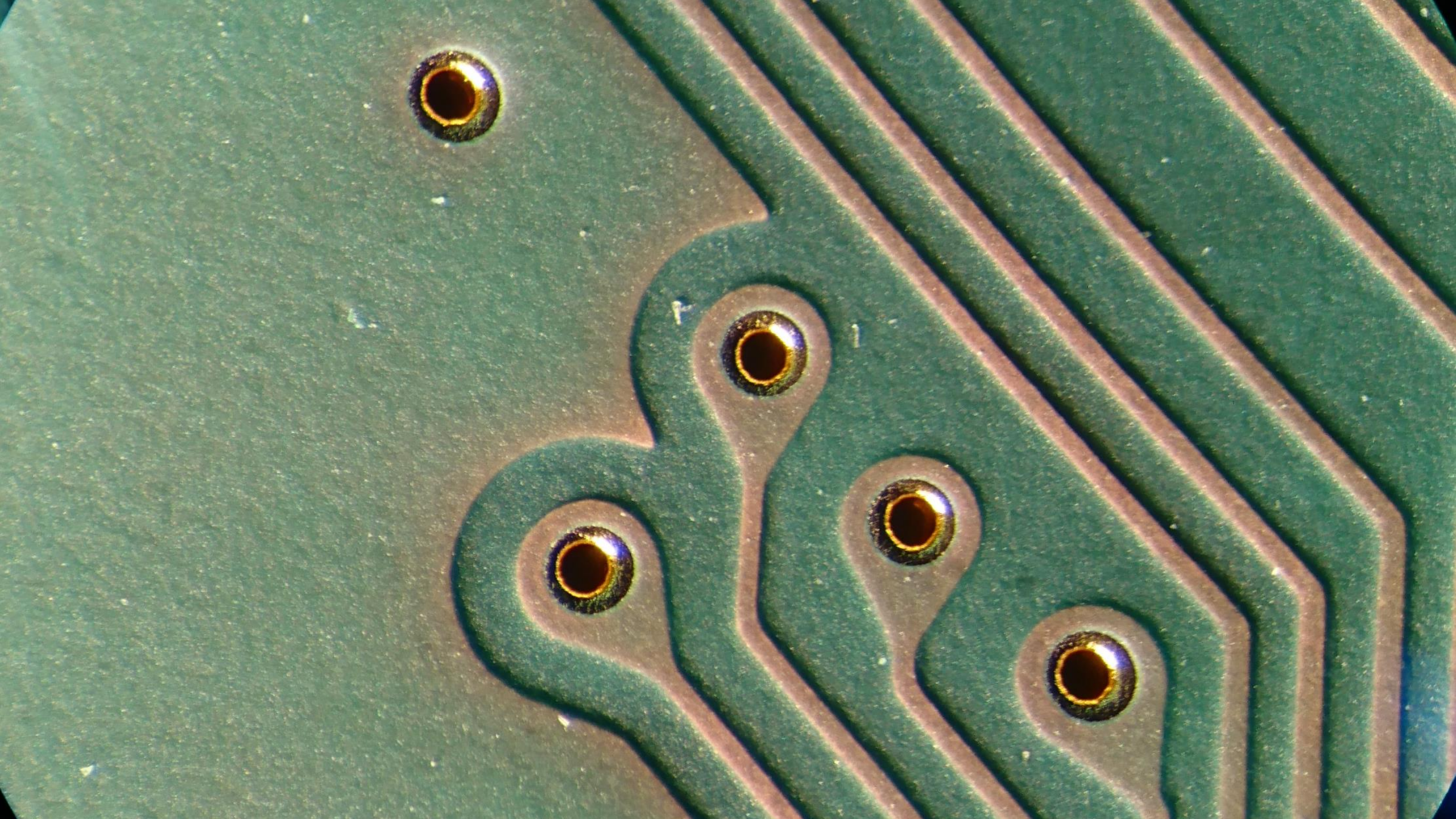


IPC-4761-5-9

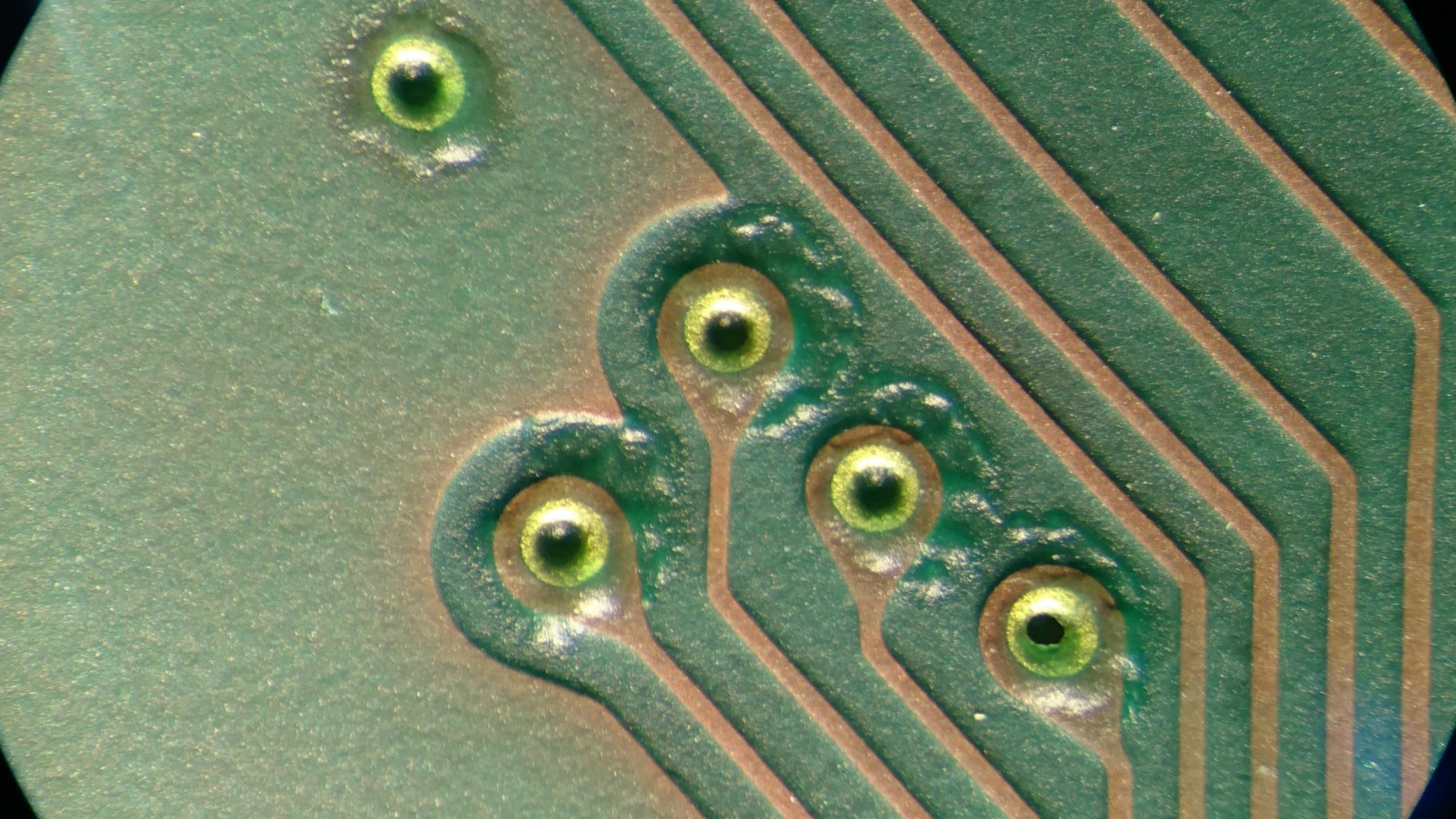
Figure 5-9 Examples of Partially Filled Vias





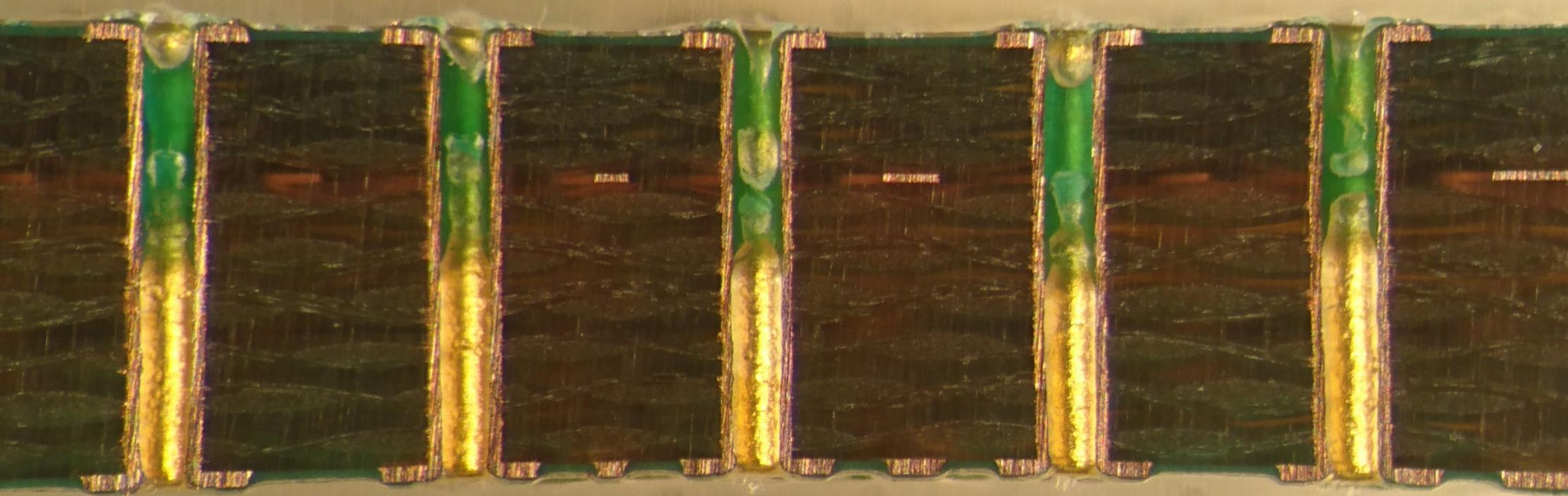




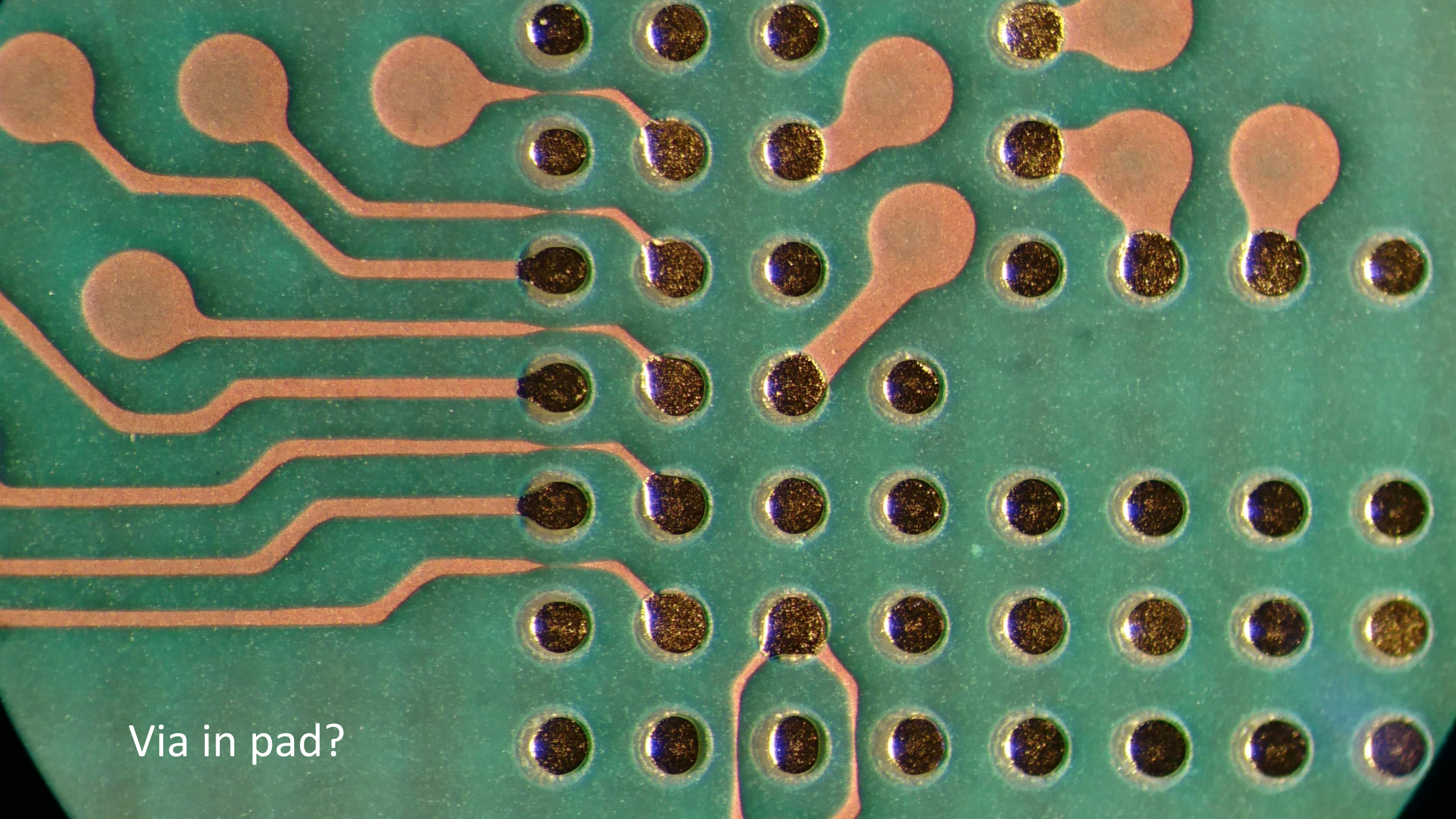




Odkriti skožniki na spajkalni kritini -> ENIG -> zaščita skožnikov IPC-4761 – Type IIIa



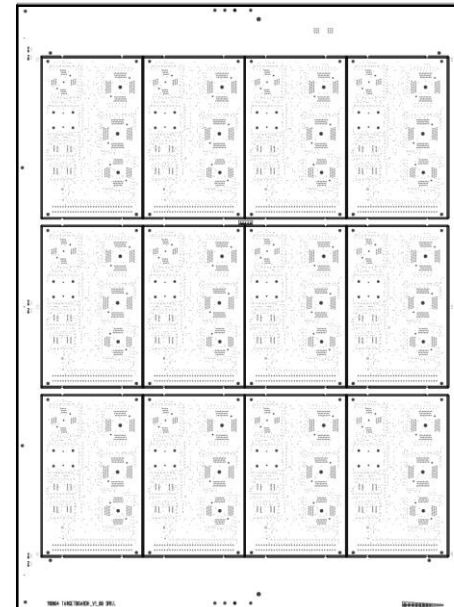
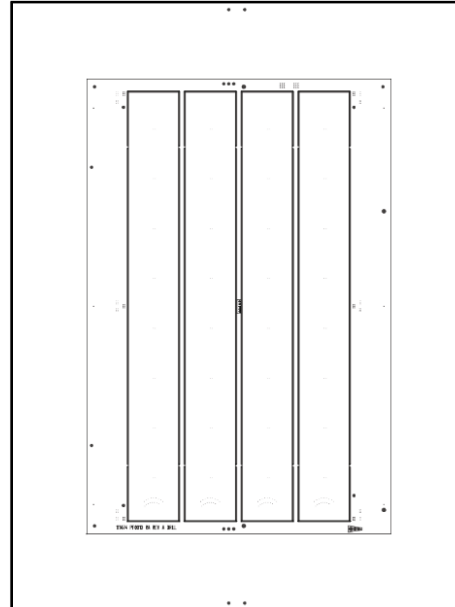
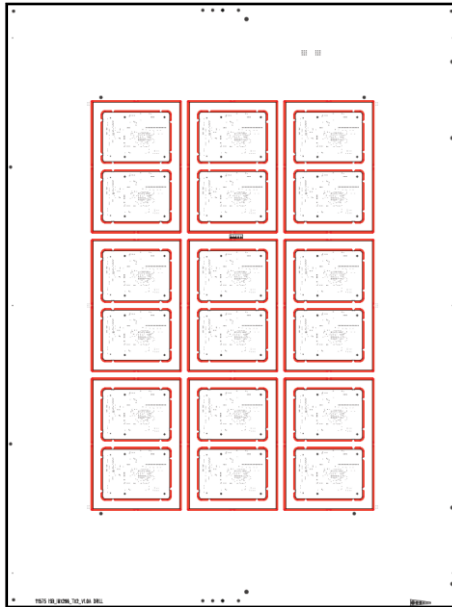
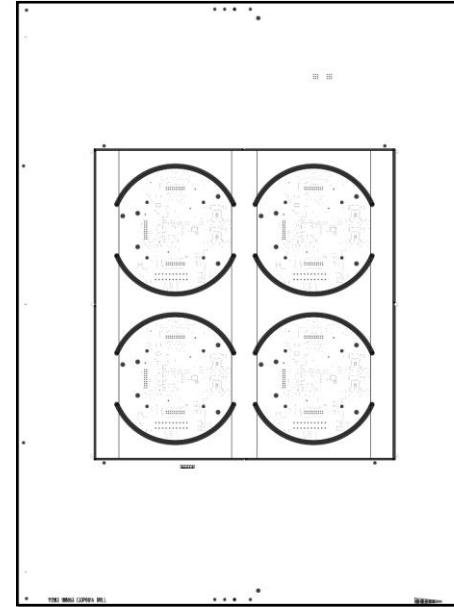
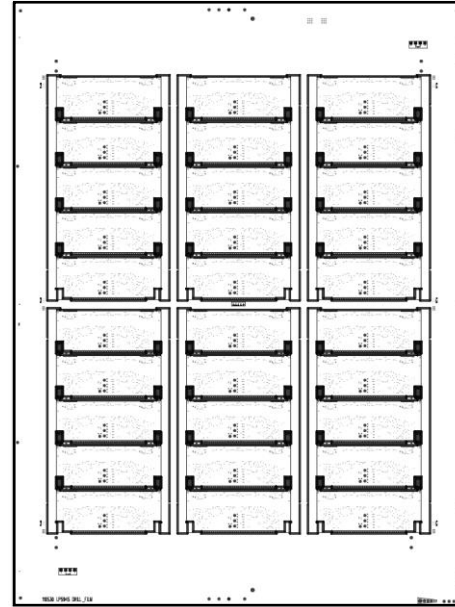
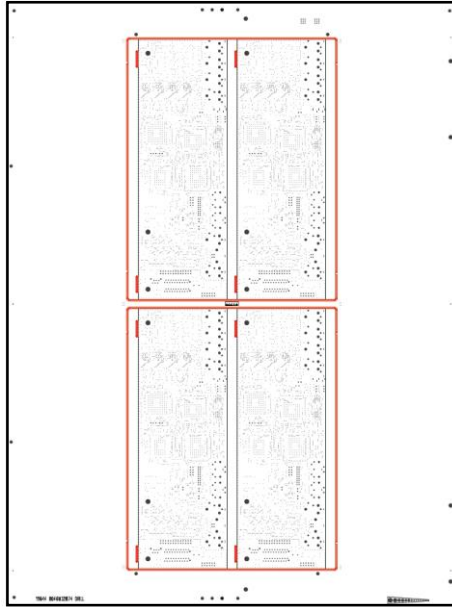




Via in pad?

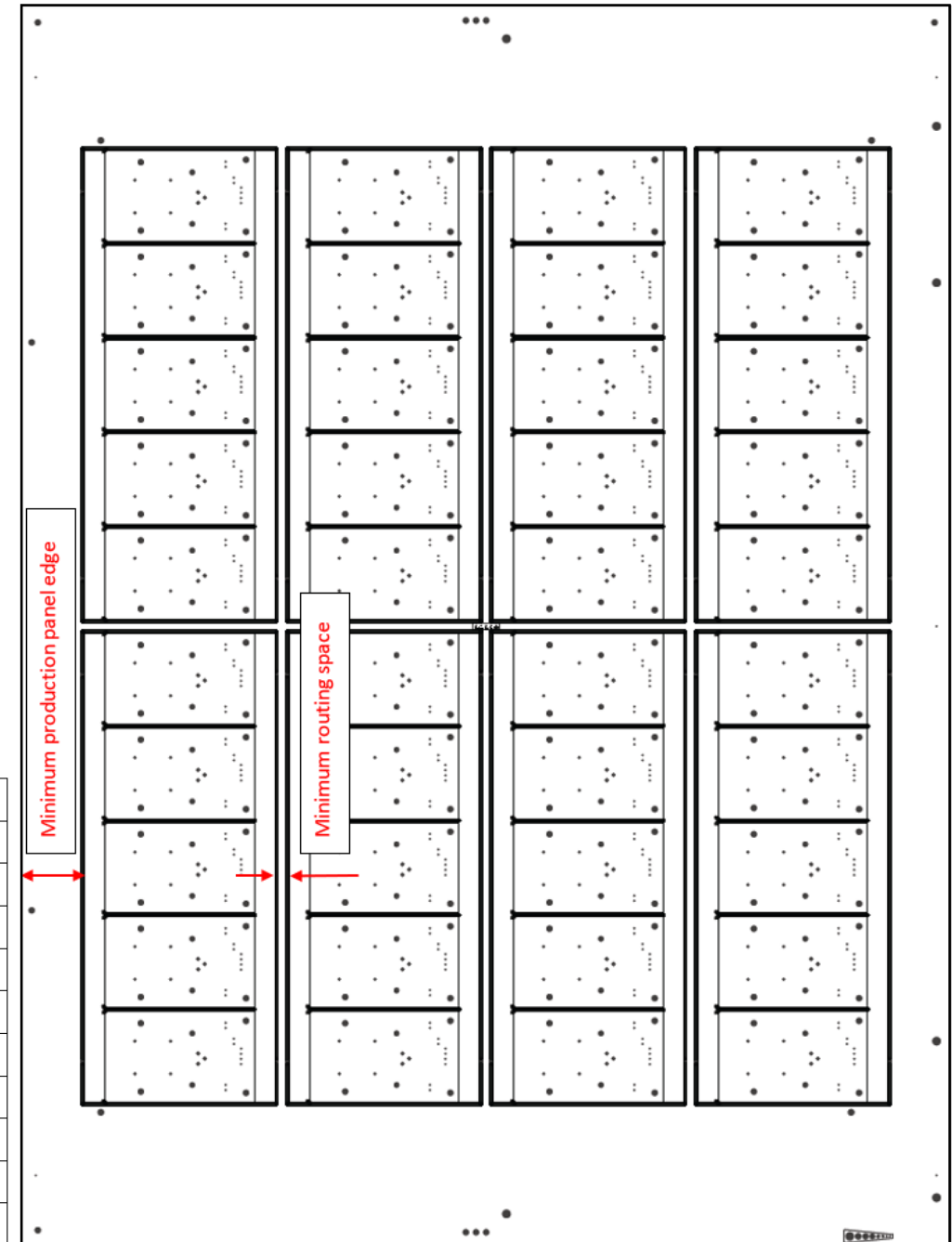


# Montaža na delovni format



# Uporabna površina delovnega formata

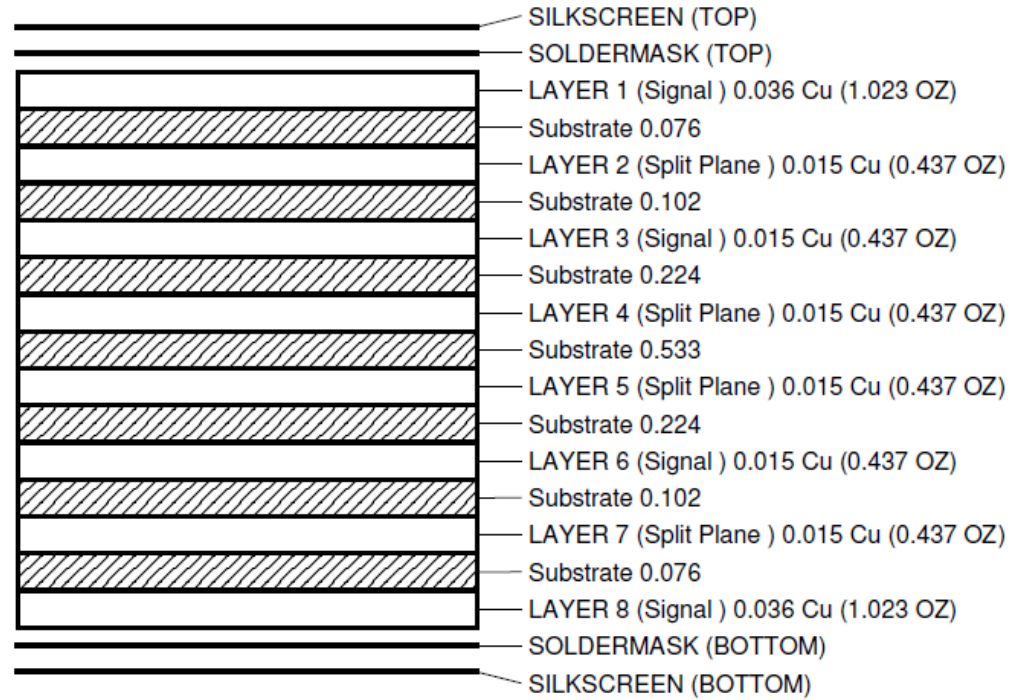
Production panel size	Type of PCB	Min. Production panel edge
457mm x 610mm	One-sided	12mm
	Double-sided	12mm-15mm, depending on the complexity
	Multi-layer ML4	15mm-20mm, depending on the complexity
	Multi-layer ML6 and more	25mm
305mm x 457mm	One-sided	12mm
	Double-sided	12mm-15mm, depending on the complexity
535mm x 610mm	One-sided	12mm
	Double-sided	12mm-15mm, depending on the complexity
280mm x 410mm	Multi-layer ML4	15mm-20mm, depending on the complexity
	Multi-layer ML6 and more	20mm





Kontrolirane impedance

## LAYER STACK-UP



IMPEDANCES			
ALL UNITS ARE IN MILLIMETERS			
LAYER	SINGLE-ENDED	DIFFERENTIAL (WIDTH/GAP)	
	50 OHM +/-10%	90 OHM +/-10%	100 OHM +/-10%
L1	0.1269	0.1267/0.2032	0.1016/0.254
L2			
L3	0.1268		0.1016/0.1397
L4			
L5			
L6	0.1268	0.1266/0.1266	0.1016/0.1397
L7			
L8	0.1269		

# Kontrolirane impedance

File Edit Configure Help

Parameter Entry Units  
 Mils  Inches  Microns  Millimetres

Surface Microstrip 1B  
Surface Microstrip 2B  
Coated Microstrip 1B  
Coated Microstrip 2B  
Embedded Microstrip 1B1A  
Embedded Microstrip 1B2A

**Coated Microstrip 1B**

Substrate 1 Height H1 150,0000 Calculate  
Substrate 1 Dielectric Er1 4,2000 Calculate  
Lower Trace Width W1 250,0000  
Upper Trace Width W2 240,0000 Calculate  
Trace Thickness T1 35,0000 Calculate  
Coating Above Substrate C1 20,0000  
Coating Above Trace C2 15,0000  
Coating Dielectric CEr 4,0000  
Impedance Zo 50,26 Calculate  
More...

Notes  
Add your comments here

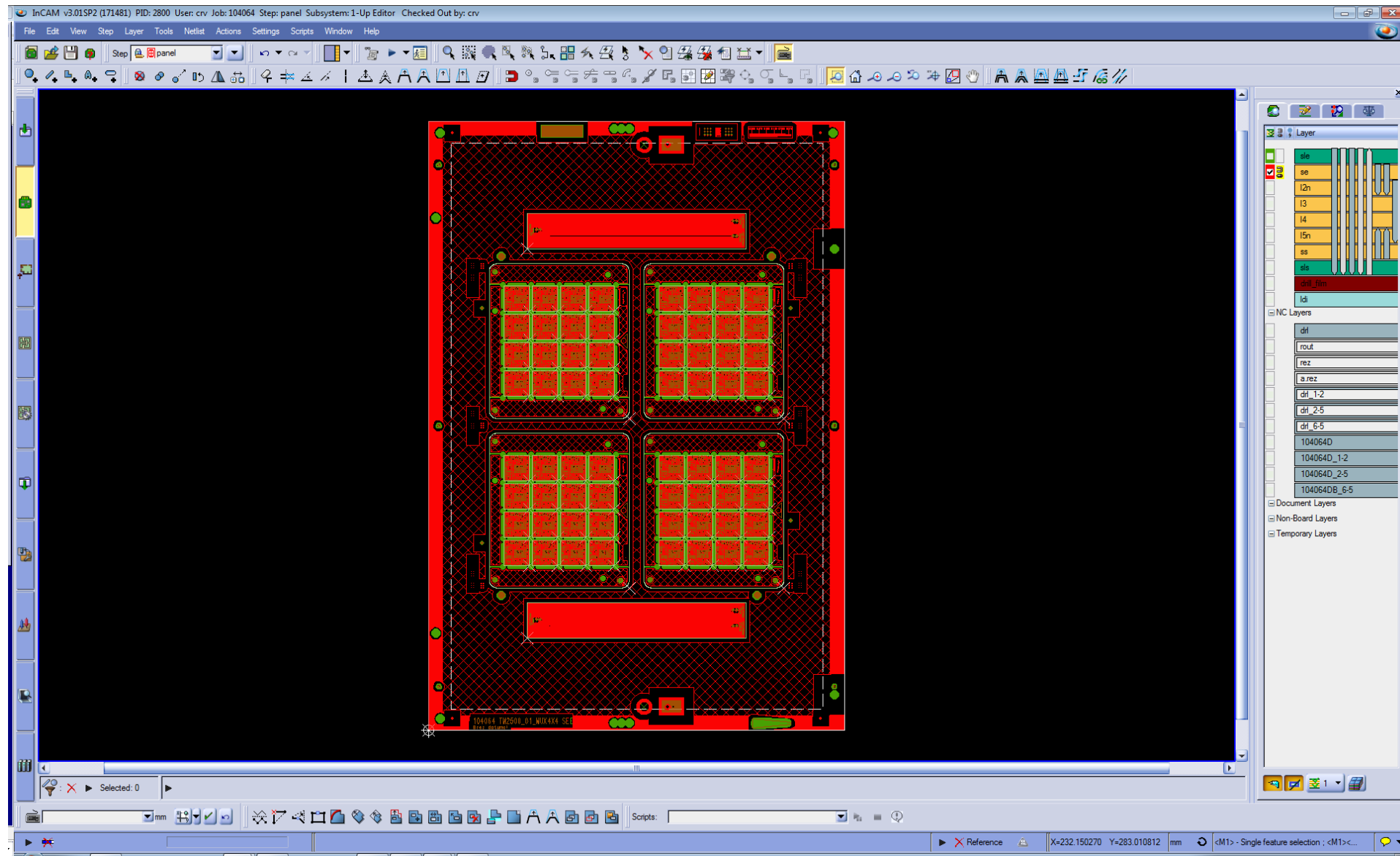
Interface Style  
 Standard  
 Extended

G.S. Convergence  
 Fine (Slower)  
 Coarse (Faster)

Lossless Calculation Frequency Dependent Calculation

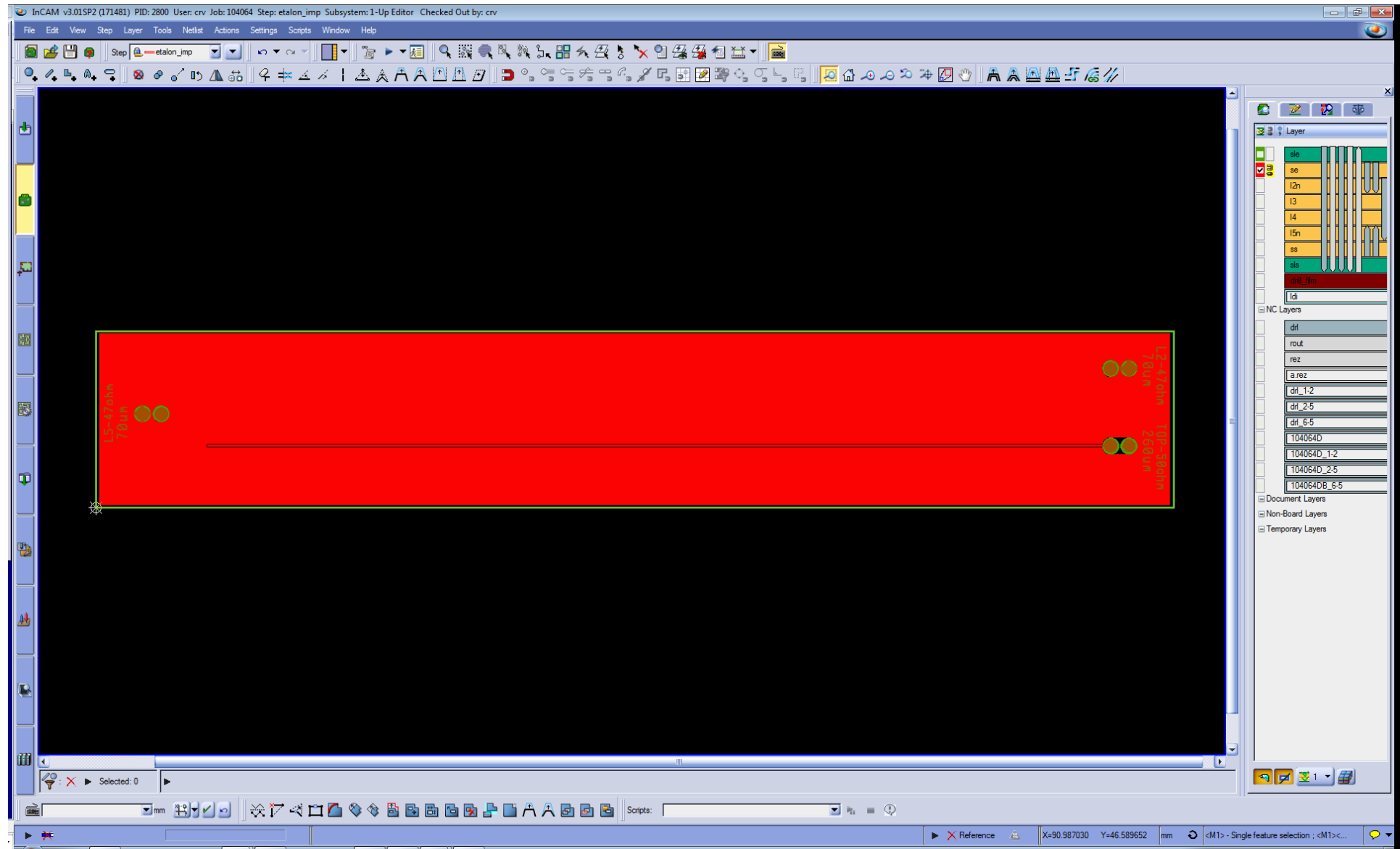
All Structures

# Kontrolirane impedance

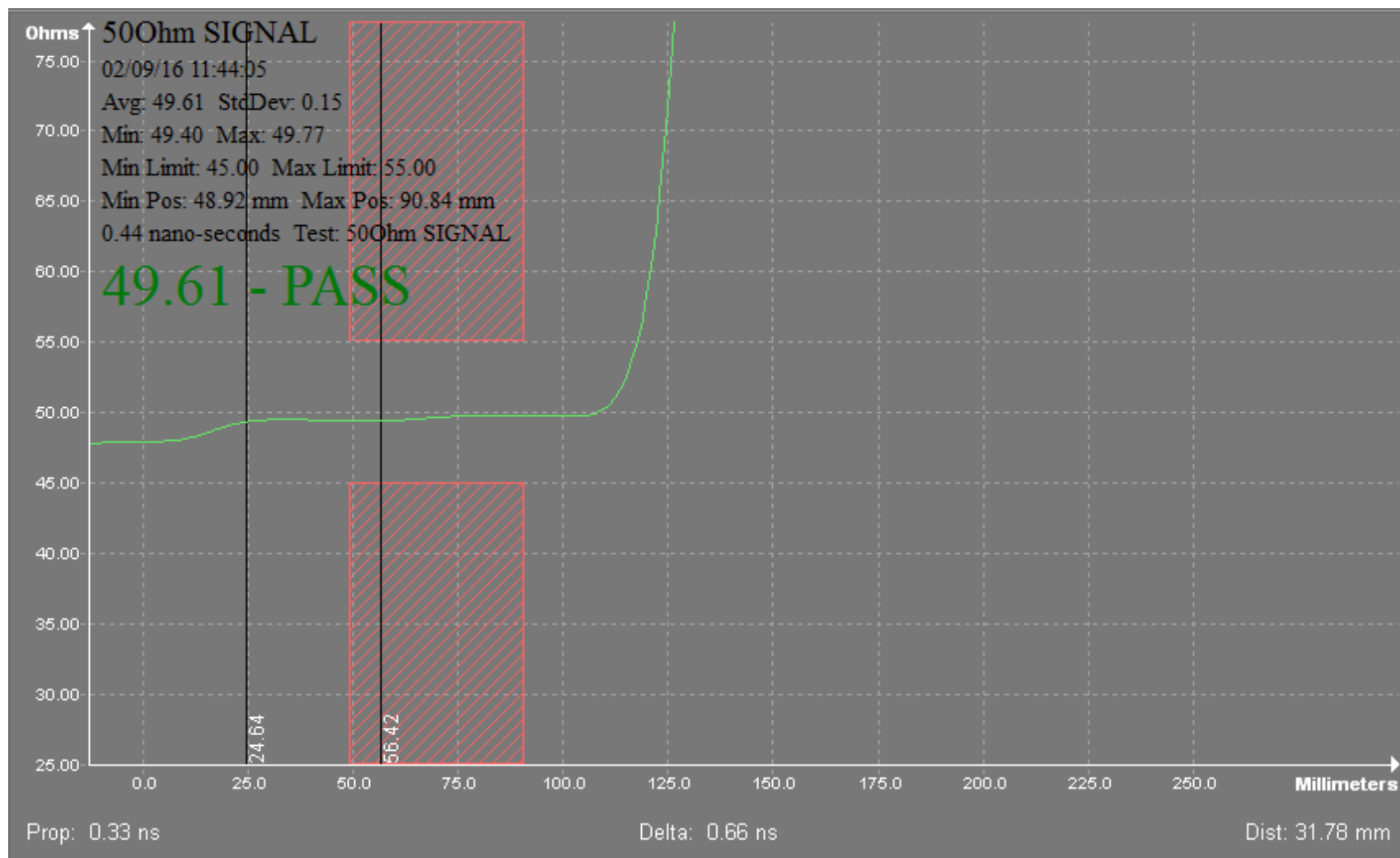




# Kontrolirane impedance



# Kontrolirane impedance



Name	Result	Avg	S/N	Job #	LYR	Time/Date	Min Z	Max Z	Std Dev	Oper
500 Ohm SIGNAL	Pass	49.61	1	103045	L3	02/09/16 11:44:04	49.40	49.77	0.15	ZORAN
500 Ohm SIGNAL	Pass	50.62	2	103045	L3	02/09/16 11:44:30	50.07	50.75	0.20	ZORAN



Razvojni in raziskovalni projekti

PROJEKT: Lasersko vrtanje

Id 113312 Kupčeva oznaka: ATTEP 3123

HDI plošča, z lasersko vrtanimi slepimi izvrtinami 0,1mm in pokopanimi izvrtinami.

Osnovni material: Panasonic R-1755M

ML struktura:

35mic.

Prepreg 1080 ..... 0,074mm

35mic.

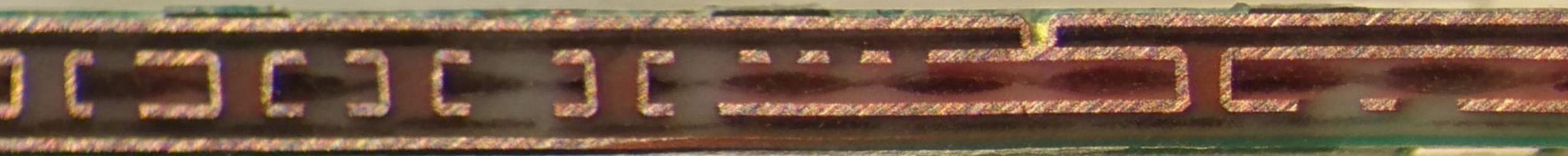
Core 0,1mm

35mic.

Prepreg 1080 ..... 0,074mm

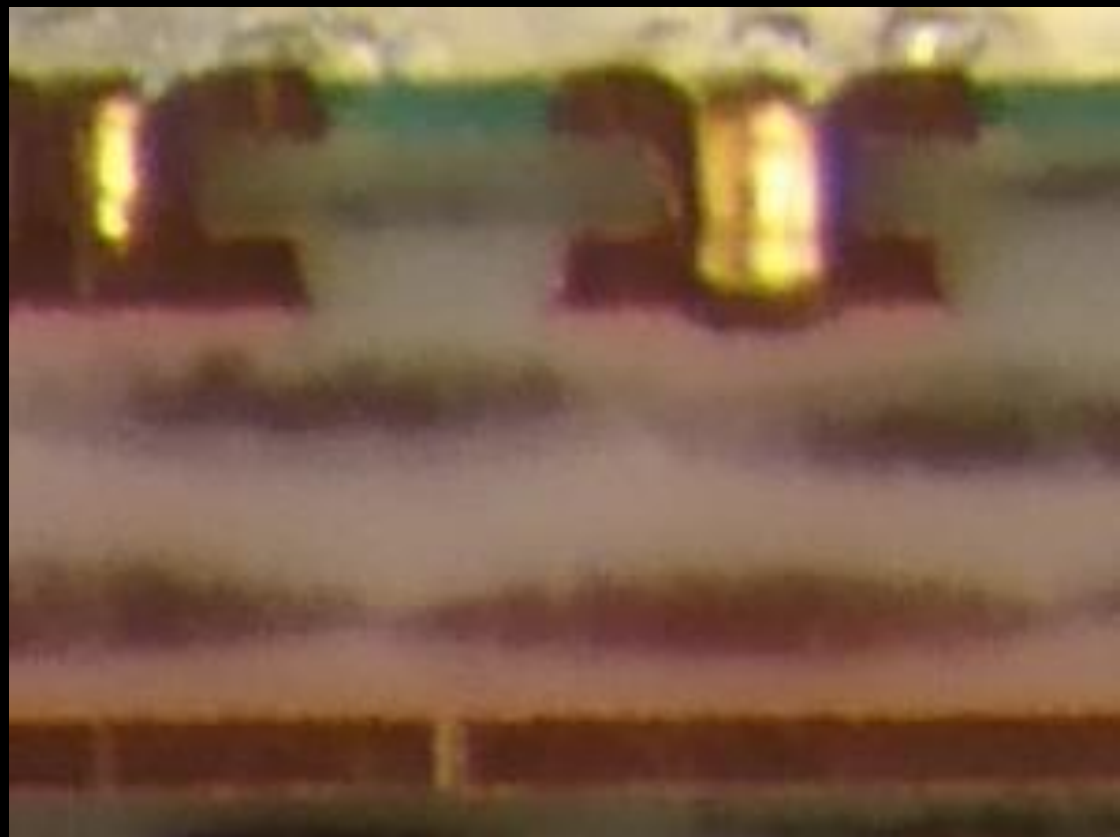
35mic.

Končna debelina ploščice  $d = 0,4\text{mm} \pm 0,1\text{mm}$

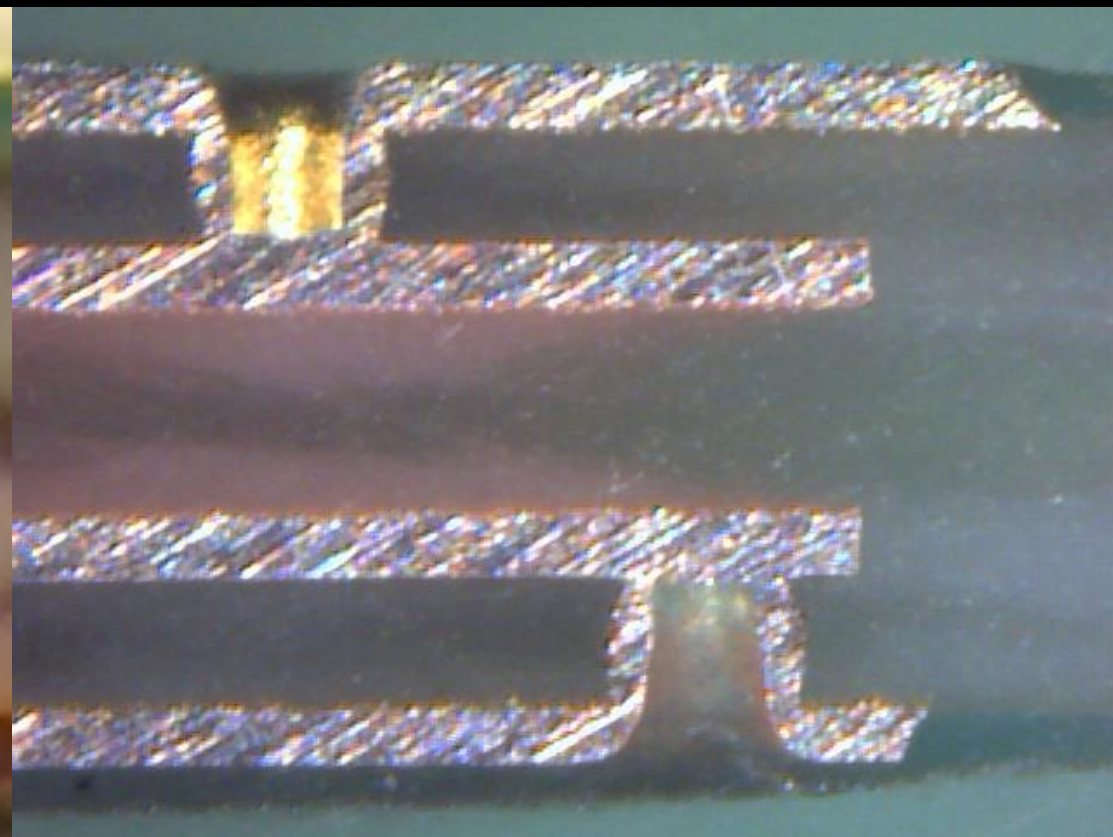




Mehansko vrtanje



Lasersko vrtanje



PROJEKT: Osnovni material MEG-6

Id 114504 Kupčeva oznaka: 56654

ML struktura:

35mic. Cu

R5670K Prepreg 2116 ..... 0,125mm nom.

35mic.

R5775K Core 0,2mm

35mic.

R5670K Prepreg 2116 ..... 0,125mm nom.

R5670K Prepreg 2116 ..... 0,125mm nom.

35mic.

R5775K Core 0,2mm

35mic.

R5670K Prepreg 2116 ..... 0,125mm nom.

R5670K Prepreg 2116 ..... 0,125mm nom.

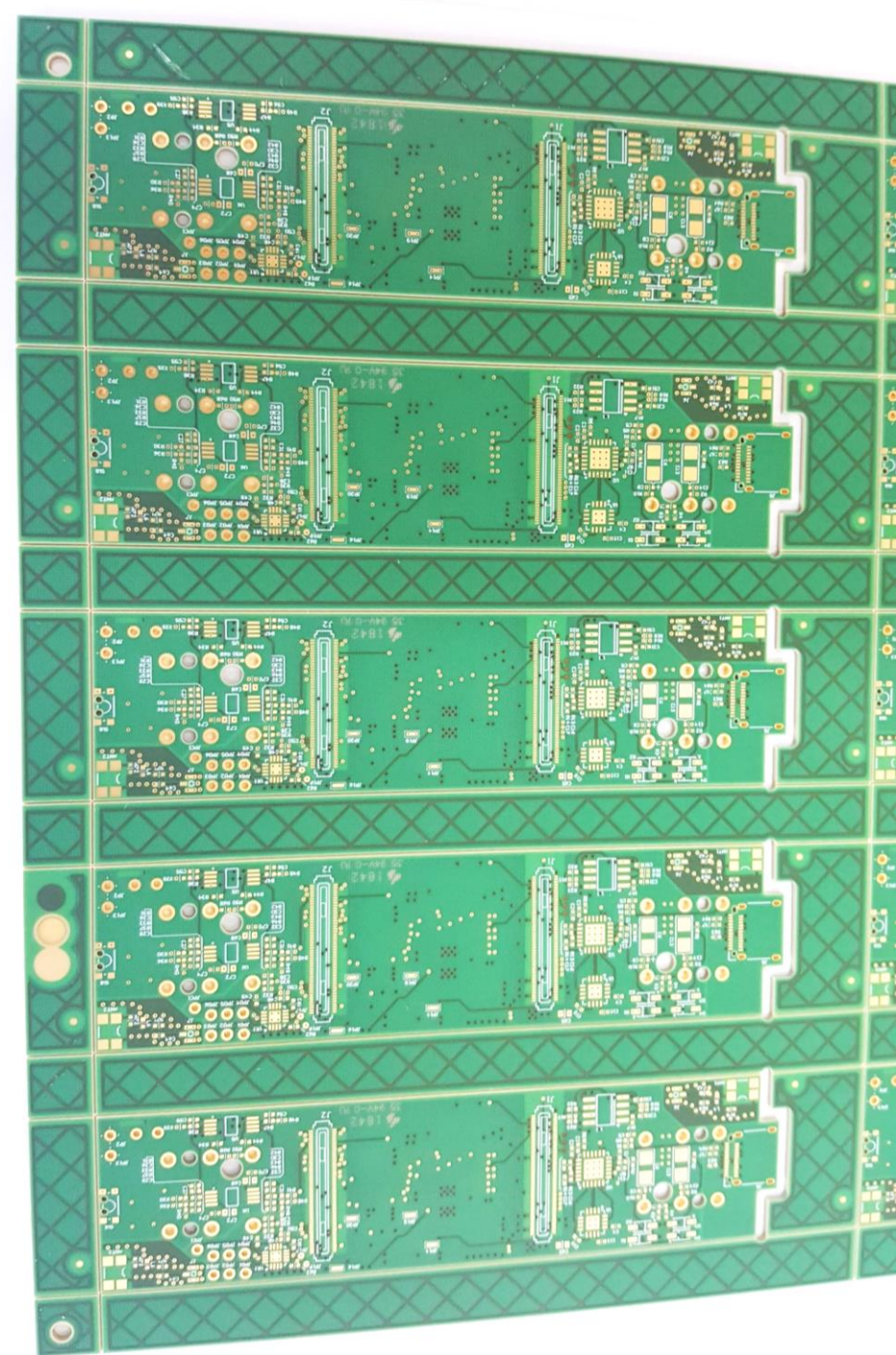
35mic.

R5775K Core 0,2mm

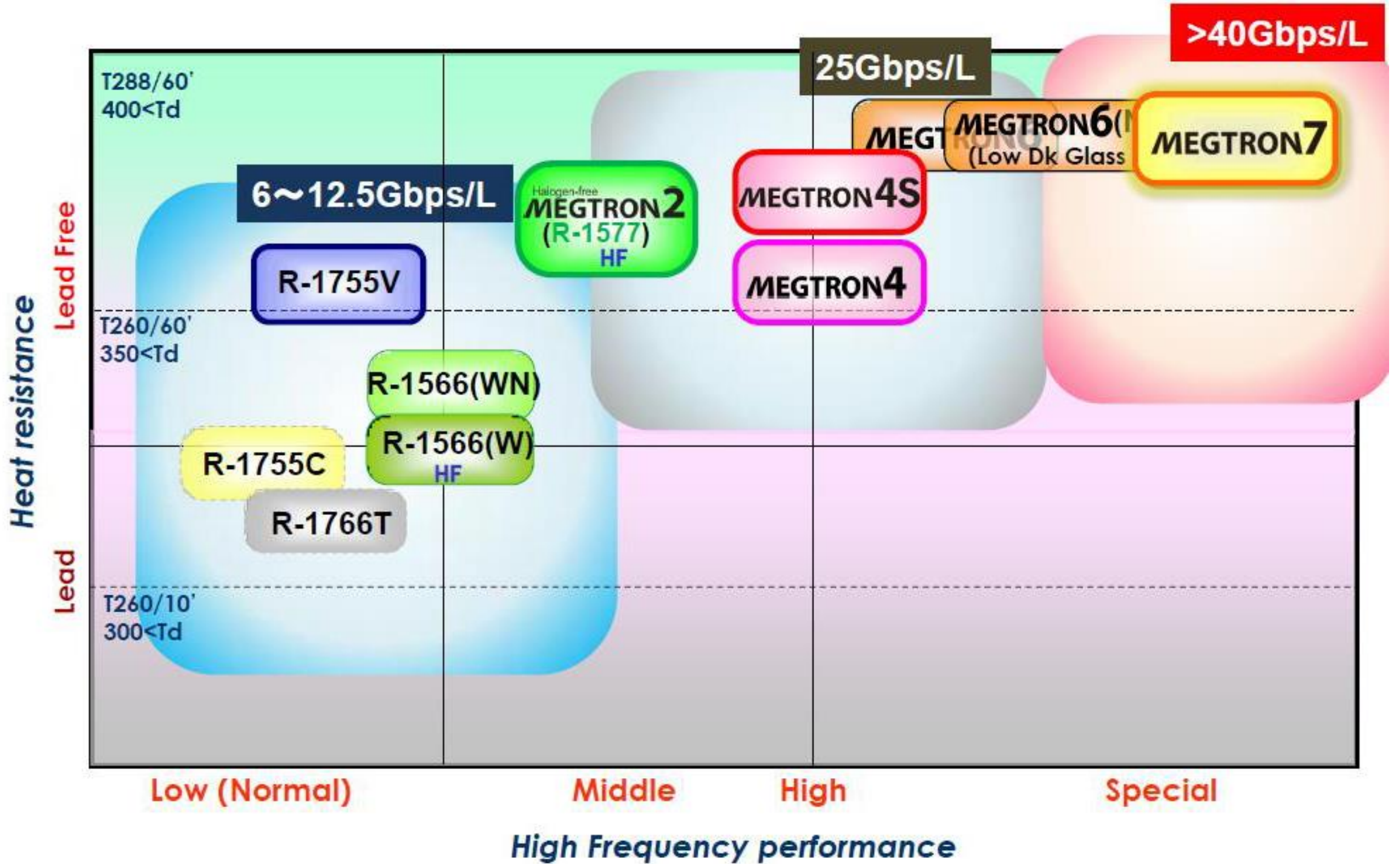
35mic.

R5670K Prepreg 2116 ..... 0,125mm nom.

35mic.







## MEGTRON 6 - Line Up für QTA Artikel vom Lager Enns/ Österreich

Material	Dicke nominal		Aufbau	Harzgehalt	Suffix	Format Kette 1100 x1255mm		Format Kette 950 x1255mm		Lagermenge	Artikelnummer
	mm	mil				RTF	RTF	RTF	RTF		
				%		18/18µm	35/35	18/18µm	35/35	Tafeln	
Laminat - R5775K	0,075	2,60	1x1078	63	-	X				10	HW00800053
	0,100	3,90	1x3313	54	-	X	X			50	HW01000156
	0,100	3,90	2x1035	65	-			X		100	HW01000177
	0,130	5,00	1x2116	54	-	X	X			10	HW01300042
	0,200	7,80	2x3313	54	-	X				10	HW02000141
	0,250	9,60	2x2116	54	-	X	X			20	HW02500055
	0,300	11,50	3x3313	54	-	X				30	HW03000044
	0,740	28,0*	4x7628	42	-	X	X			10	HW07400004
	1,490	58,00	8x7628	42	-	X	X			10	HW14900002

Material	Dicke nominal		Gewebe	Harzgehalt	Suffix	Rollenbreite		Lagermenge	Artikelnummer
	µm					1285mm			
				%				Laufmeter	
Prepreg - R5670K	49		1027	75	KD	X		200	HW10270077
	60		1035	70	KD	X		100	HW10350064
	68		1035	73	KF	X		100	HW10350047
	74		1035	75	KG	X		100	HW10350048
	89		1078	68	KF	X		100	HW10780037
	104		1078	72	KG	X		100	HW10780055
	98		3313	54	KC	X		100	HW33130025
	106		3313	57	KD	X		100	HW33130085
	125		2116	54	KG	X		100	HW21160366



# PROJEKT: TRAFO 20kV

Id 114715 Kupčeva oznaka: WORK\_SDU

Stackup	Layer	% Cu	Board Layer Stack	Name	Thickness	
				Top Solder	Solder Resist	0 mm
L1	54		Top Layer	Copper	0,14 mm	
			R1650M 2116	Prepreg	0,122 mm	
L2	73		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L3	77		Signal	Copper	0,175 mm	
			R1650M 2116	Prepreg	0,122 mm	
L4	58		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L5	61		Signal	Copper	0,175 mm	
			R1650M 2116	Prepreg	0,122 mm	
L6	65		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L7	65		Signal	Copper	0,175 mm	
			R1650M 2116	Prepreg	0,122 mm	
L8	63		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L9	62		Signal	Copper	0,175 mm	
			R1650M 2116	Prepreg	0,122 mm	
L10	81		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L11	80		Signal	Copper	0,175 mm	
			R1650M 2116	Prepreg	0,122 mm	
L12	60		Bottom Layer	Copper	0,14 mm	
			Bottom Solder	Solder Resist	0 mm	
Calculated Thickness before pressing					3,262 mm	

Stackup	Layer	% Cu	Board Layer Stack	Name	Thickness	
				Top Solder	Solder Resist	0 mm
L1	54		Top Layer	Copper	0,14 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 1080	Prepreg	0,086 mm	
L2	73		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L3	77		Signal	Copper	0,175 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 1080	Prepreg	0,086 mm	
L4	58		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L5	61		Signal	Copper	0,175 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 1080	Prepreg	0,086 mm	
L6	65		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L7	65		Signal	Copper	0,175 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 1080	Prepreg	0,086 mm	
L8	63		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L9	62		Signal	Copper	0,175 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 7628	Prepreg	0,204 mm	
			R1650M 1080	Prepreg	0,086 mm	
L10	81		Signal	Copper	0,175 mm	
			R-1755M	Core	0,1 mm	
L11	80		Signal	Copper	0,175 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 1080	Prepreg	0,086 mm	
			R1650M 7628	Prepreg	0,204 mm	
L12	60		Bottom Layer	Copper	0,14 mm	
			Bottom Solder	Solder Resist	0 mm	
Calculated Thickness before pressing					5,602 mm	

PROJEKT: TRAF0 20kV

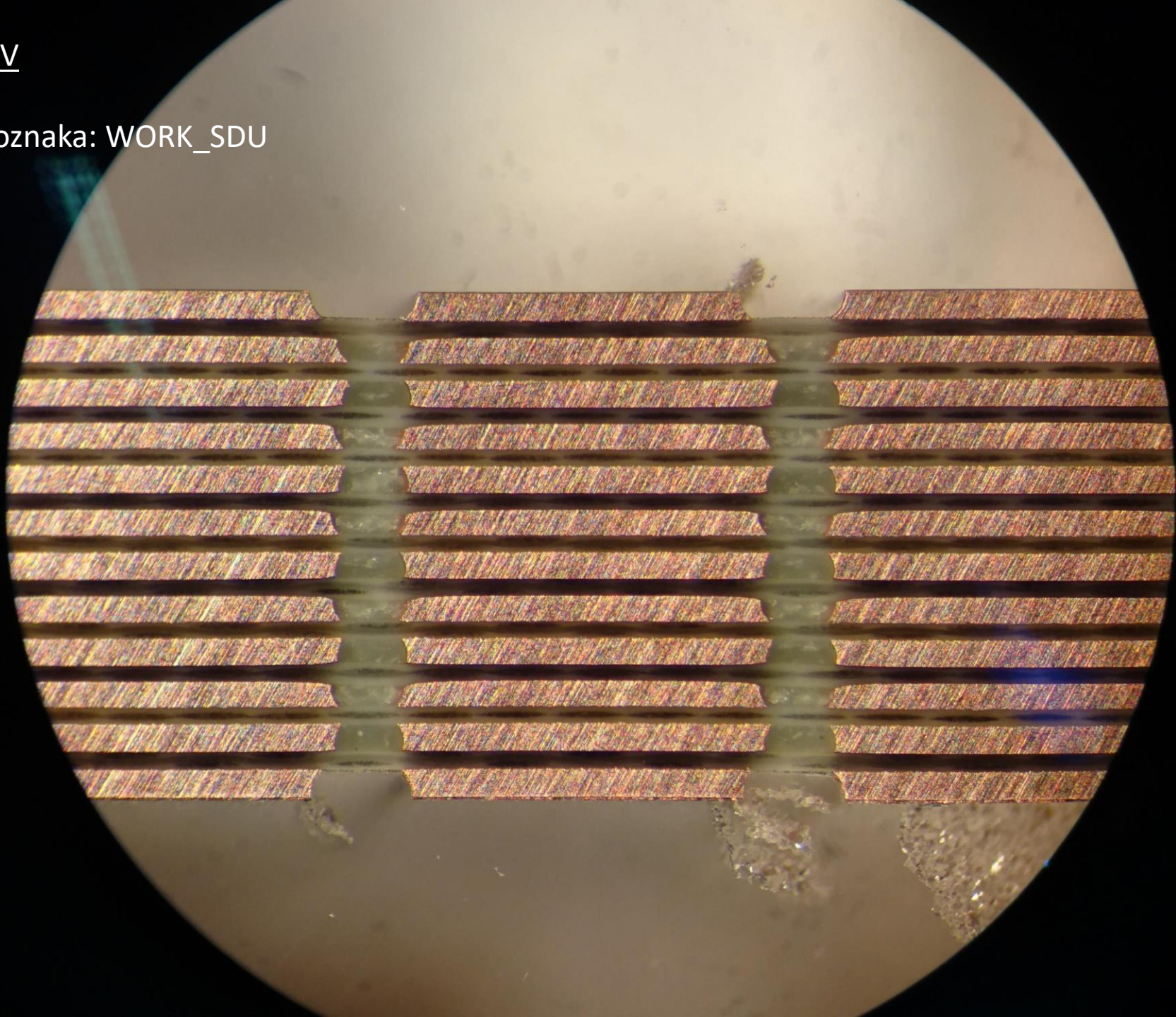
Id 114715 Kupčeva oznaka: WORK\_SDU



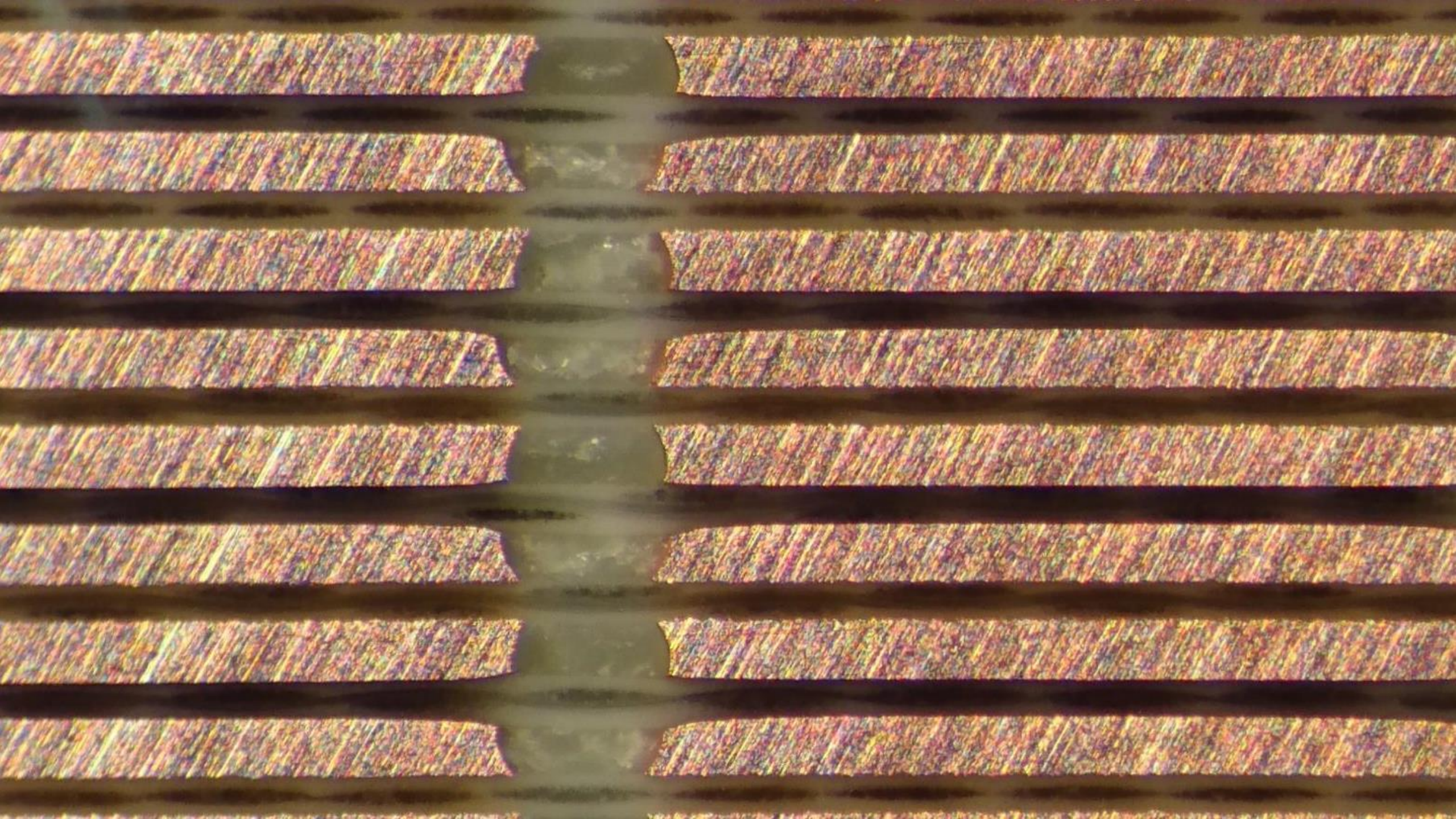


PROJEKT: TRAF0 20kV

Id 114715 Kupčeva oznaka: WORK\_SDU

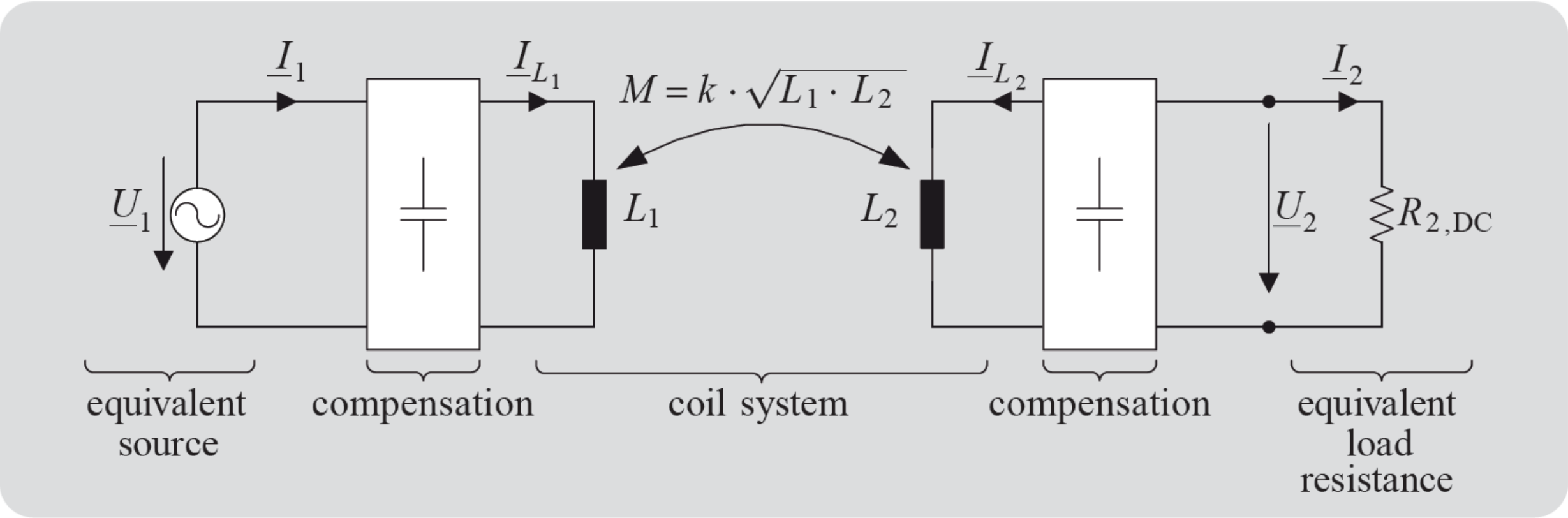






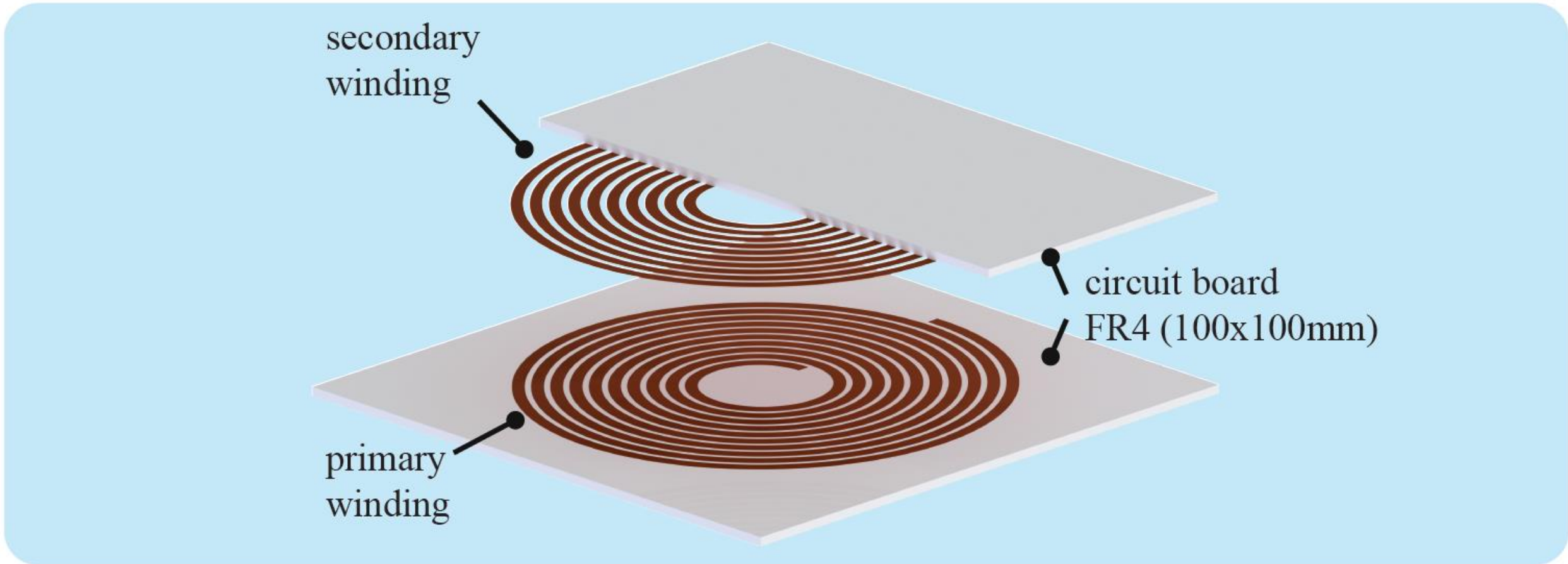


# Contactless Energy Transfer

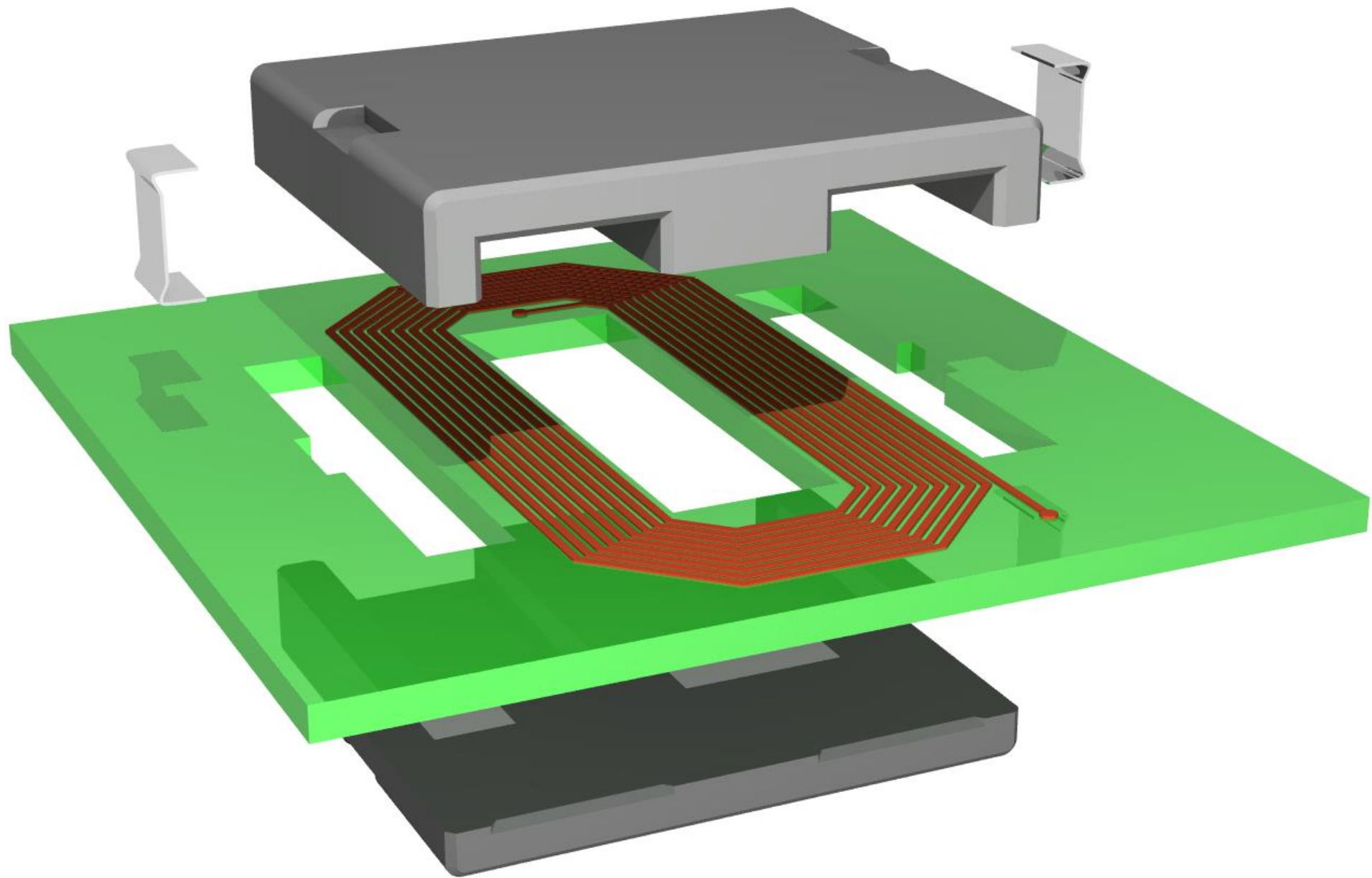


**Figure 1: Overview of an inductive CET system with reactive power compensation and coil system**

# Geometry



**Figure 2: 3D model of the coil system with 10 copper windings on a FR4 PCB board. For improved visibility, only one copper layer of the coil is shown.**



PROJEKT: plošča s kovinsko sredico in izoliranimi izvrtinami

Id 113440 Kupčeva oznaka: Master V297 Cu core

Kovinska sredica: bakrov substrat debeline 1,0mm

Toplotna prevodnost: 4,1W/m.K

Struktura kompozita:

35mic.baker

Prepreg 2116 ..... 0,122mm

Prepreg 2116 ..... 0,122mm

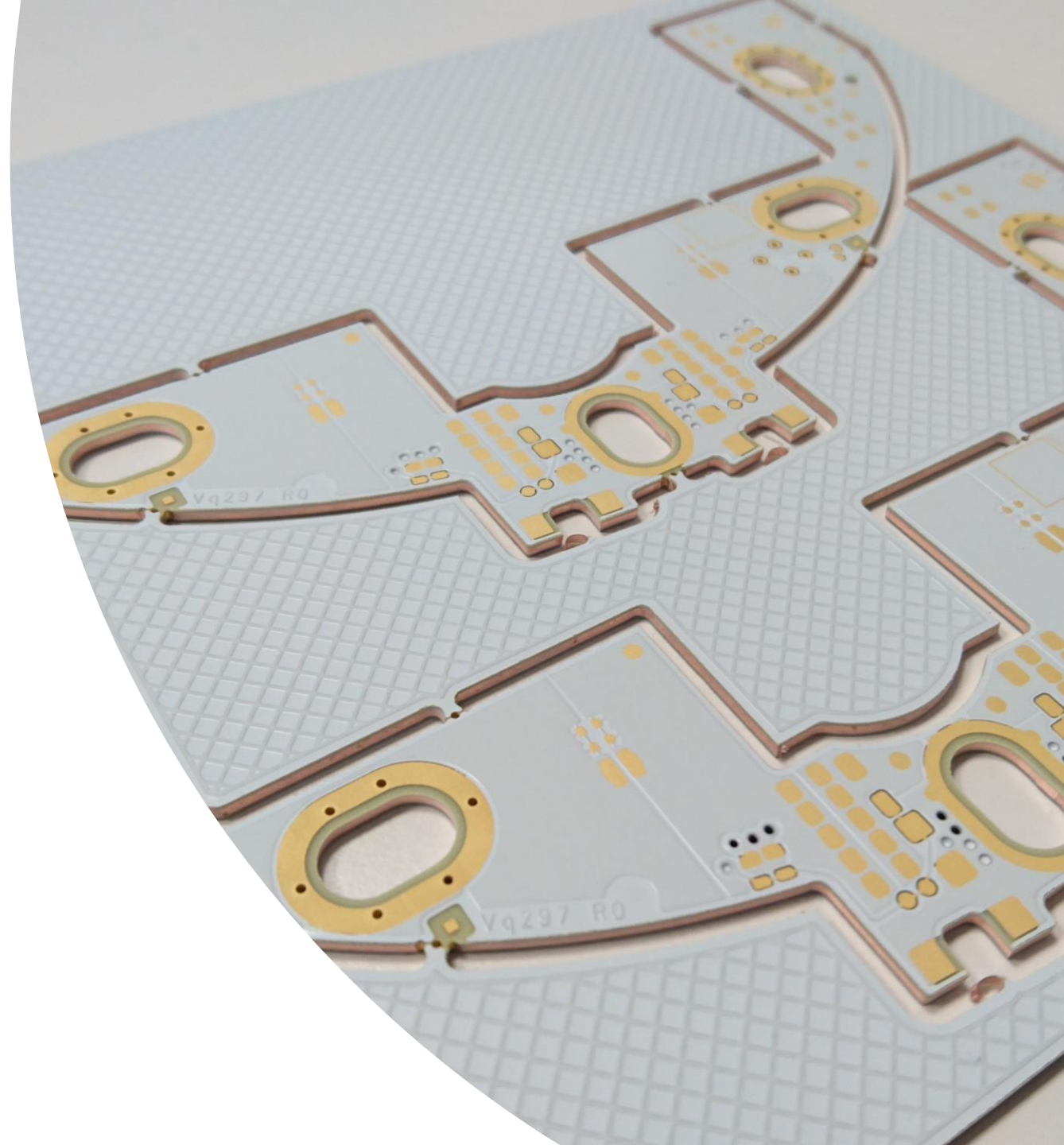
Bakrov substrat Bergquist d= 1,0mm

Prepreg 2116 ..... 0,122mm

Prepreg 2116 ..... 0,122mm

35mic.baker

Končna debelina plošče 1,6mm

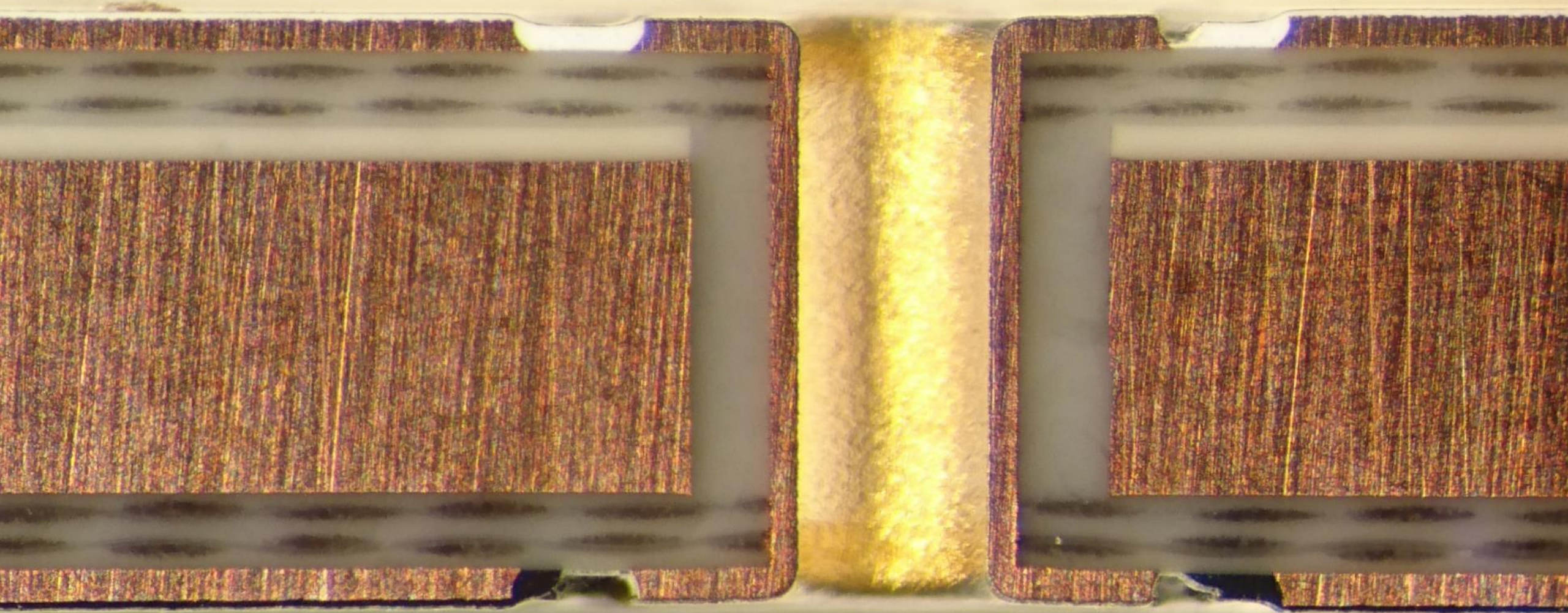




PROJEKT: plošča s kovinsko sredico in izoliranimi izvrtinami

Izolirane izvrtine

Id 113440 Kupčeva oznaka: Master V297 Cu core

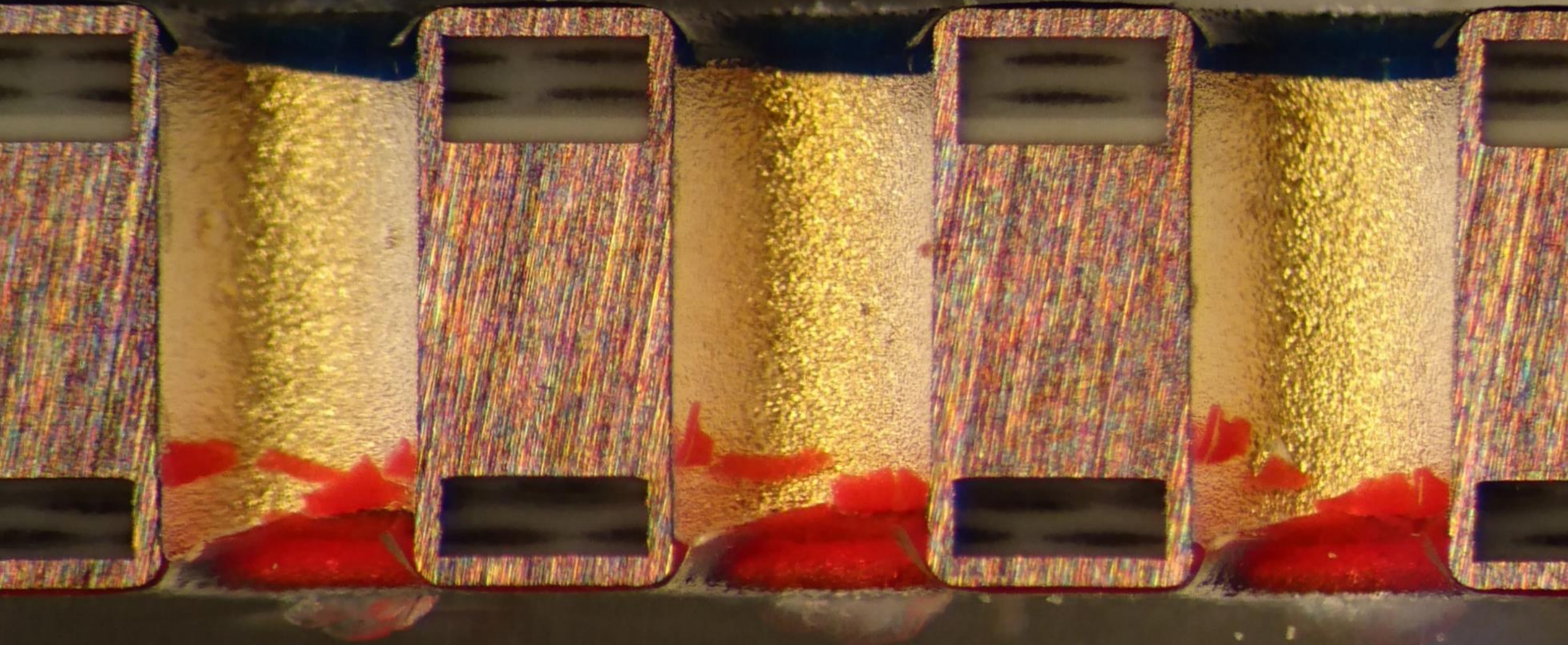




PROJEKT: plošča s kovinsko sredico in izoliranimi izvrtinami

Termalne izvrtine

Id 113440 Kupčeva oznaka: Master V297 Cu core





PROJEKT: FLEX PI 25mic

Id 113826 Kupčeva oznaka: 614752 A19HP2

Polyimid: KREMPEL AKAFLEX 25mic

Štoplak: Tayo - flex – oranžen

Površinska zaščita: ENIG



Embedded feritno jedro



# Feritno jedro



**R 6.30 × 3.80 × 2.50**

**B64290P0037**

■ Parylene coating

**R 6.30 × 3.80 × 2.50 (mm)**

**R 0.248 × 0.150 × 0.098 (inch)**

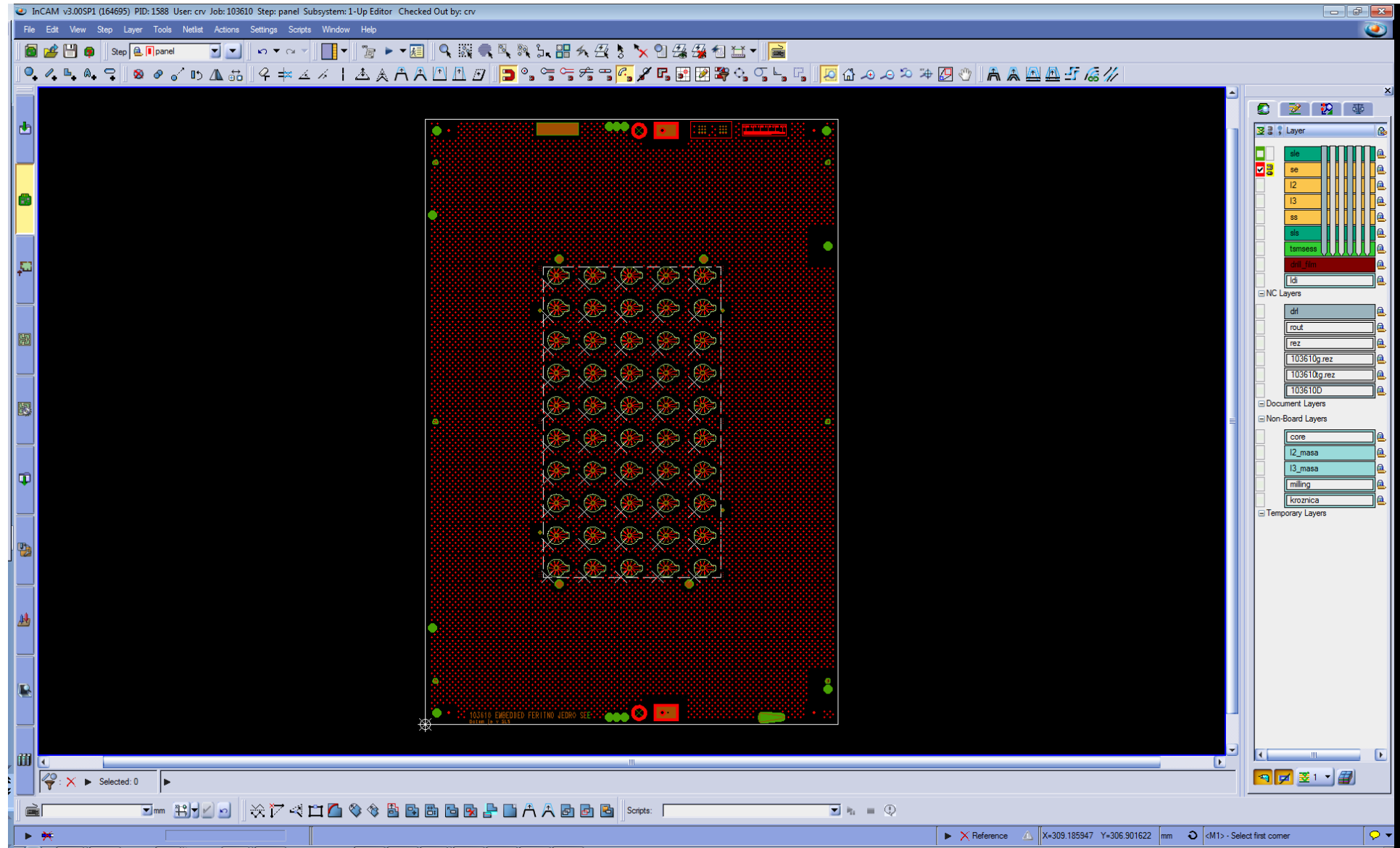
## Dimensions

d <sub>a</sub> (mm)	d <sub>i</sub> (mm)	Height (mm)	d <sub>a</sub> (inch)	d <sub>i</sub> (inch)	Height (inch)	
6.30 ±0.15	3.80 ±0.12	2.50 ±0.12	0.248 ±0.006	0.150 ±0.005	0.098 ±0.005	uncoated <sup>1)</sup>
Coating thickness 0.017 mm						coated

## Characteristics and ordering codes

Material	A <sub>L</sub> value nH	μ <sub>i</sub> (approx.)	Ordering code	Magnetic characteristics				Approx. weight g
				ΣI/A mm <sup>-1</sup>	I <sub>0</sub> mm	A <sub>0</sub> mm <sup>2</sup>	V <sub>0</sub> mm <sup>3</sup>	
K1	20 ±25%	80	B64290P0037X001	4.97	15.21	3.06	46.5	0.2
N87	560 ±25%	2200	B64290P0037X087					
N30	1090 ±25%	4300	B64290P0037X830					
T65	1160 ±30%	4600	B64290P0037X065					
T38	2530 ±30%	10000	B64290P0037X038					
T46	3600 ±30%	14000	B64290P0037X046					

# Testna matrika v delovnem formatu



## Štiri vrste preprega

<b>Zaporedna Št.</b>	<b>Material</b>	<b>Odstotek epoksi smole</b>
1	Tkanina 106	75
2	Tkanina 1080	64
3	Tkanina 2116	54
4	Tkanina 7628	47

# Vložek za stiskanje

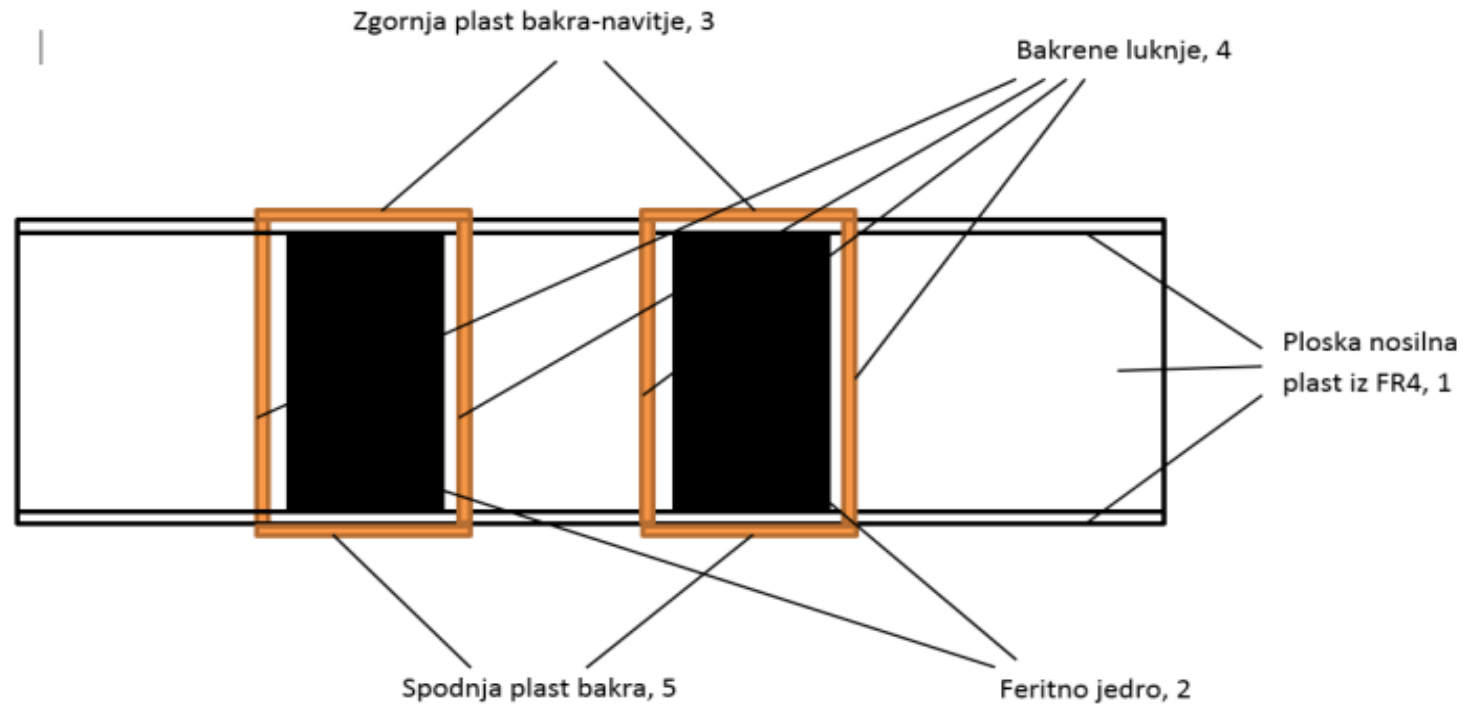




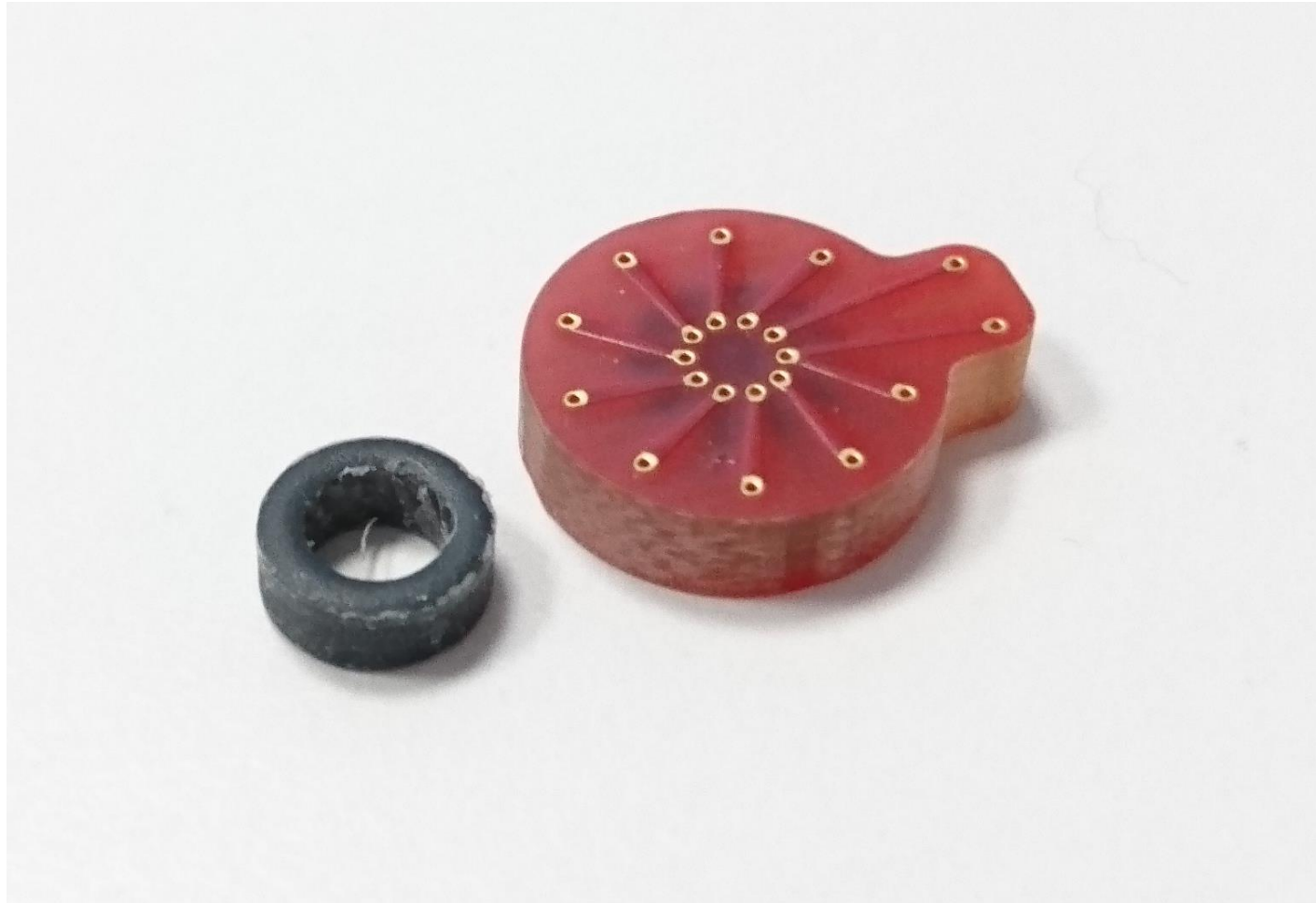
# Stiskalnica



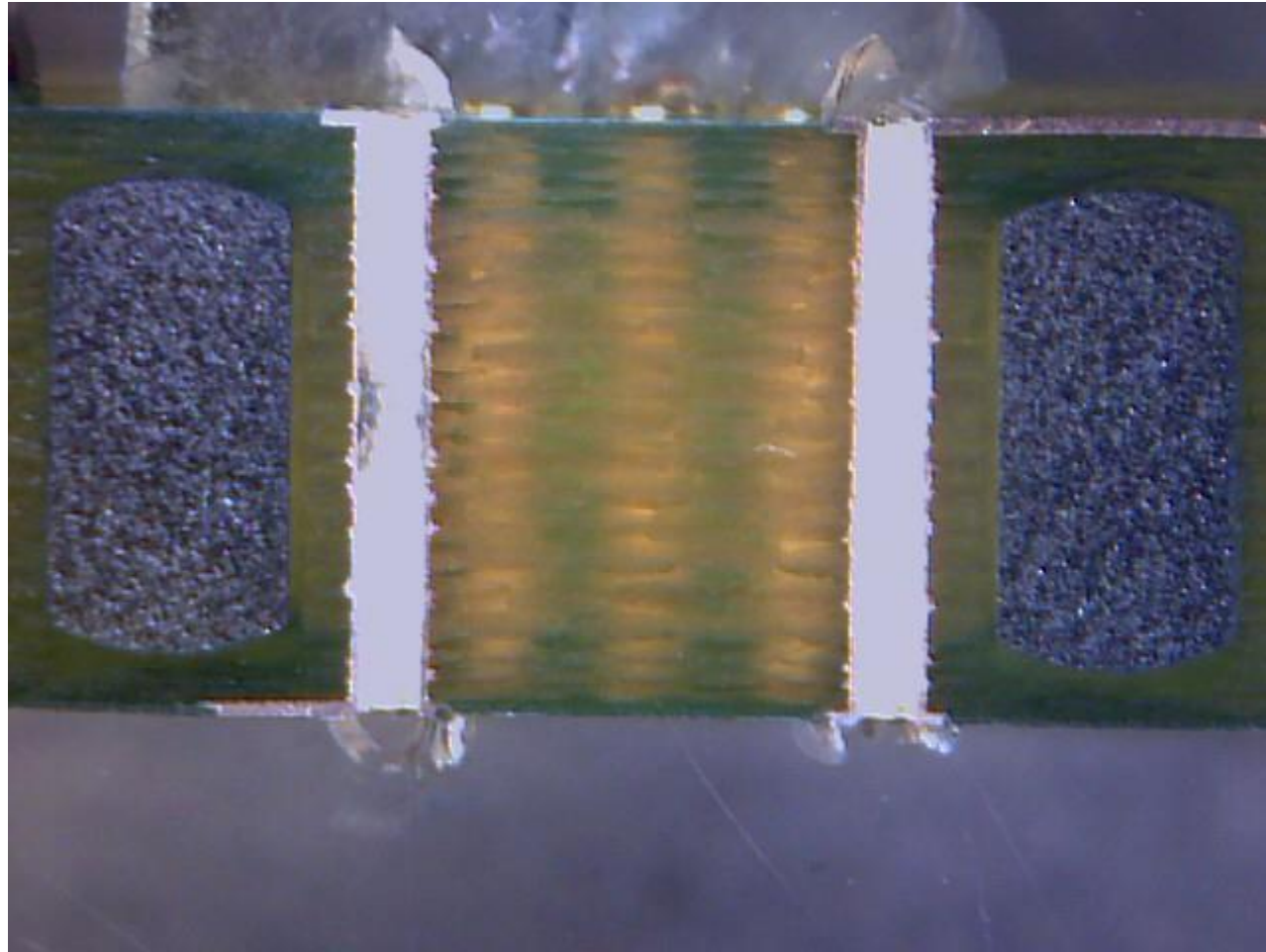
# Shematični prikaz prereza magnetne komponente



## Embedded magnetna komponenta

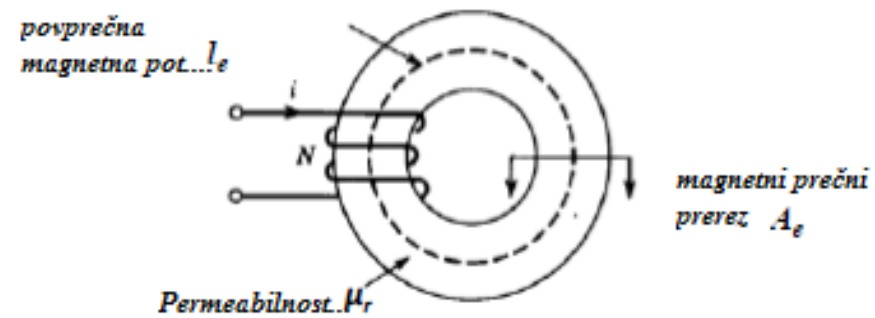


# Mikrosekcija embedded magnetne komponente



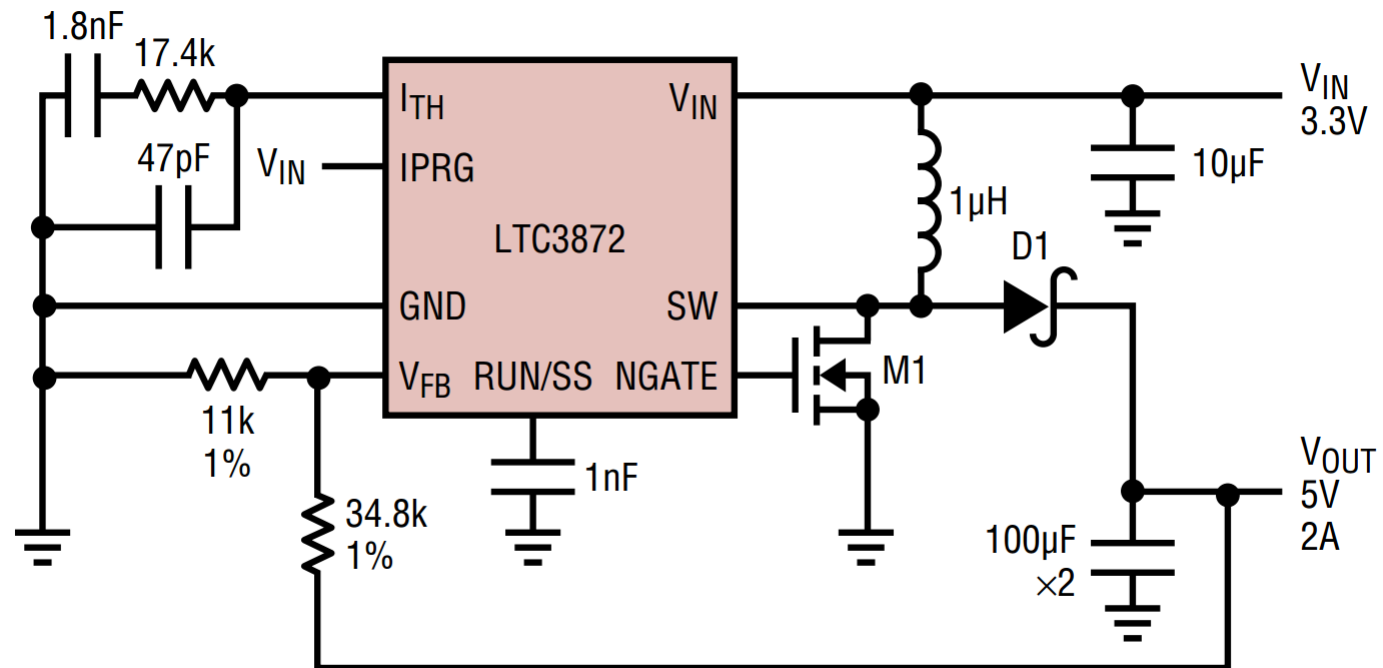


# Izračun induktivnosti



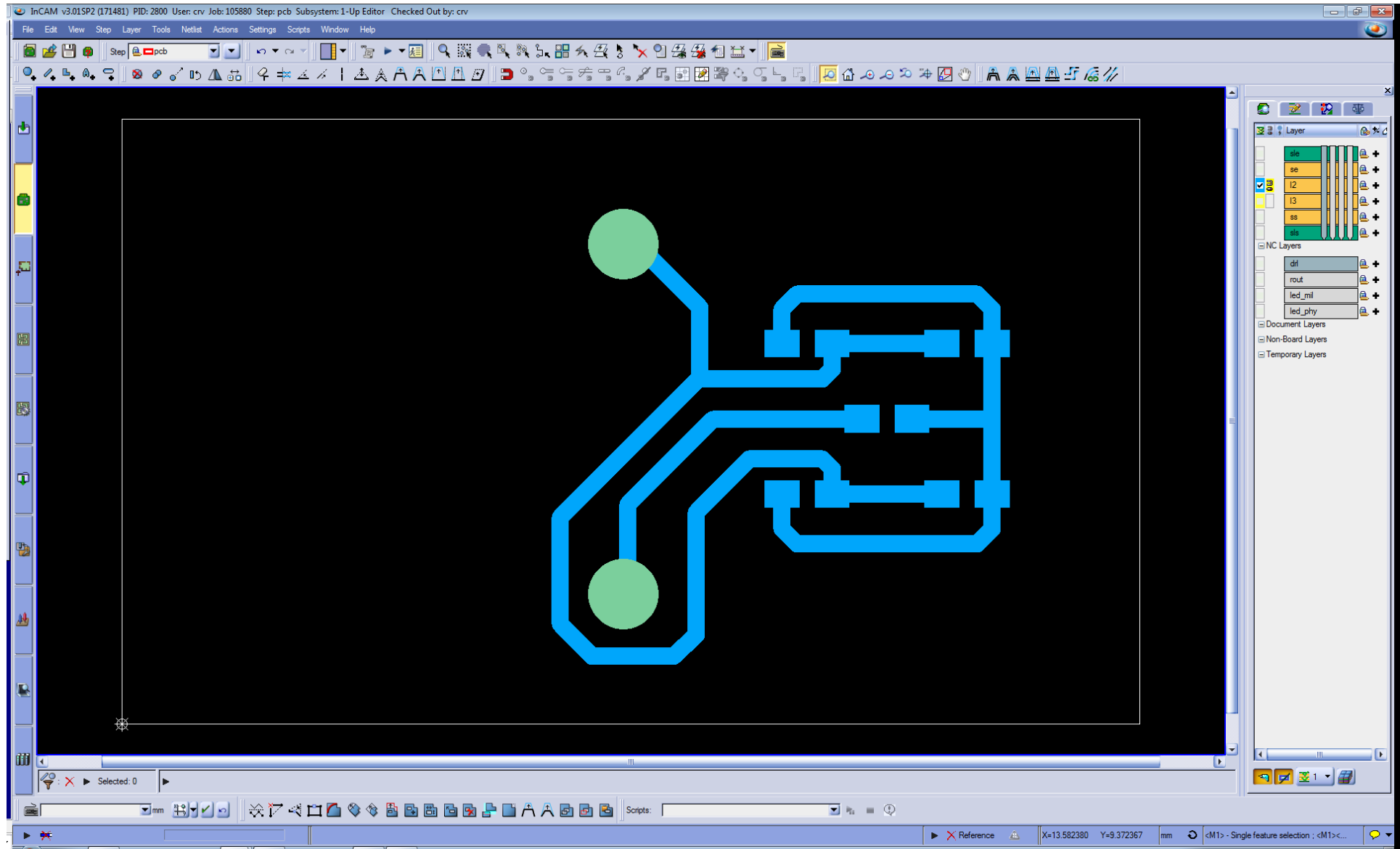
$$L = \mu_0 \mu_r N^2 \frac{A_e}{l_e}$$

# Shema preklopnega DC/DC pretvornika



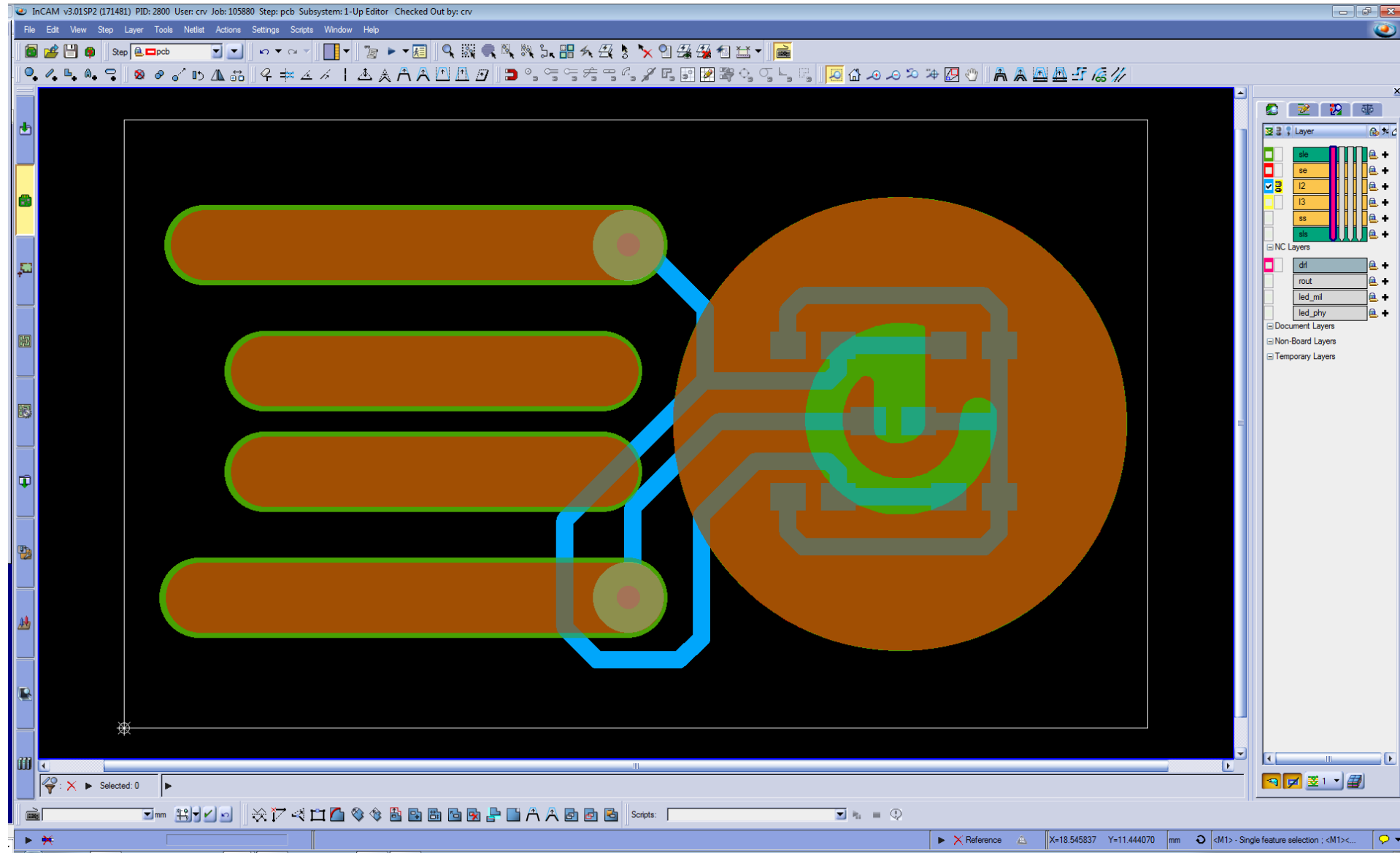
# Embedded LED USB

# Embedded LED USB





# Embedded LED USB

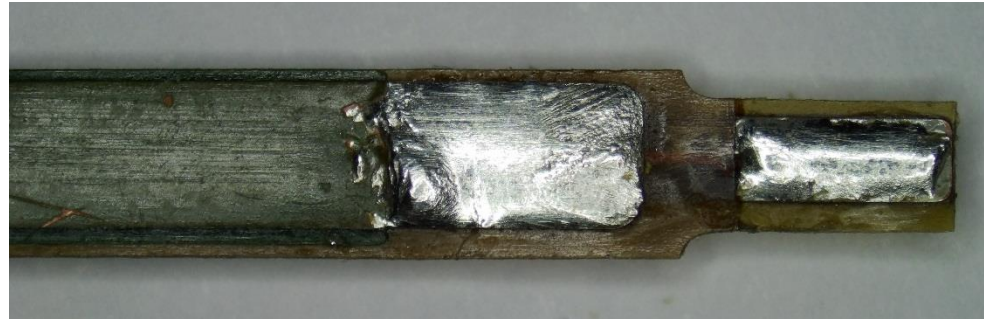


# Embedded LED USB



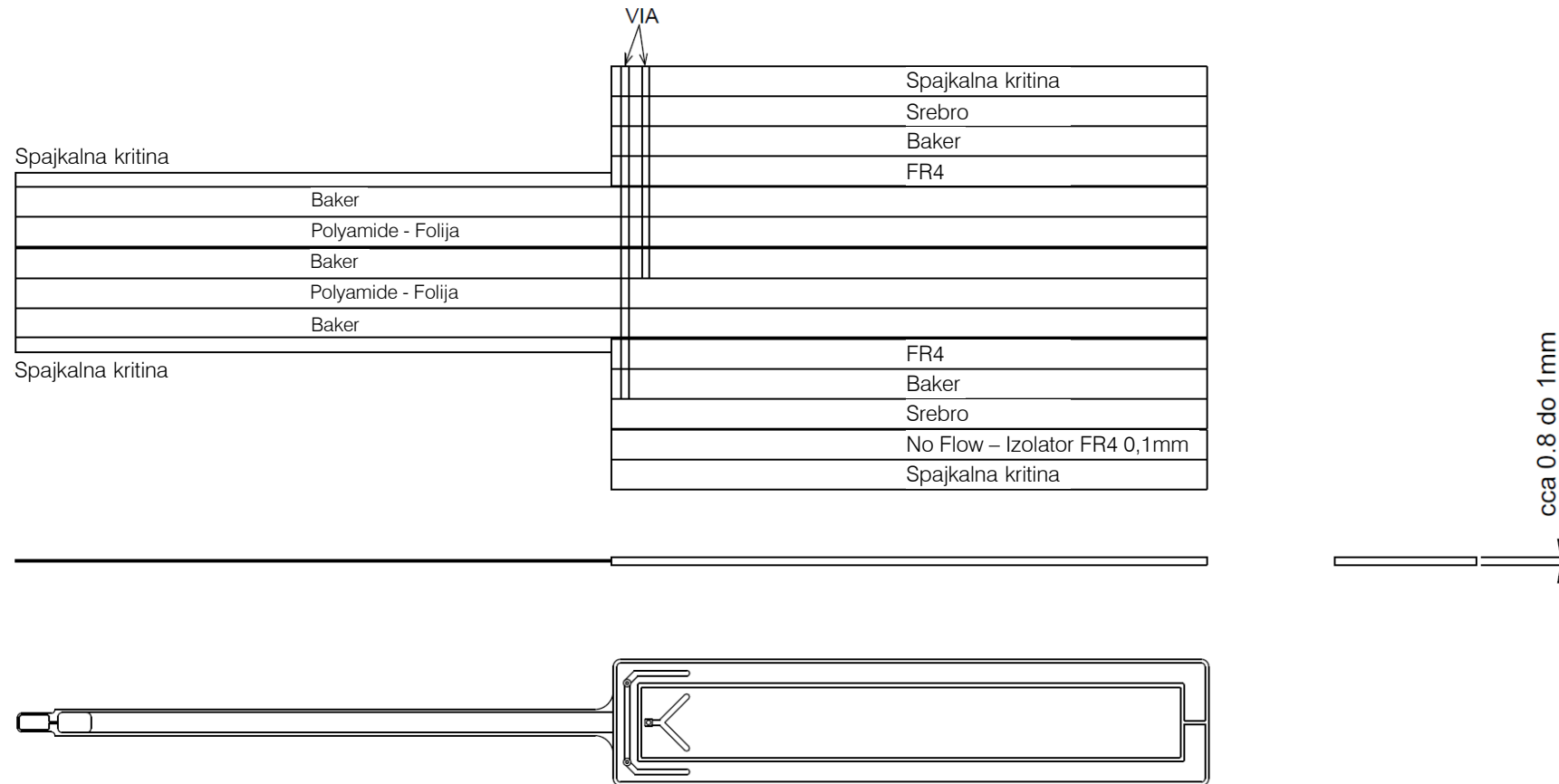
# Nova generacija kapacitivnega senzorja

# Naročnikov funkcionalen prototip

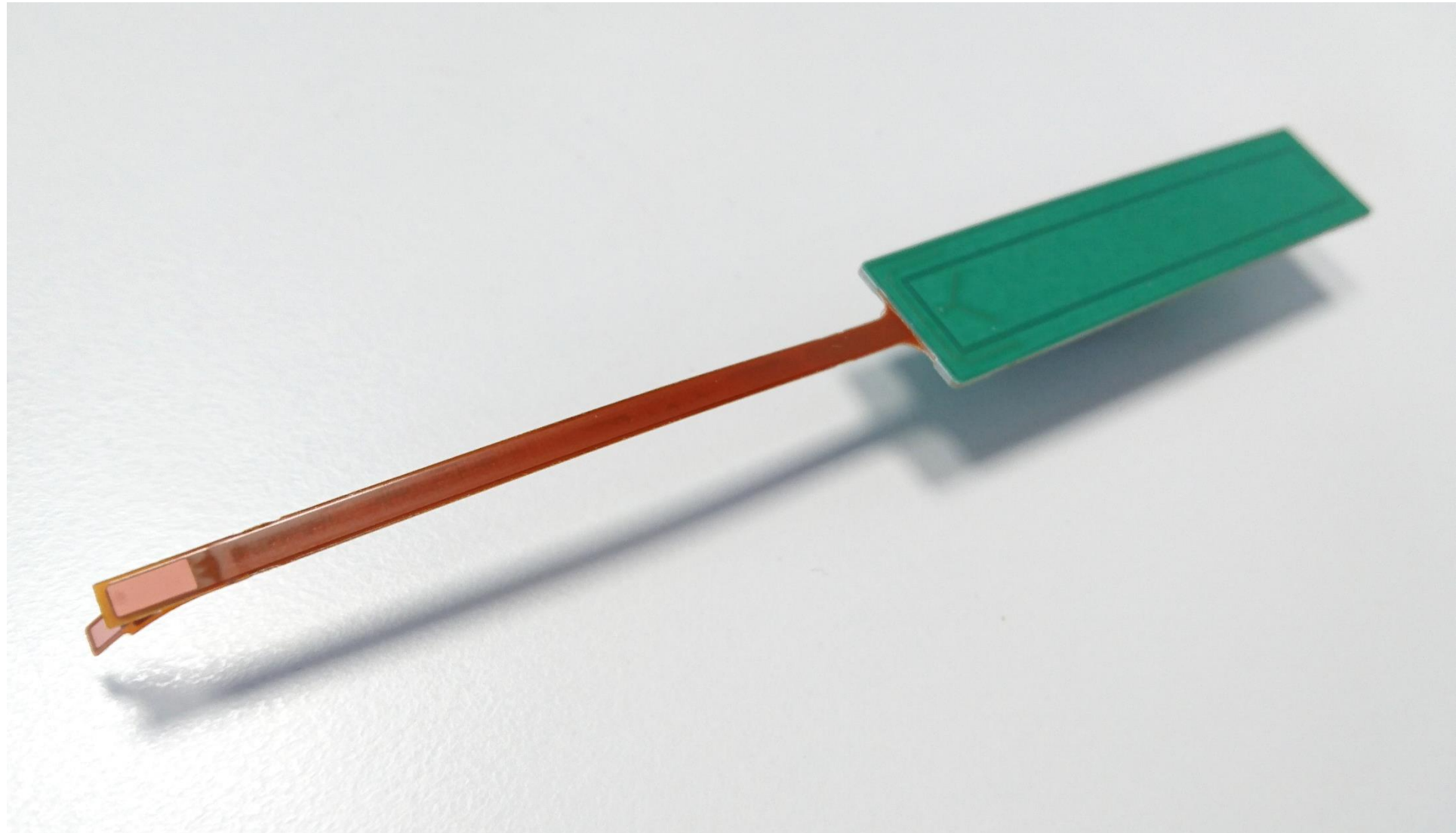




# Struktura PTIV – Novi Senzor



V Intectiv izdelana plošča tiskanega vezja – Kapacitivni senzor



V Intectiv izdelana plošča tiskanega vezja – Kapacitivni senzor

